

Baseband and mm-wave circuit techniques for energy-efficient communication systems at up to 1Tb/s per carrier

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Qualcomm, October 19, 2012

Credits

Graduate students

- ♦ Yannis Sarkas
- ♦ Andreea Balteanu
- ♦ Alex Tomkins
- ♦ Eric Dacquay
- ♦ Katya Laskin

Collaborators

- ♦ Juergen Hasch
- ♦ Pascal Chevalier
- ♦ Peter Asbeck
- ♦ Gabriel Rebeiz
- ♦ Jim Buckwalter
- ♦ Larry Larson

- NSERC, OCE
- Robert Bosch GmbH, DARPA, Ciena, Gennum for funding
- STMicroelectronics, Darpa, Ciena for chip donations

Outline

- Why?
- How?
 - System
 - Baseband
 - Radio transceiver
- Summary

Energy Efficiency of Communication Links

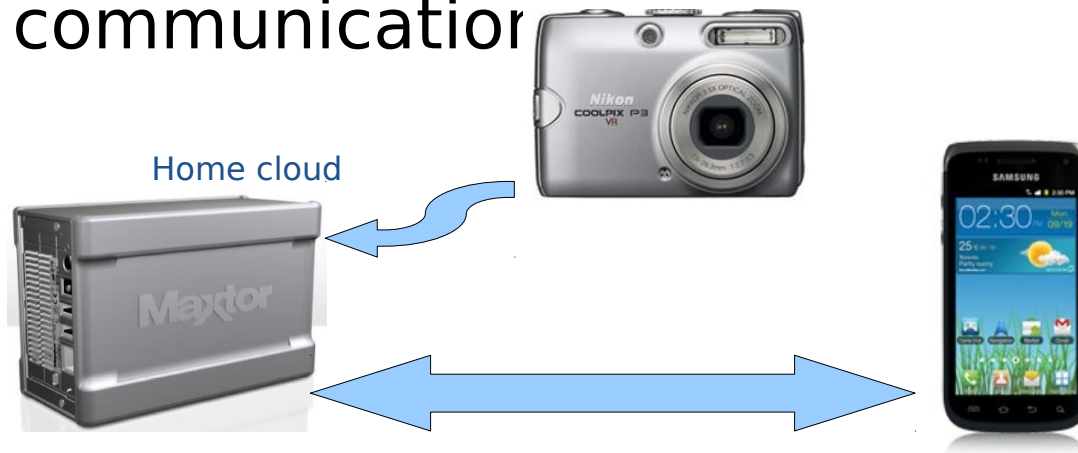
	4G WiMAX	60 GHz LOS Radio	Wireline IEE 802.3.an	Fiber SerDes VCSEL	Fiber DP-QPSK/BPSK
Data Rate	≤ 1 Gbps	5.3 Gbps	10 Gbps	10 Gbps	50 Gbps
Power	1.76 W	350 mW	2 W	2.5 W	25 W
Distance		2 m	100 m	20 km	3500 km
Energy/bit	1.6 nJ/b	66 pJ/b	200pJ/b	250 pJ/b	500pJ/b
Energy/bit/m		33 pJ/b/m	2 pJ/b/m	12.5 fJ/b/m	0.14 fJ/b/m
Reference	[Krishnamurthy, •RFIC 2010]	[Laskin, •RFIC 2011]	[Gupta, ISSCC 2012]	[Voinigescu, CICC 2001]	[Crivelli, ISSCC 2012]

Need solutions in...

- Wireless, wireline, fiberoptic system architectures that
 - ♦ Increase data rate >1 Tb/s carrier (imperative in fiber links)
 - ♦ Increase efficiency per bit
- Faster, more efficient circuit topologies
 - ♦ CMOS logic at 50-100 Gb/s to save power?
 - ♦ Stacked CMOS logic for large swing drivers?
- Can we push the carrier frequency to 300 GHz?

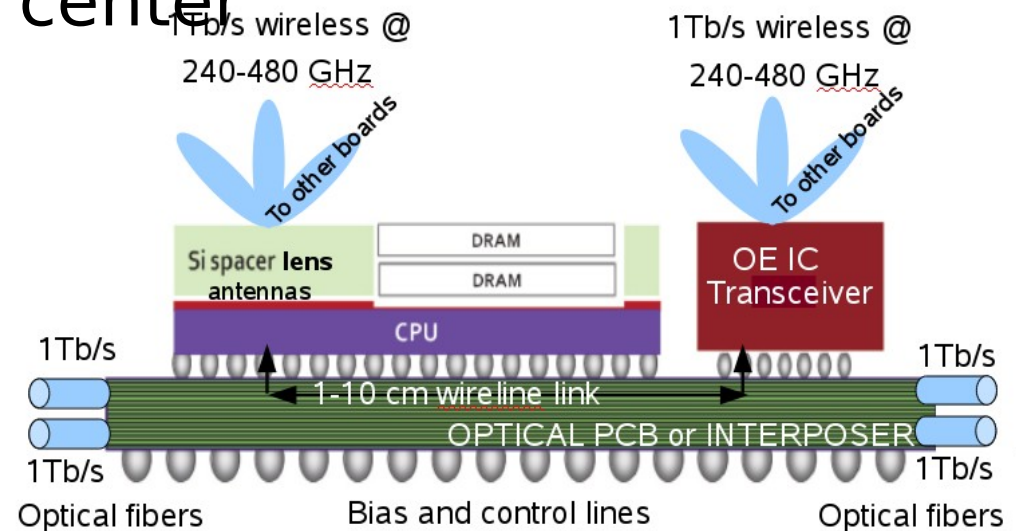
Why Tb/s wireless?

- Near field communication



- Short-range reconfigurable wireless data transmission in the data center

- Board-to-board



Scalable Digital Radio Transmitters

- Can we improve efficiency by increasing the modulation rate per carrier at fixed P_{OUT} ?

Scalable Digital Radio Transmitters

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- Example: 300 Gb/s with 1 W PA $\Rightarrow$ 3.3 pJ/b

Scalable Digital Radio Transmitters

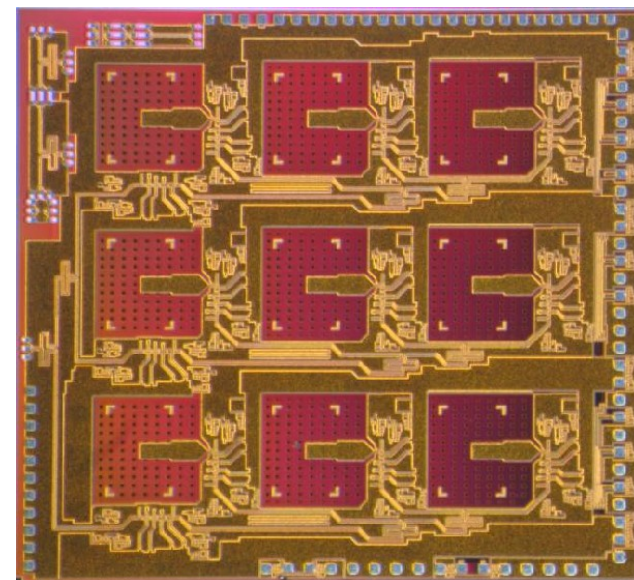
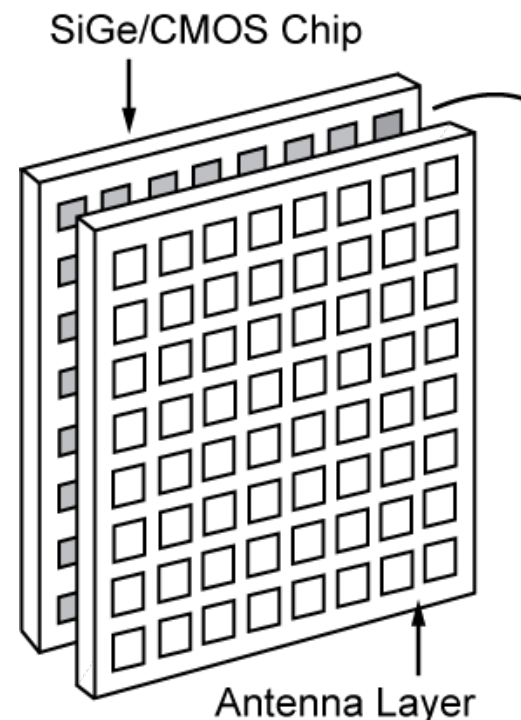
- Can we improve efficiency by increasing the modulation rate per carrier at fixed P_{OUT} ?
- Example: 300 Gb/s with 1 W PA $\Rightarrow$ 3.3 pJ/b
 - But 300 Gb/s with 64 QAM modulation requires 50 Gb/s serial baseband lanes,
 - difficult to realize efficiently with up-conversion transmitter architecture

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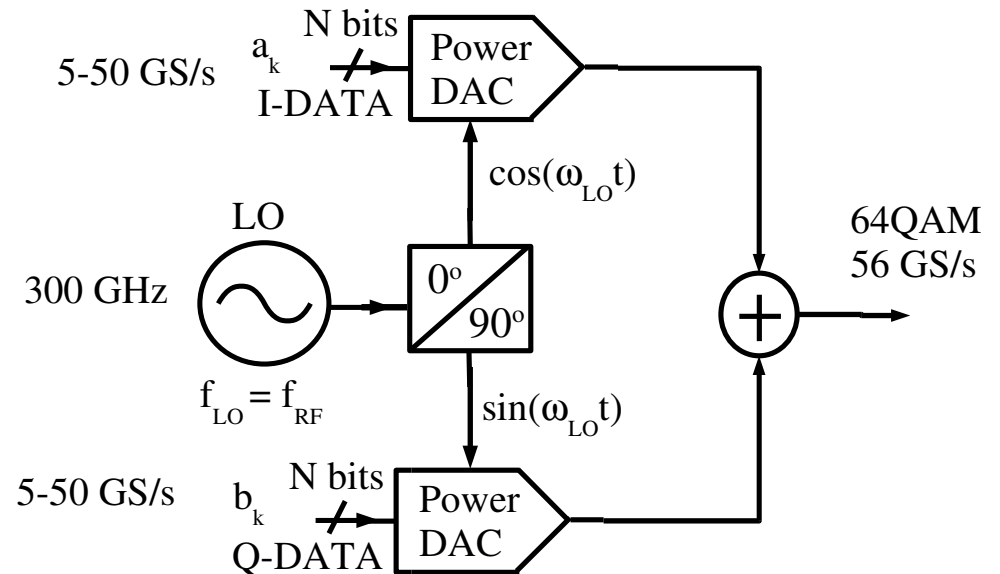
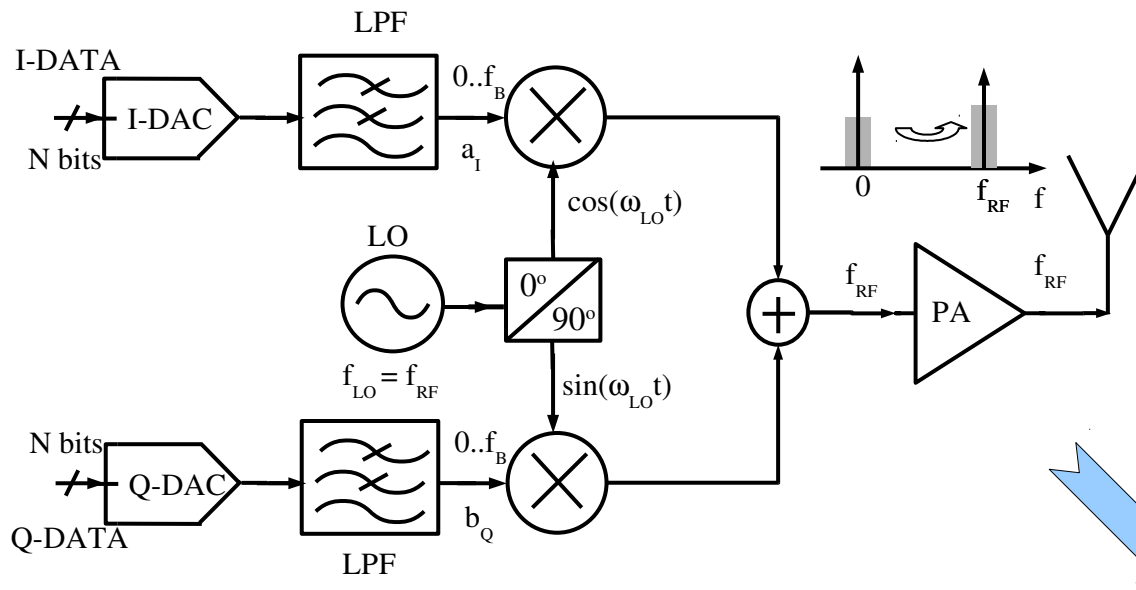
Why 100-300 GHz?

- Silicon transistors with $f_{\text{MAX}} > 400$ GHz
- Smaller wavelengths: high res, high BW
- Small antenna size with good gain
- Lower power LNA, mixer, receiver
- But...
 - ♦ higher power PLL,
 - ♦ reduced P_{out} ,
 - ♦ shorter range $\sim 1/f^2$ or $\sim 1/f^4$



Source: G. Rebeiz UCSD

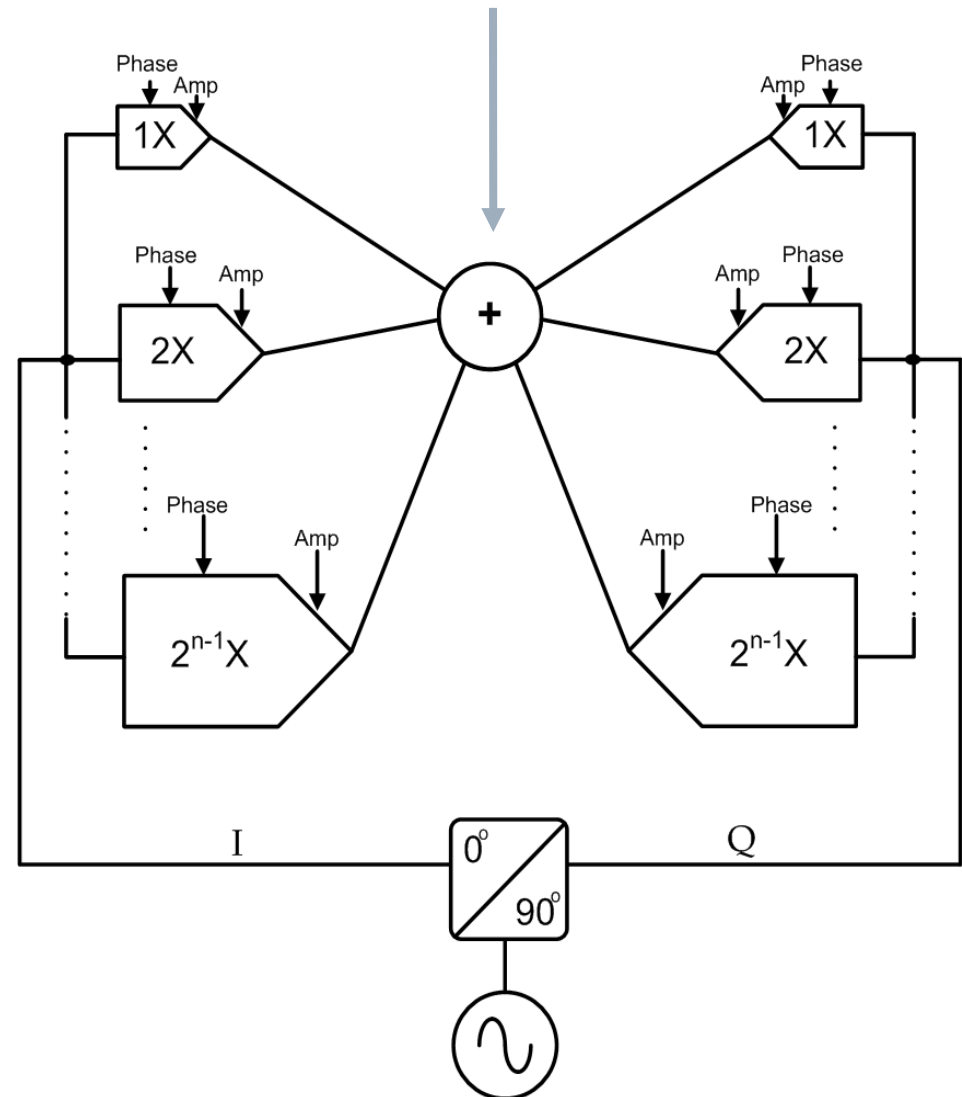
Potential Solution: Direct Modulation TX Radio



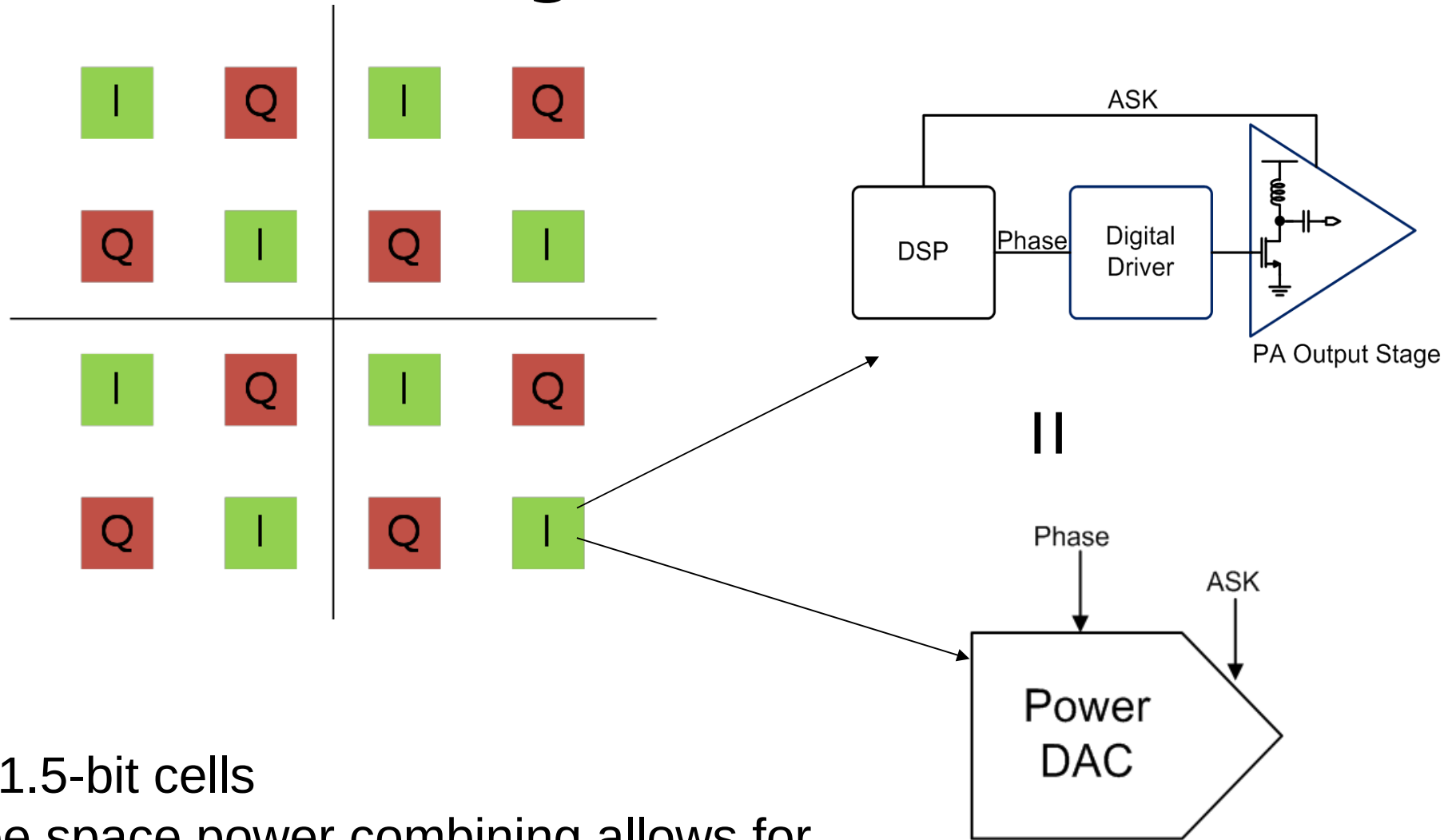
Direct Modulation TX Radio

- Merge DAC with PA
- 1.5-bit polar-modulated, binary weighted PA cells driven in quadrature
- No back-off needed for linearity
- Phase/Amp bits @ 1-50 Gbps

- On chip free-space power combiner

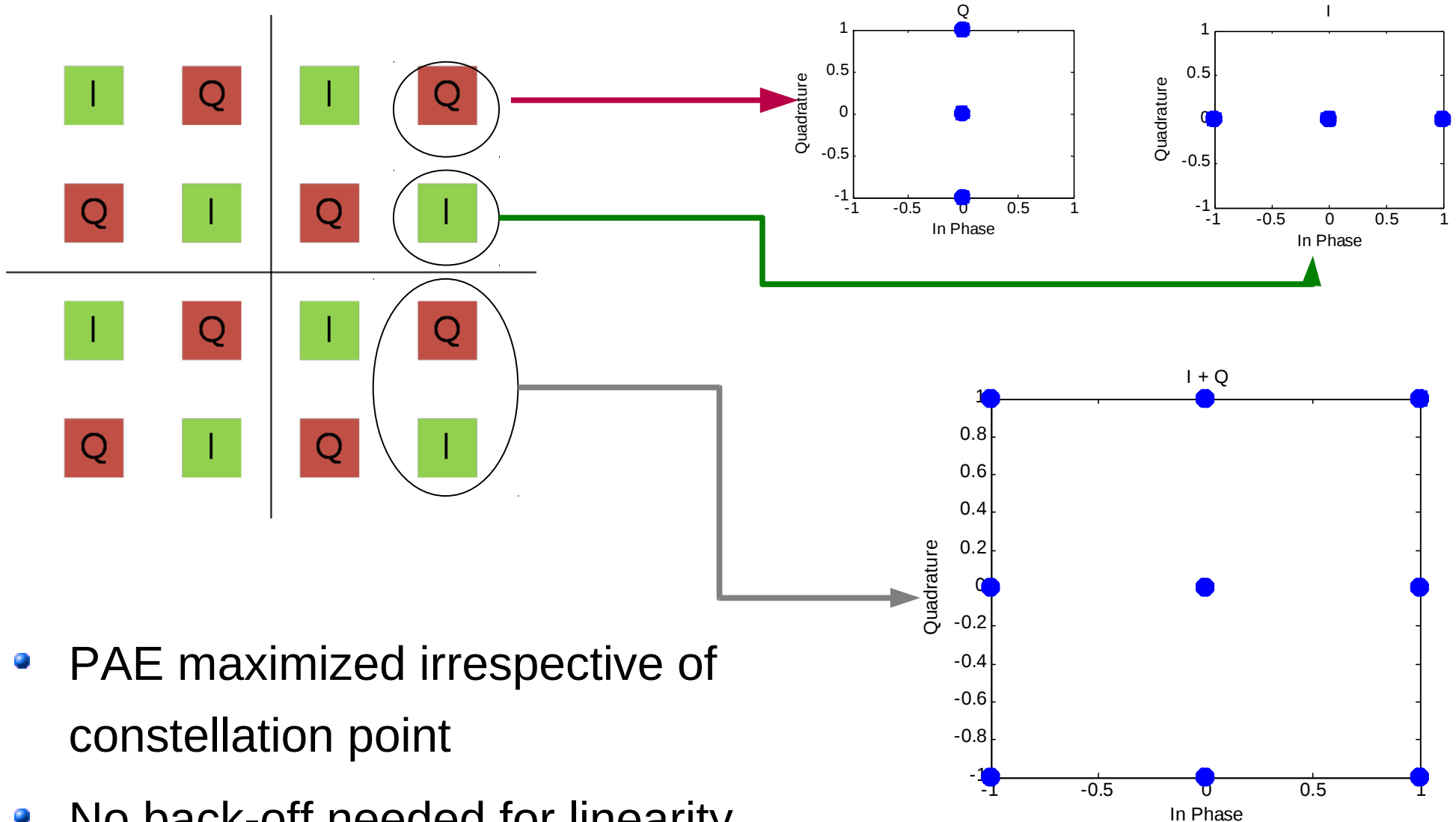


IQ DAC TX with Antenna Level Segmentation



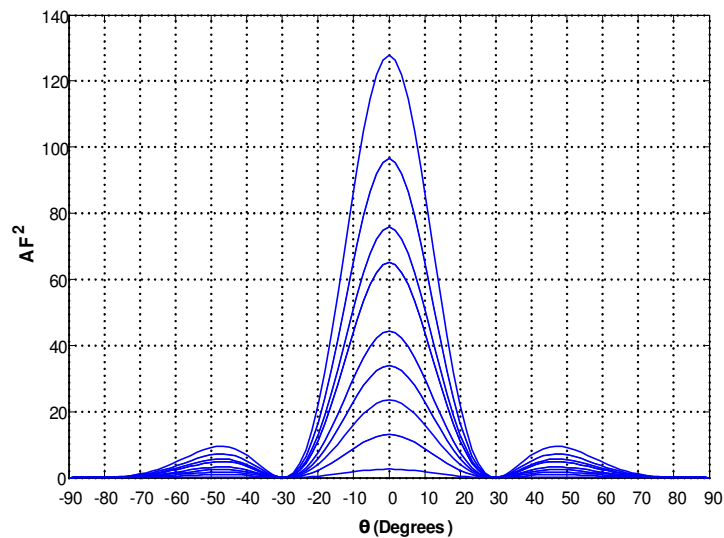
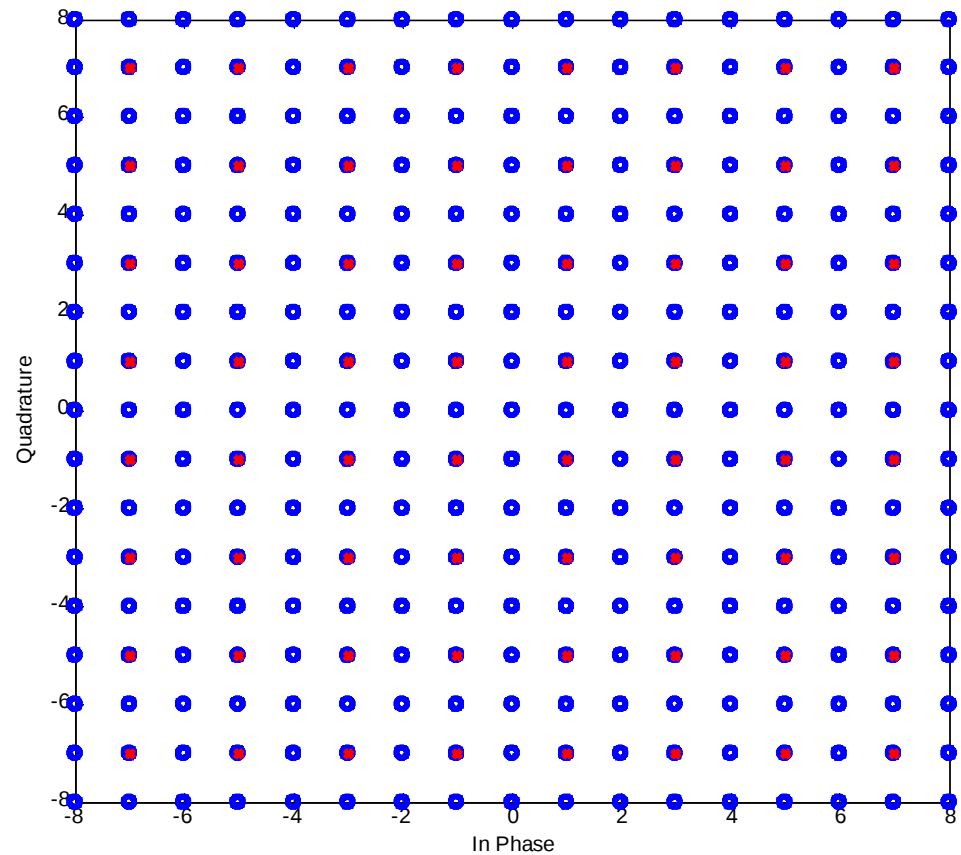
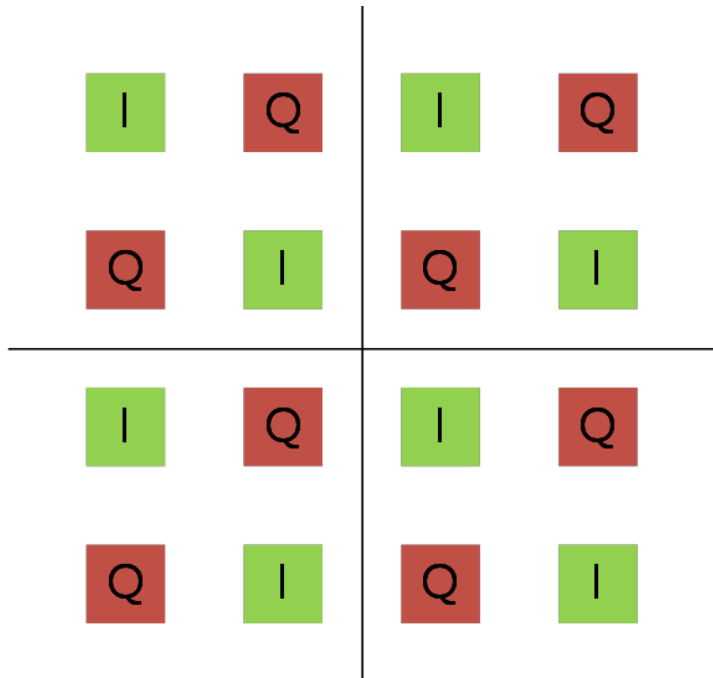
- ◆ 16 1.5-bit cells
- ◆ Free space power combining allows for antenna segmentation

IQ DAC TX Constellation



- PAE maximized irrespective of constellation point
- No back-off needed for linearity

Full 8I + 8Q Constellation



64 QAM Constellation Points

8I + 8Q $\rightarrow$ 289 Constellation Points $> 2^8$
2 extra bits

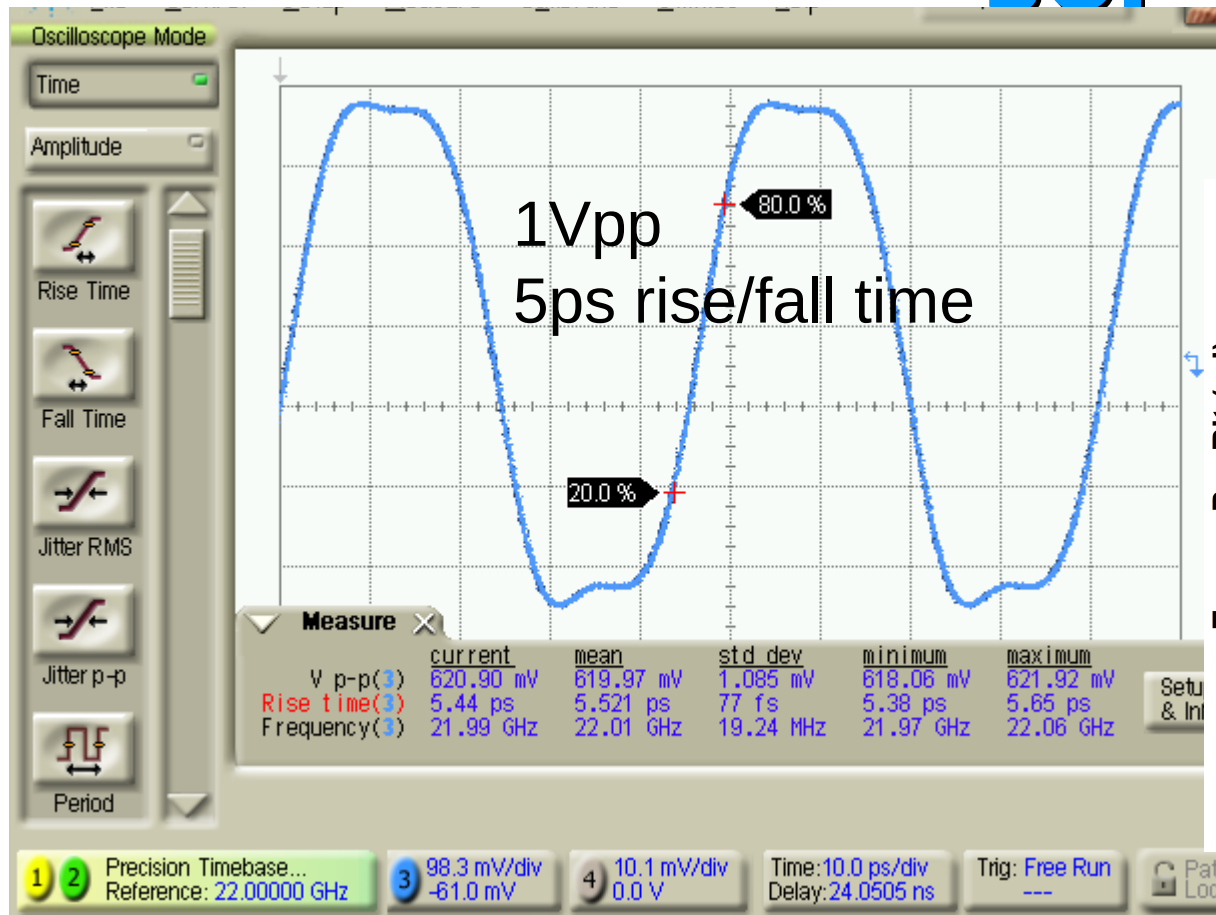
Wish list for sub-millimetre wave radio

- 100 Gb/s standard CMOS baseband lanes
 - ♦ Efficiency scalable with data rate
- $P_{TX} = 10$ dBm
- PLL with $PN < -90$ dBc/Hz in band at 300 GHz
- $NF < 12$ dB
- $P_{DC} < 1$ W
- $BW = 25-30\%$
- Antenna gain > 20 dB (lens)
- Distance: 10's cm

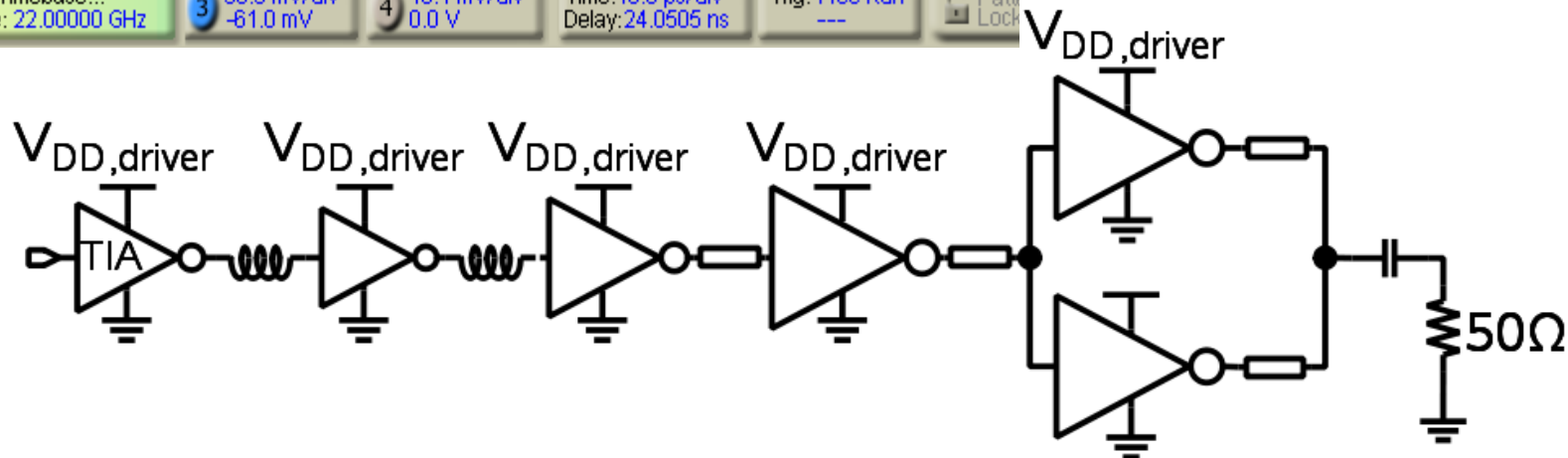
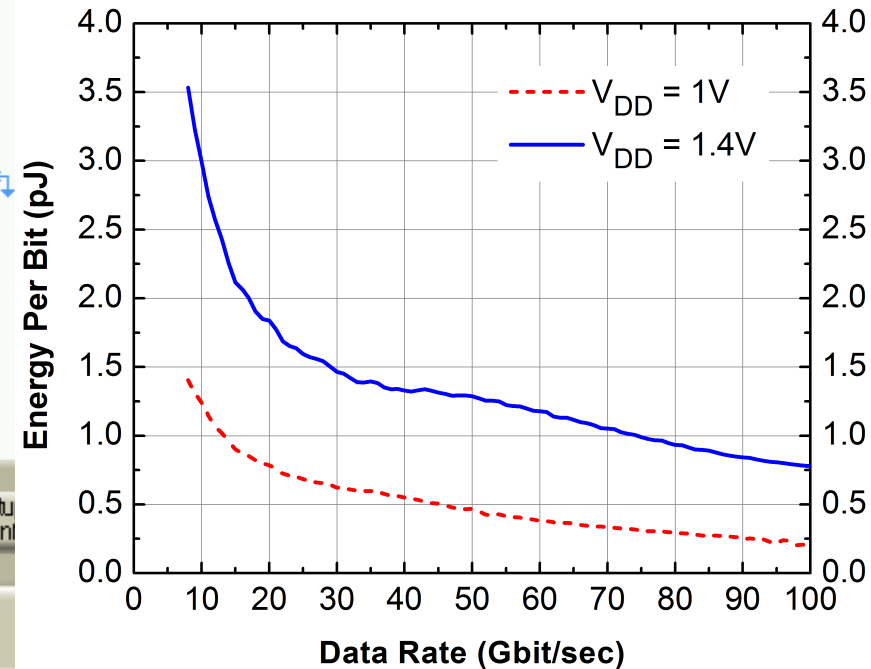
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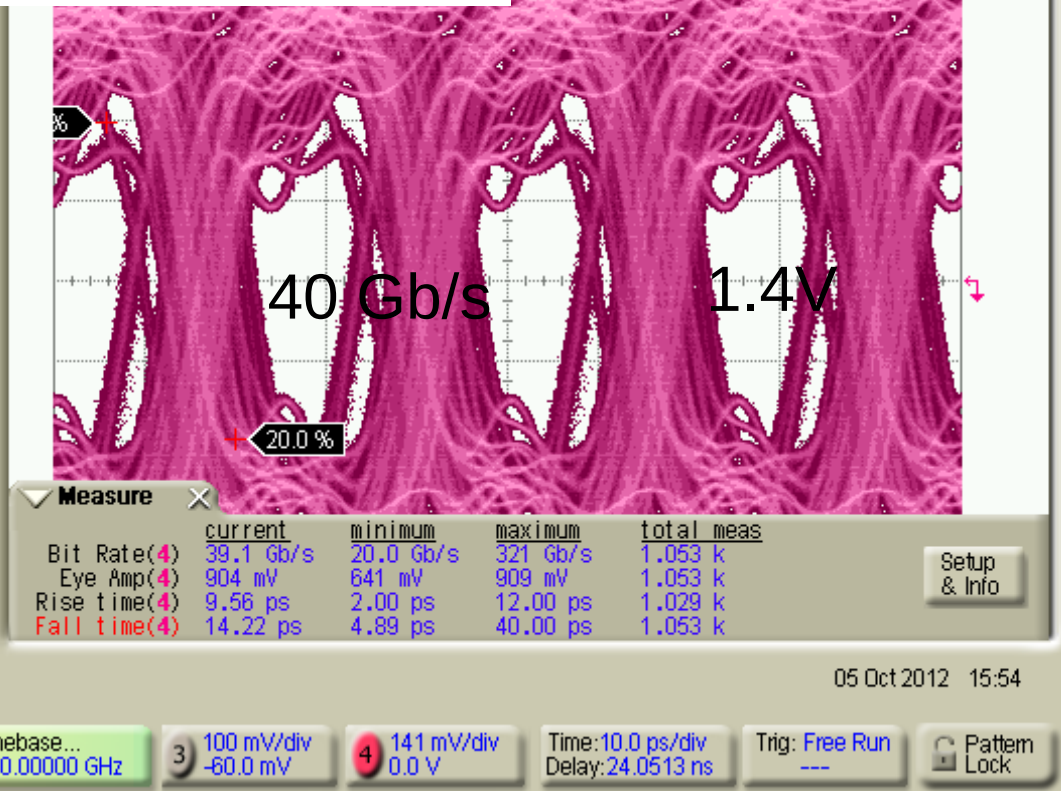
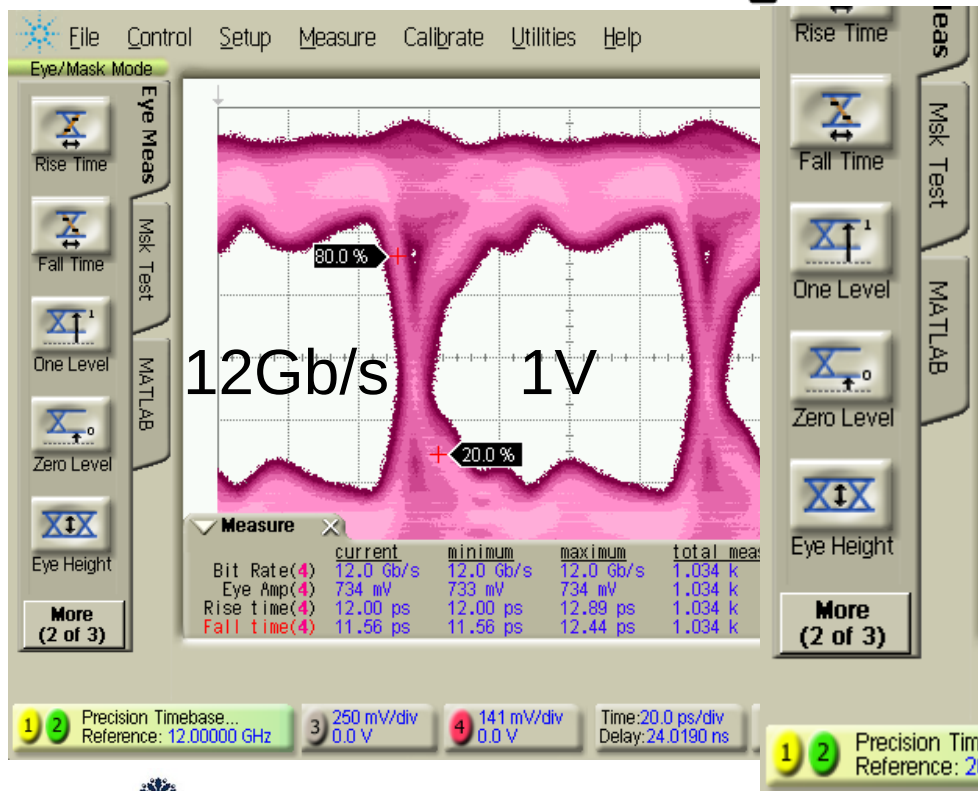
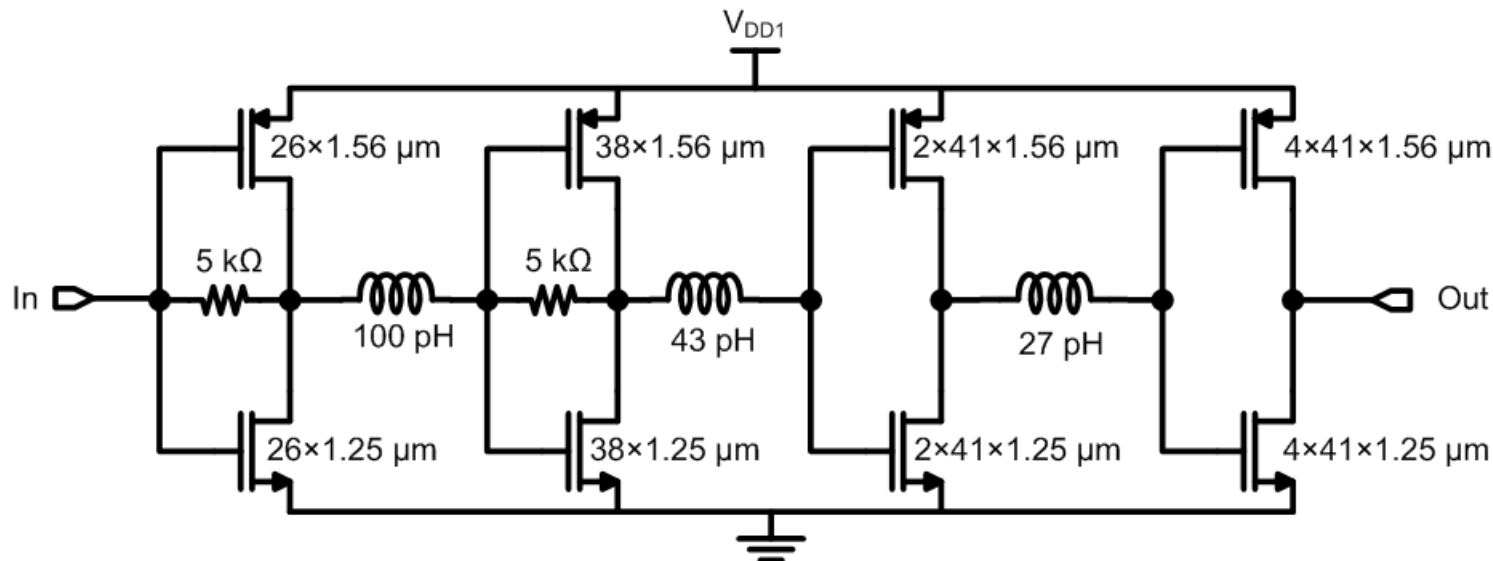
Rise/fall time, efficiency/bit in 45-nm SOI



[I. Sarkas, ISSCC 2012]

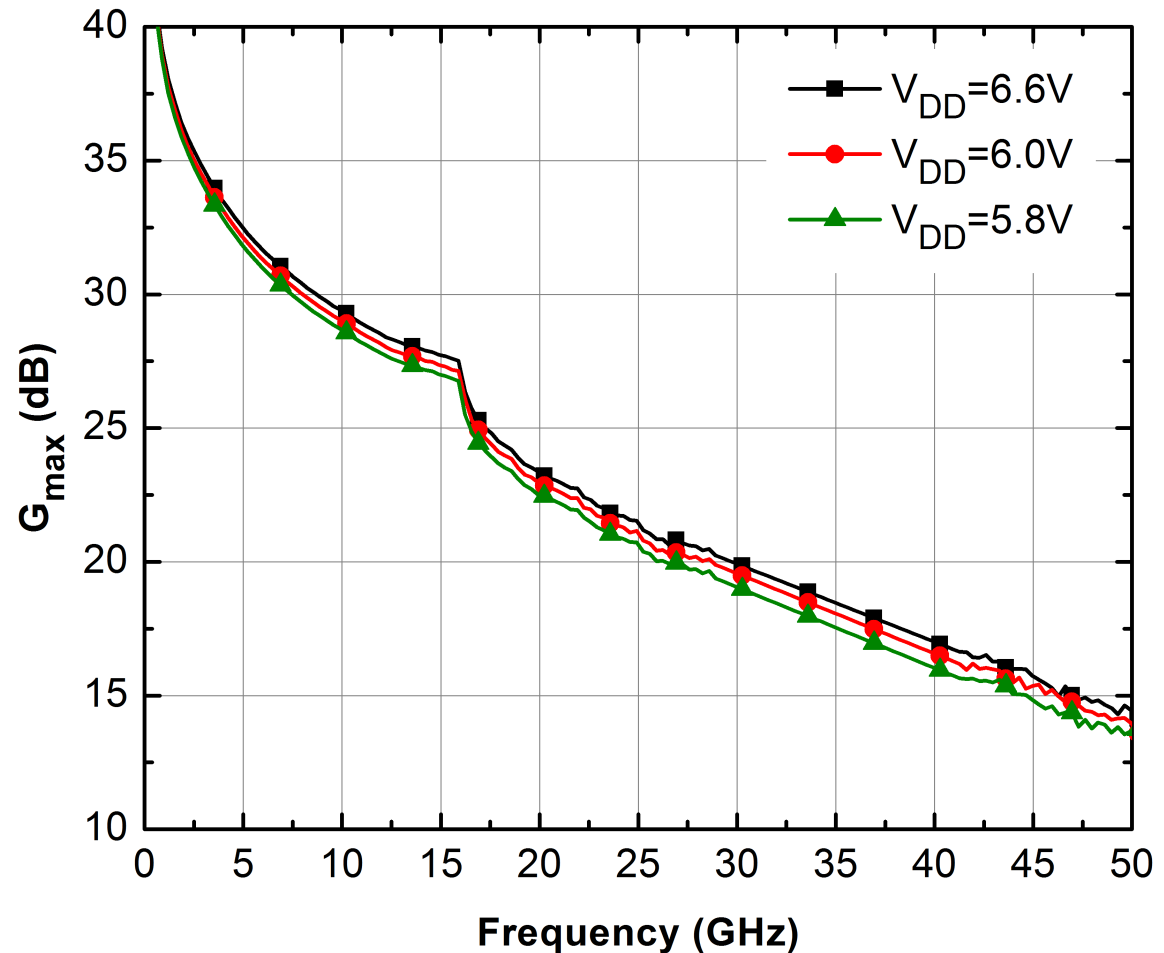
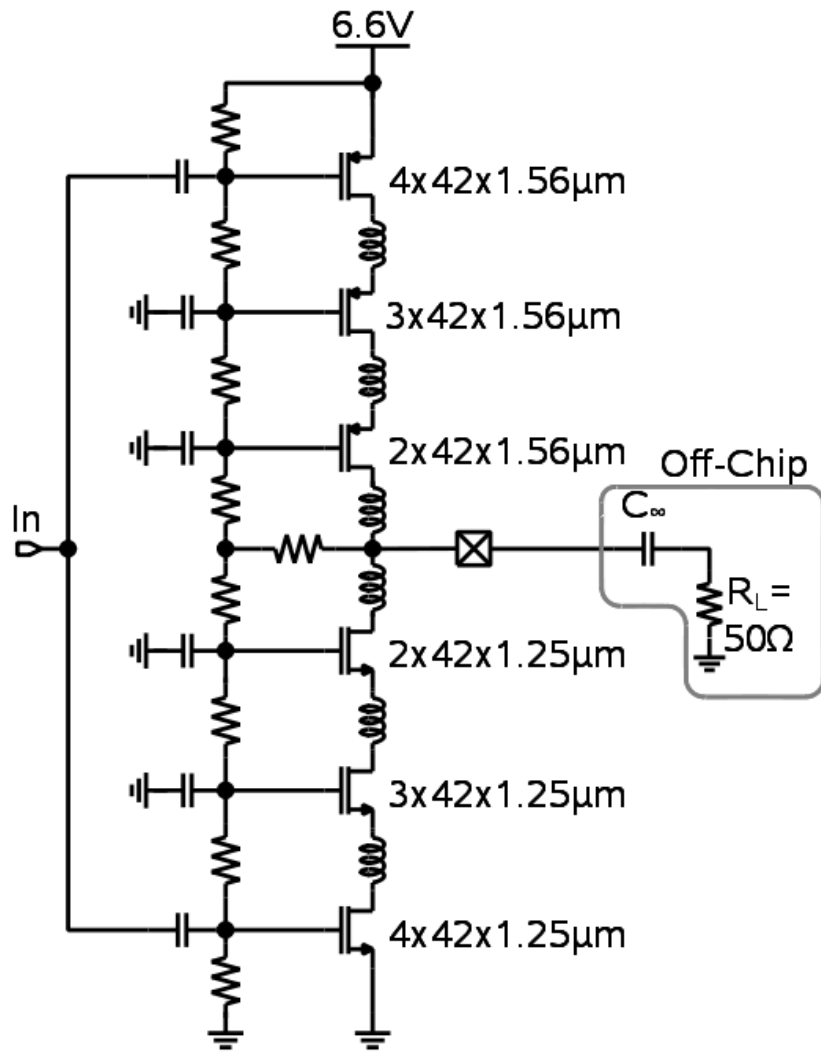


40+ Gb/s inductively-peaked CMOS logic



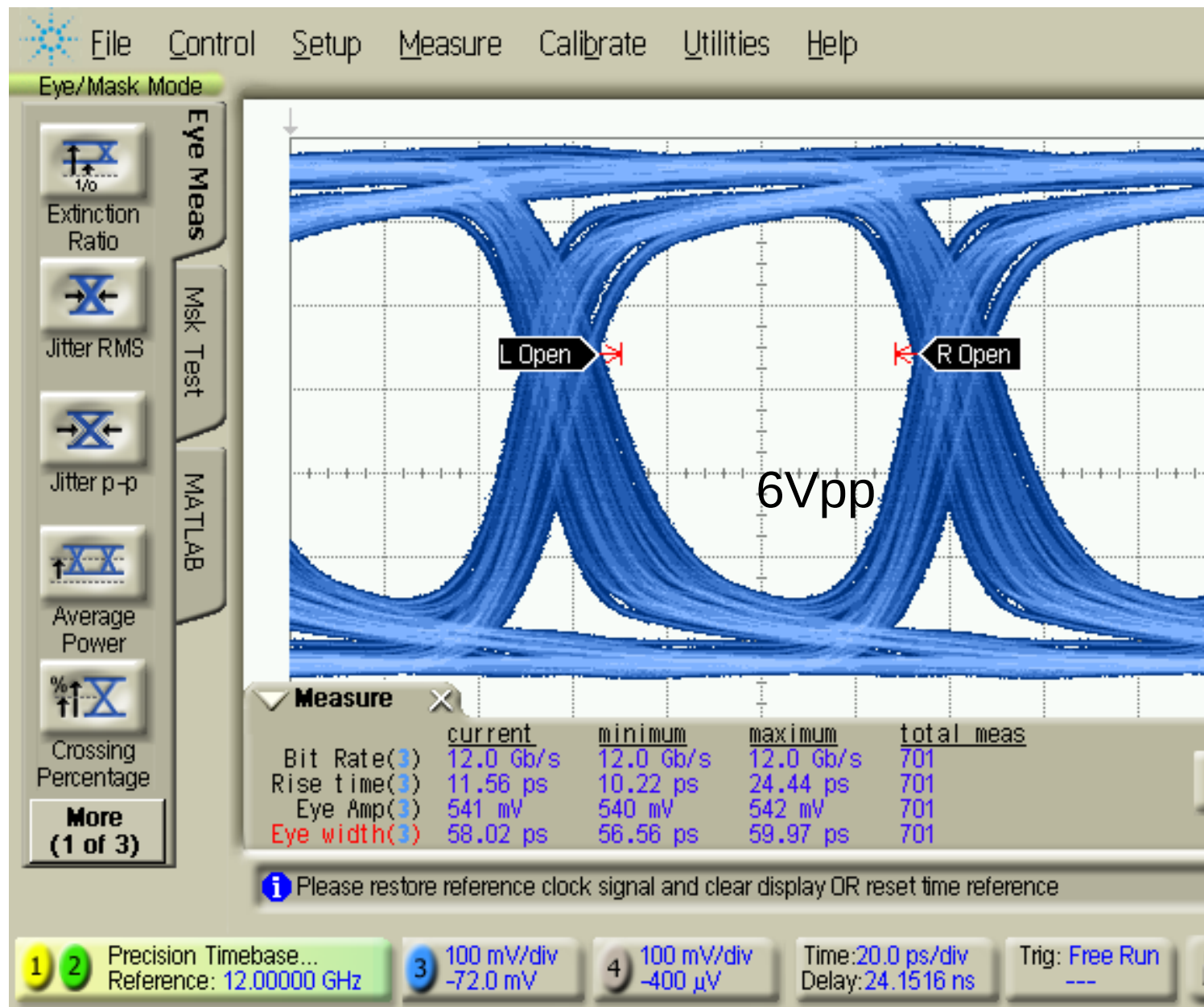
Large swing stacked CMOS inverter LOGIC

[I. Sarkas, ISSCC 2012]

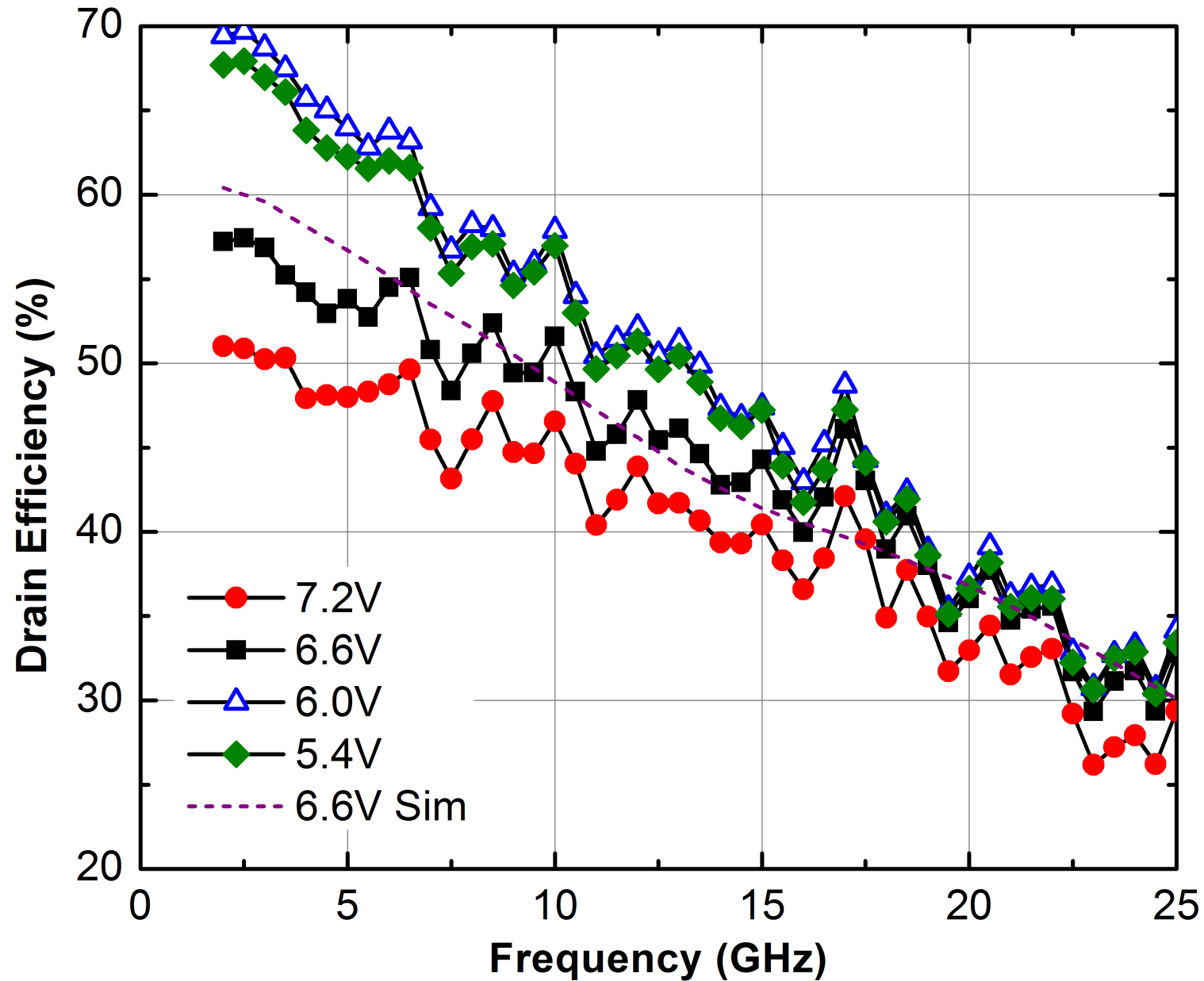


Inspired by
P. Asbeck's group work

Eye diagrams at 12 Gb/s

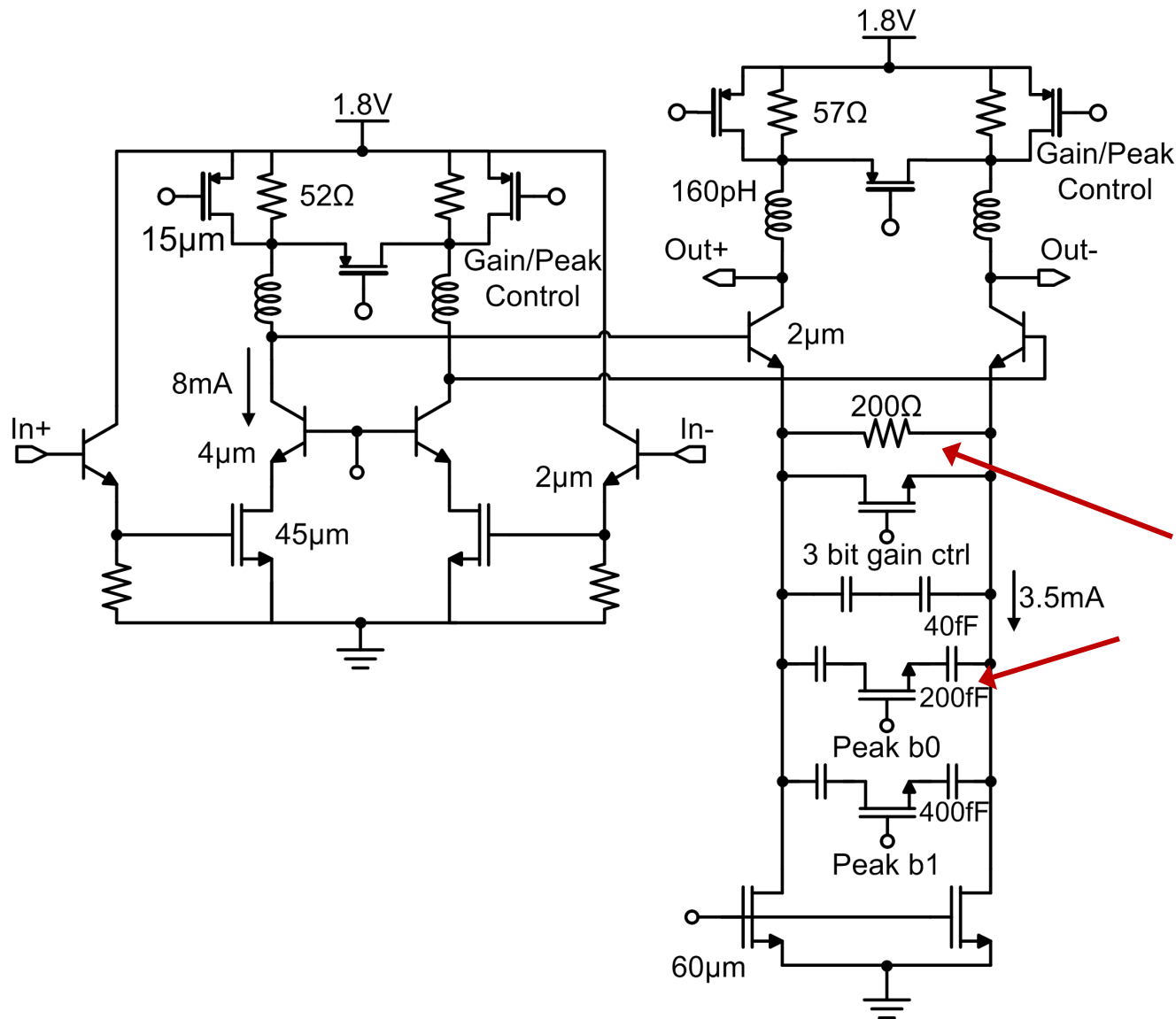


Efficiency



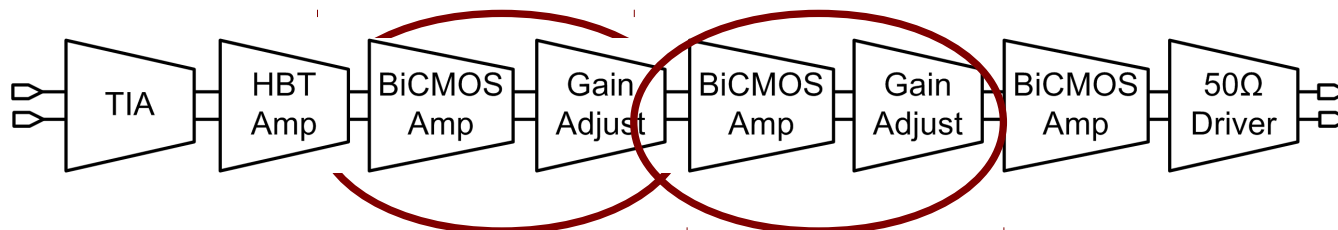
1.8V 80-Gb/s Cable Equalizer

[I. Sarkas
CSICS 2012]

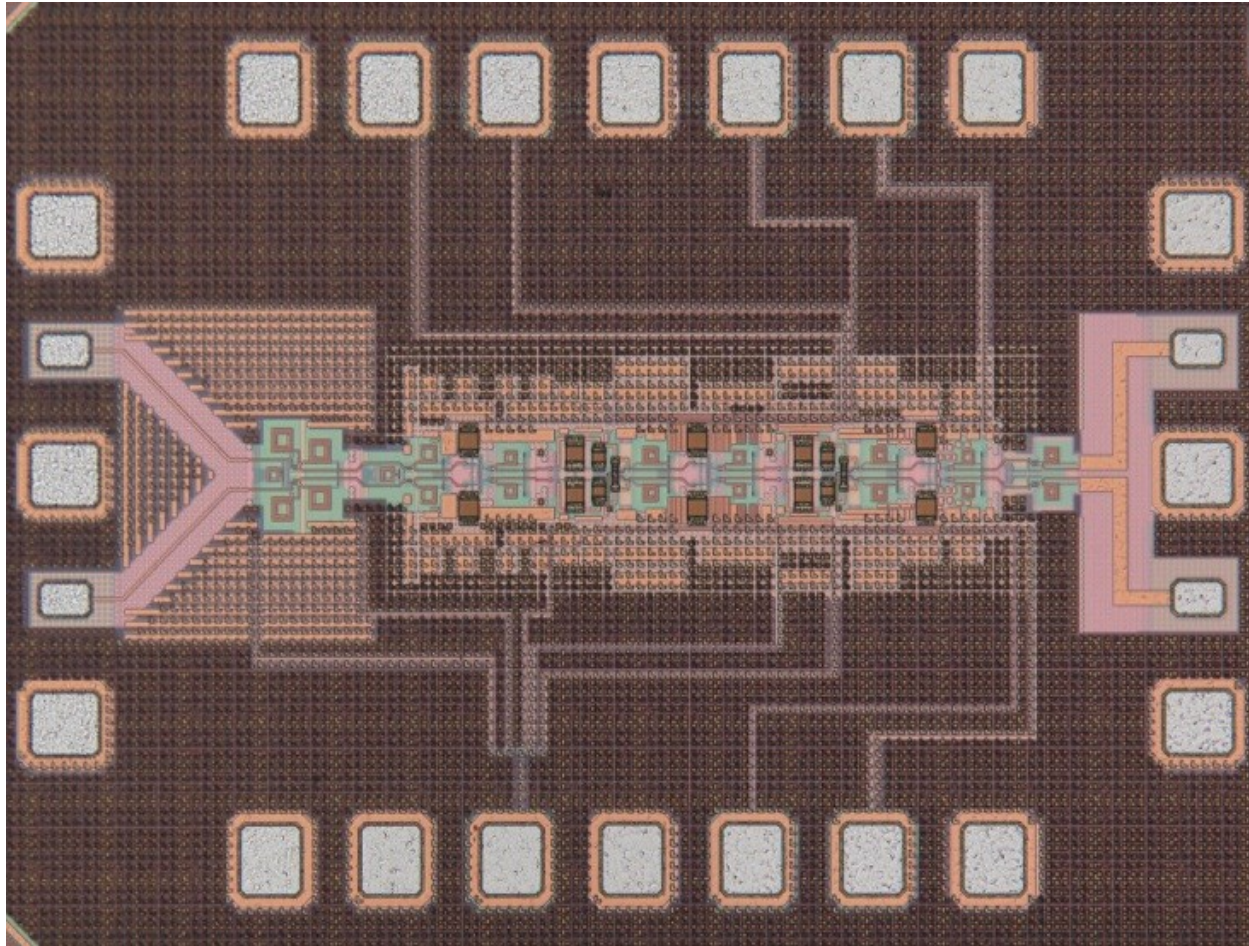


Adjustable DC gain
also Important for
linearity

Adjustable zero
frequency

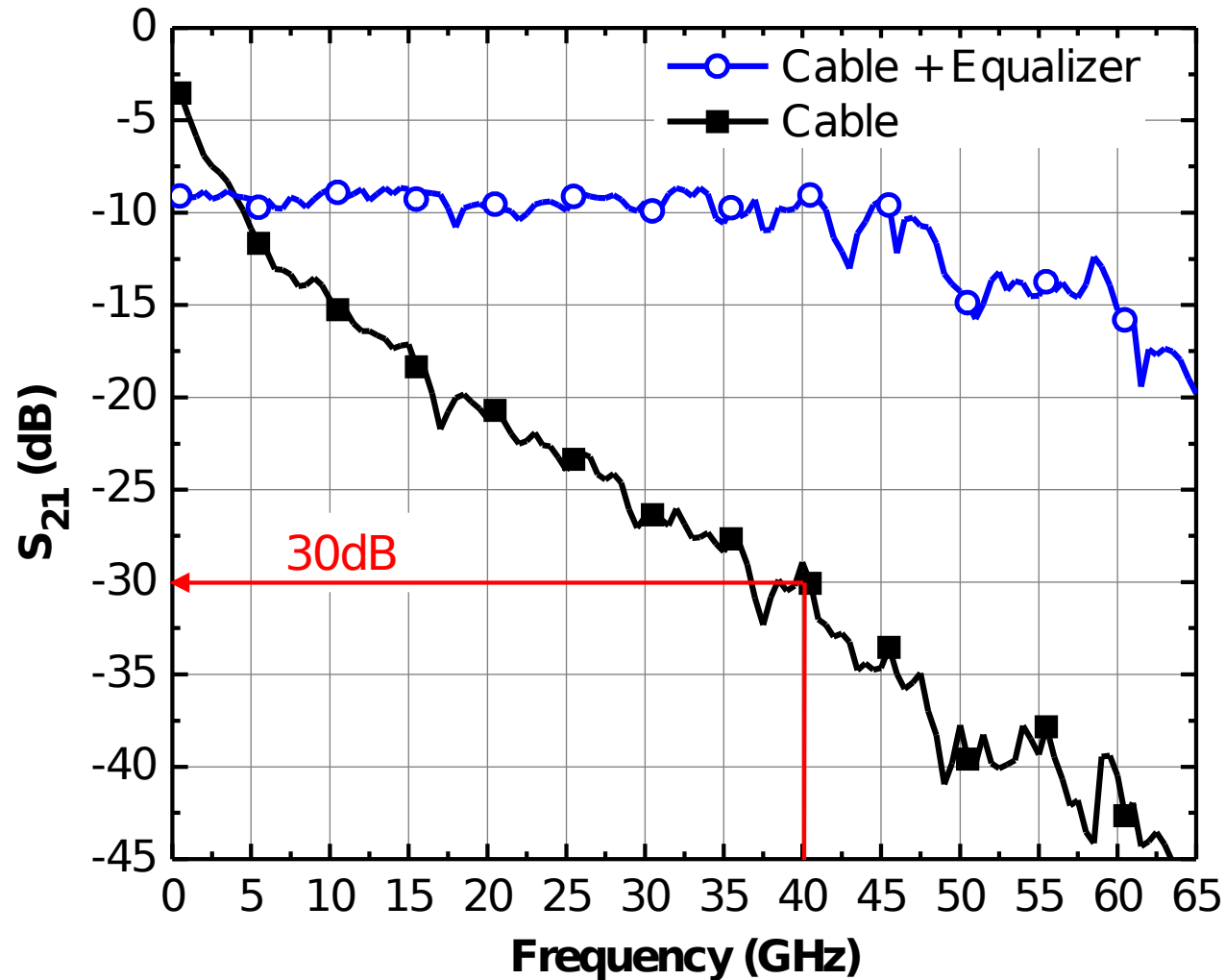


Die Photo



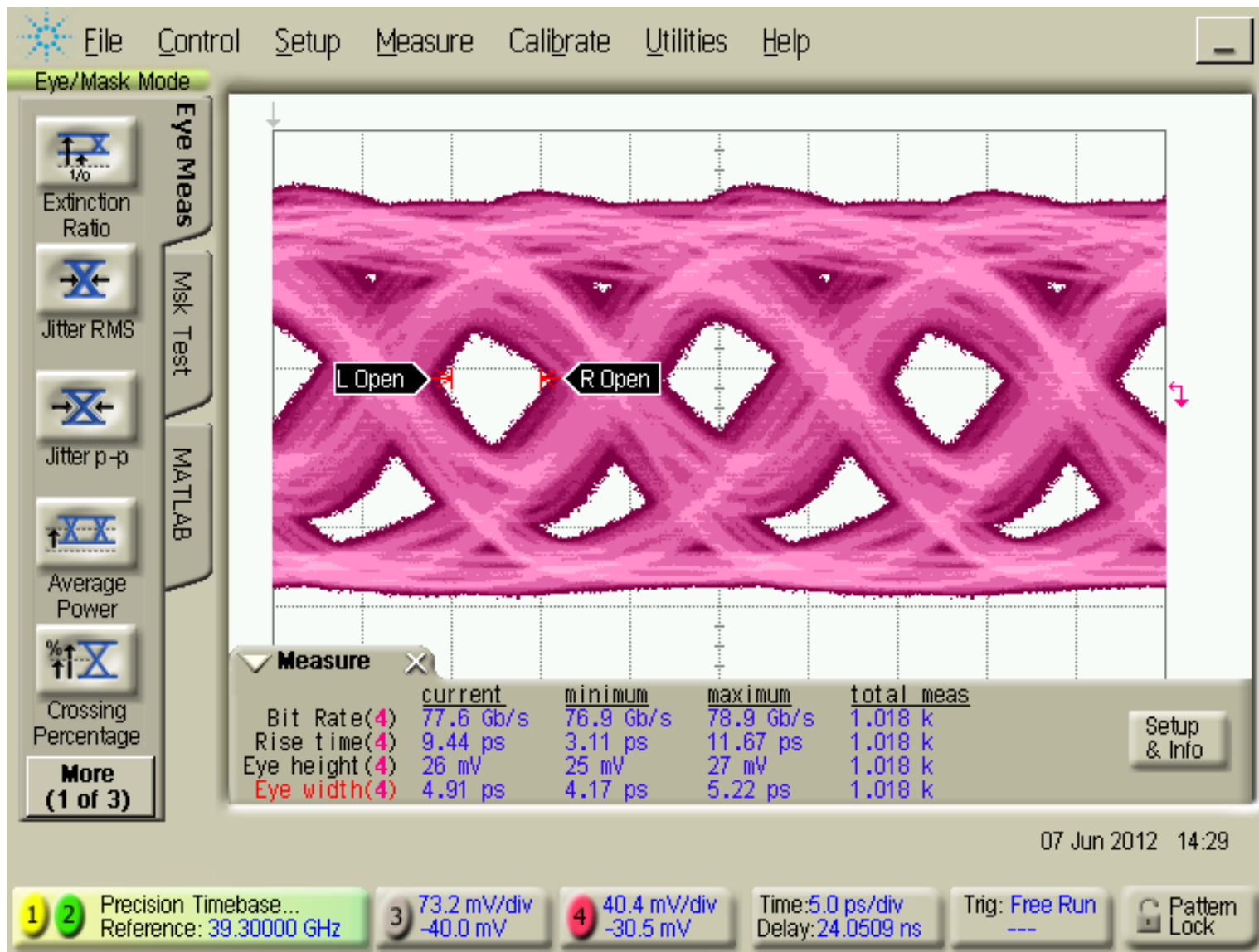
- STMicroelectronics' 130nm SiGe BiCMOS process with $f_T/f_{MAX} = 220/280$ GHz
- 1×0.7 mm $P_{DC} = 250$ mW

3.9m Cable Equalized S-parameters



- 30dB loss @ 40GHz
- BW = 50GHz after equalization

3.9m Cable - Equalized Eye



Outline

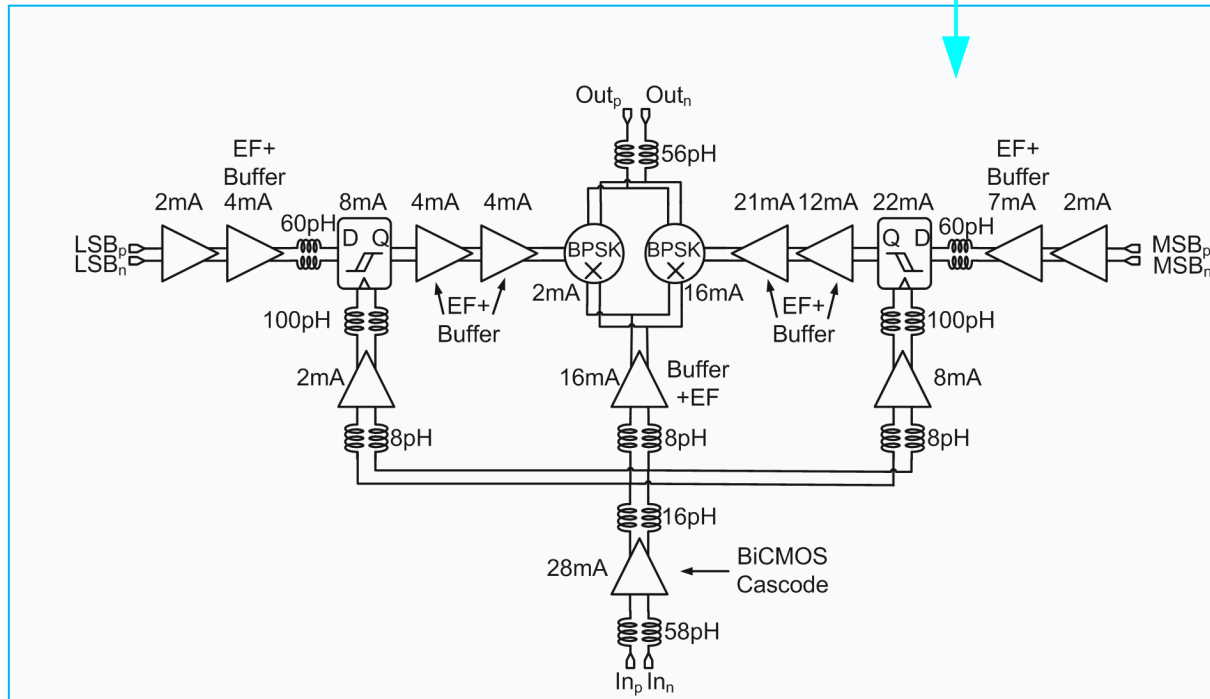
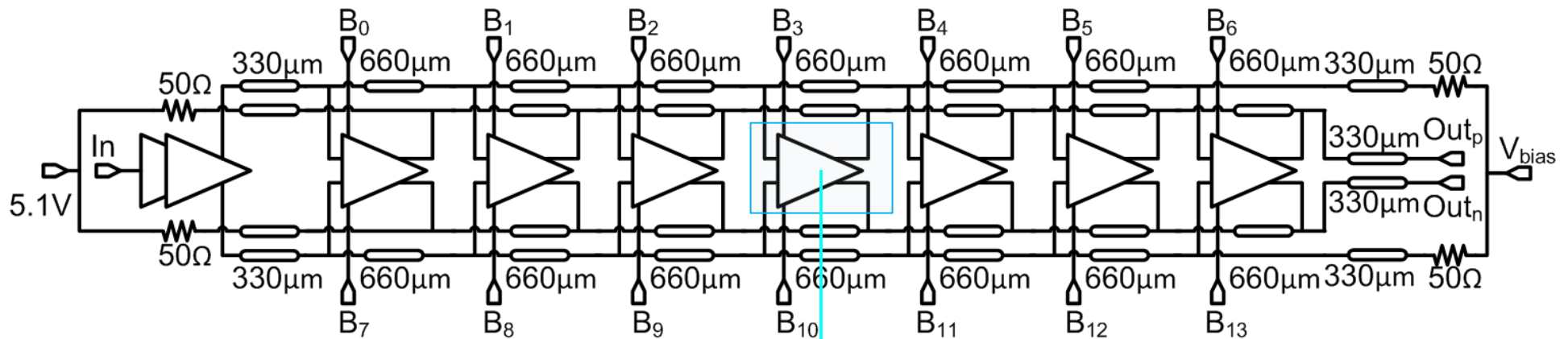
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- **Broadband and Tuned mm-wave DAC Transmitters**
- 150-170 GHz Transceiver with 3 on Die Antennas
- 143-150 GHz SUCCESS Sensor with BIST
- Potential Solutions for H-Band

6Vpp, 50-GS/sec, 6-bit RZ-DAC



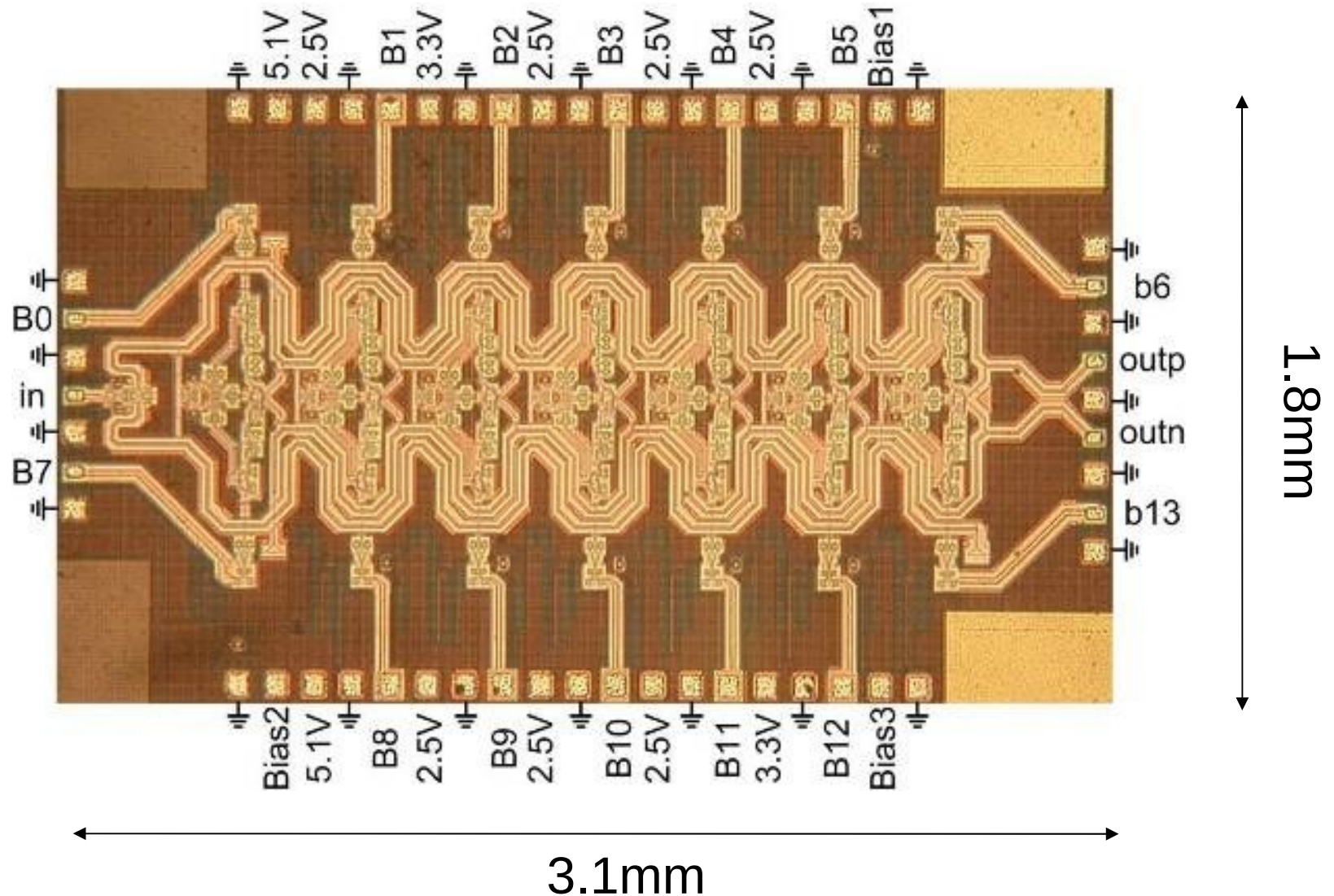
$$P_{DC} = 5W$$

Output stage = 1.2W
14 CML bit streams at
50 Gb/s => 3.8W

[A. Balteanu
IMS 2012]

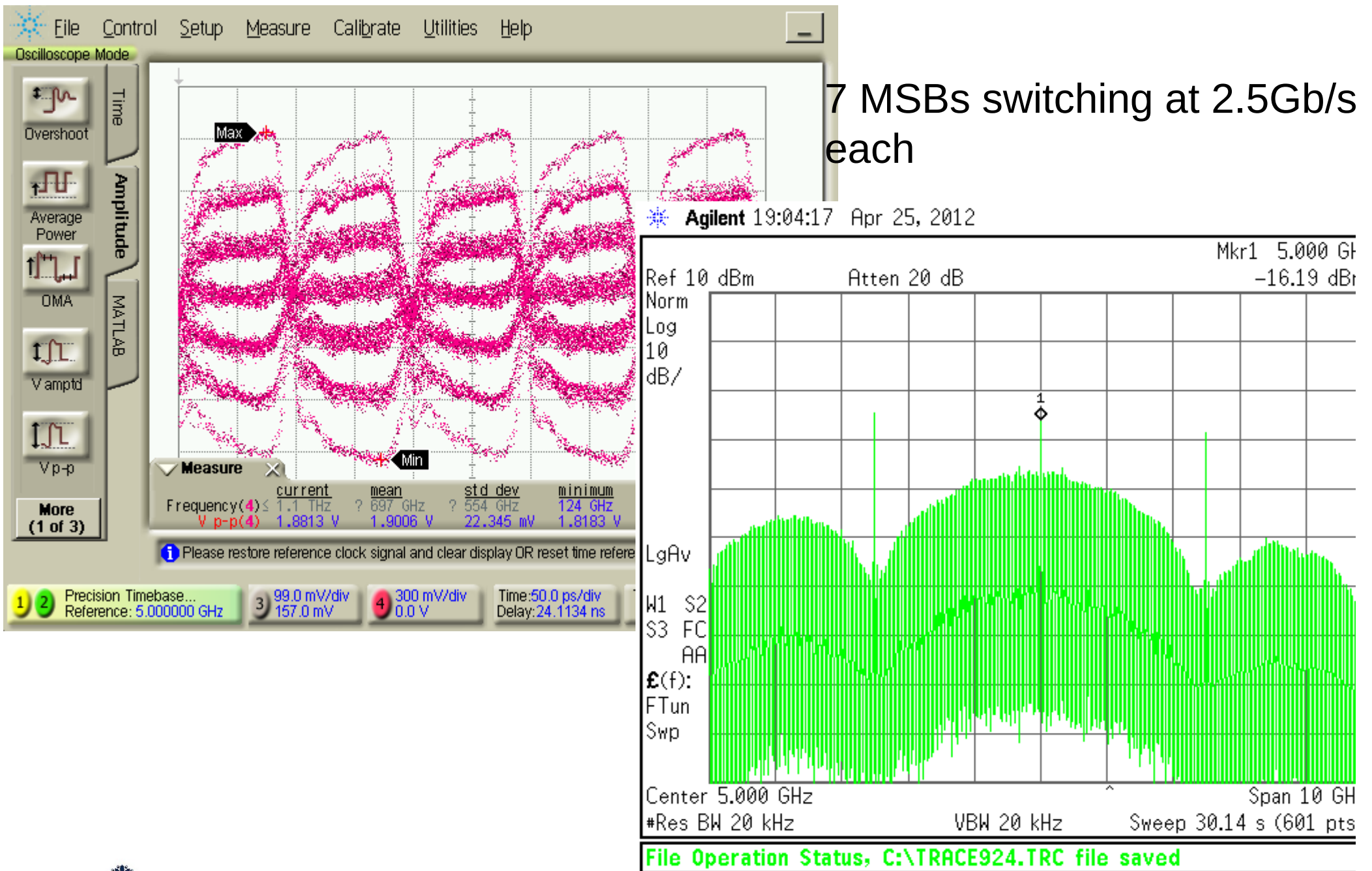
- Distributed Segmentation: 7 MSBs and 7 LSBs in 8:1 size ratio
- Each bit retimed at up to 50 GHz

Die Photo (V1)

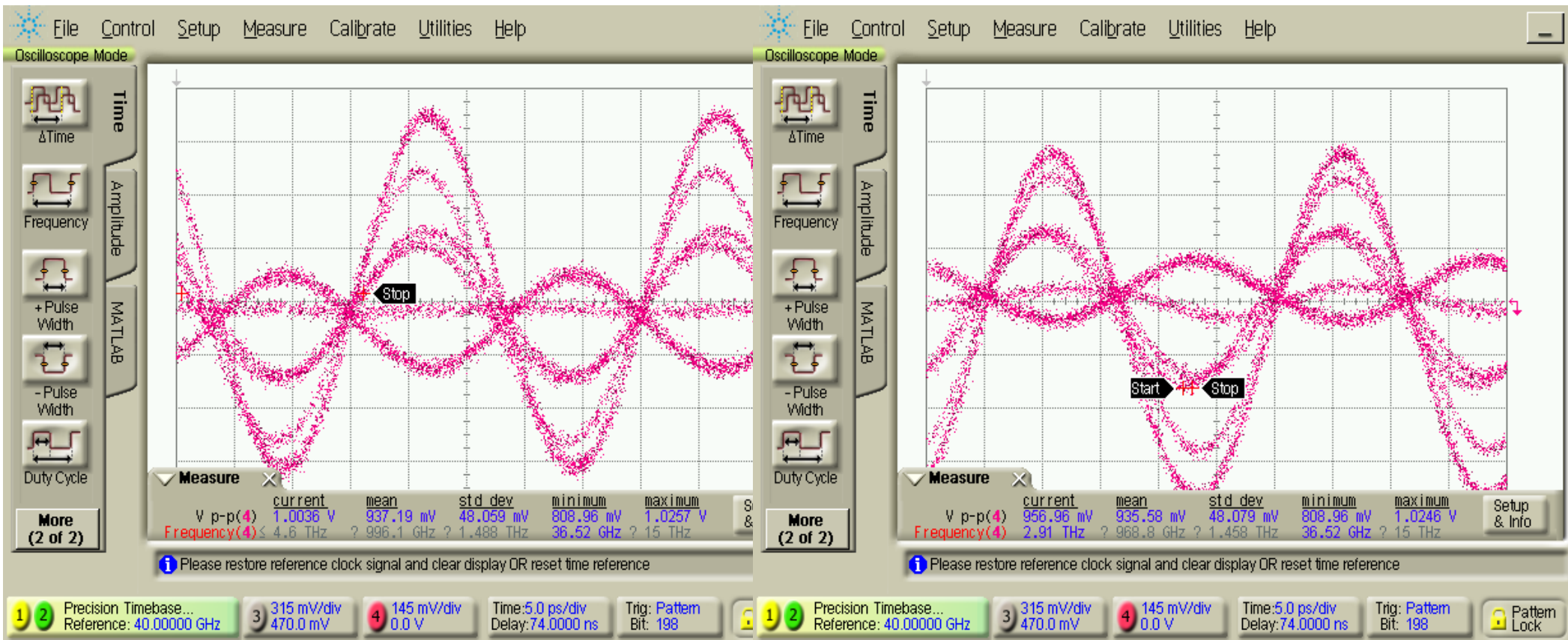


ST's 130-nm SiGe BiCMOS Production Process
 $f_T/f_{MAX} = 230/280$ GHz

5 GHz large signal swing, spectra



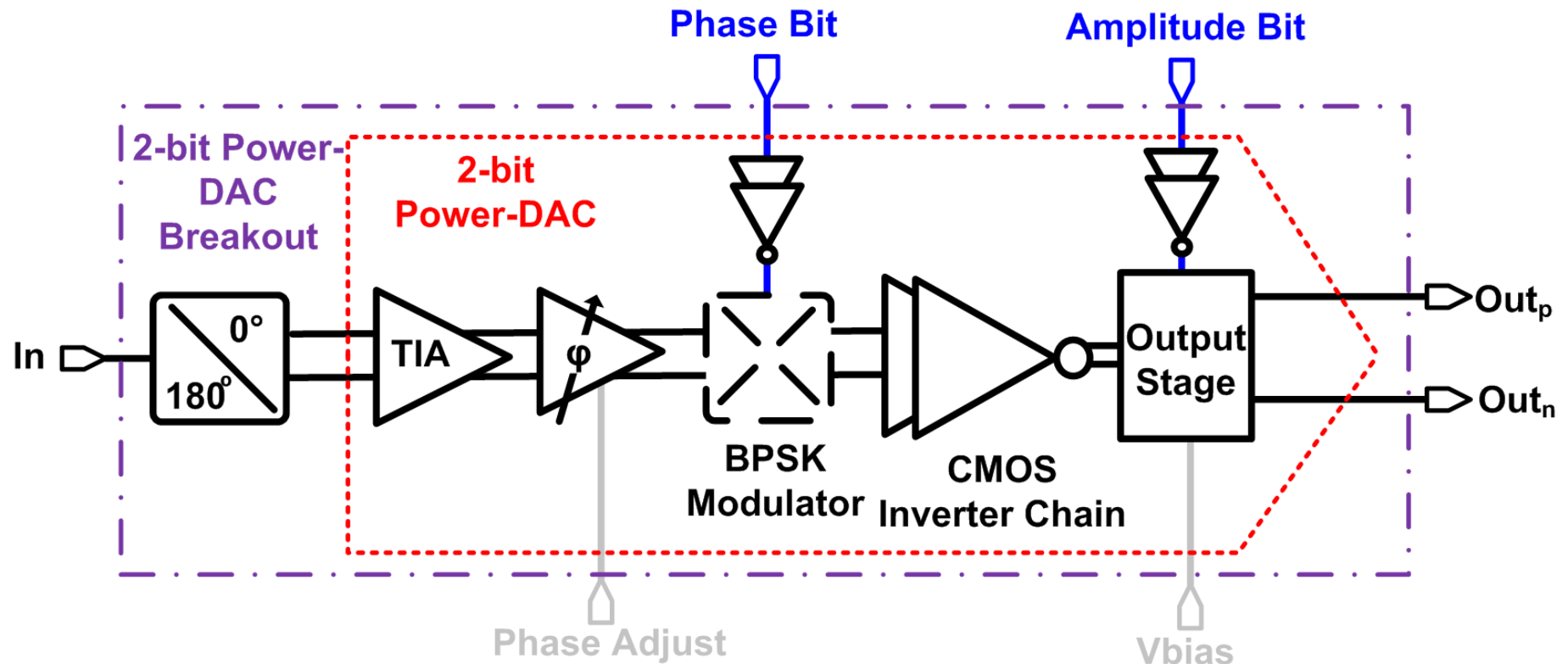
40 GHz with Sign Reversal



4 MSB's switching at 1.25 Gb/s
Retimed at 40 GHz
all other MSB's = "0"

4 MSB's switching at 1.25 Gb/s
Retimed at 40 GHz
all other MSB's = "1"

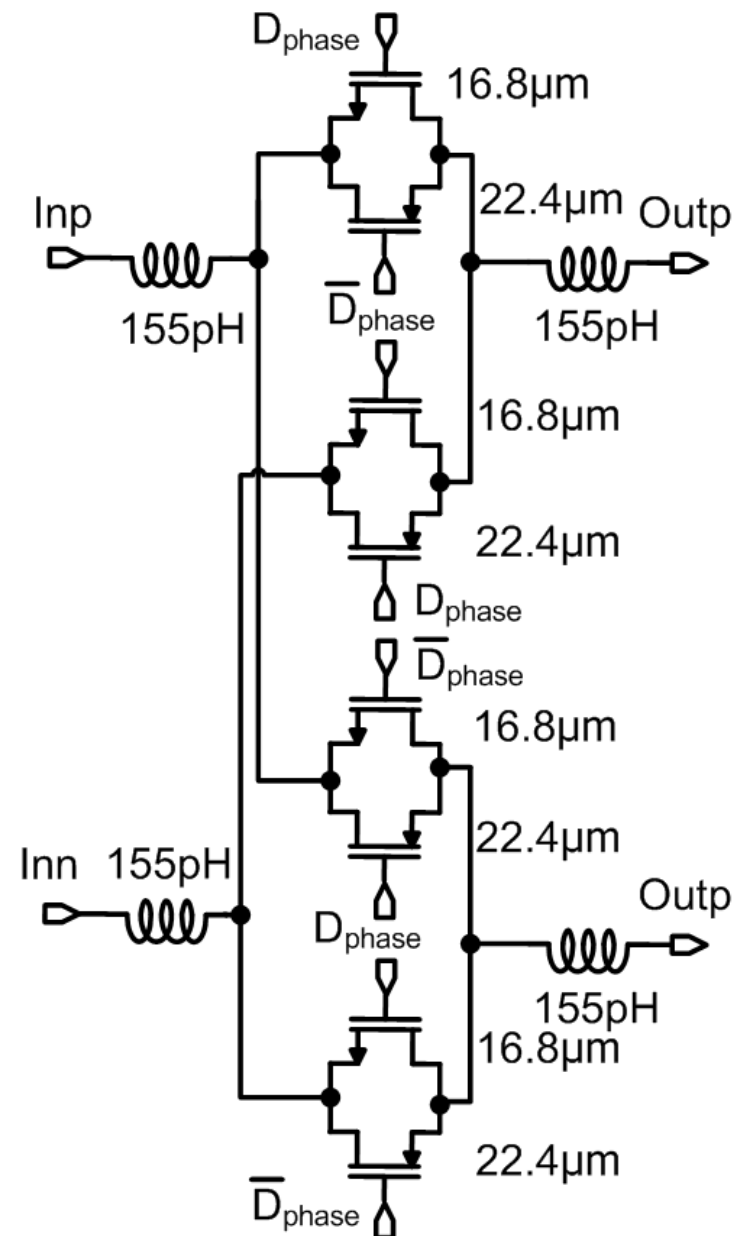
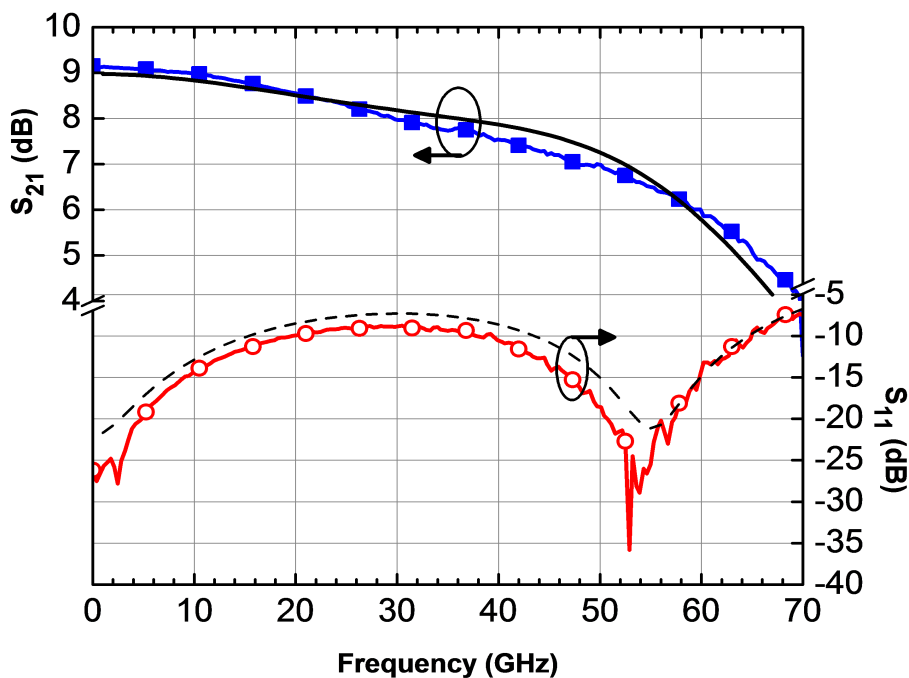
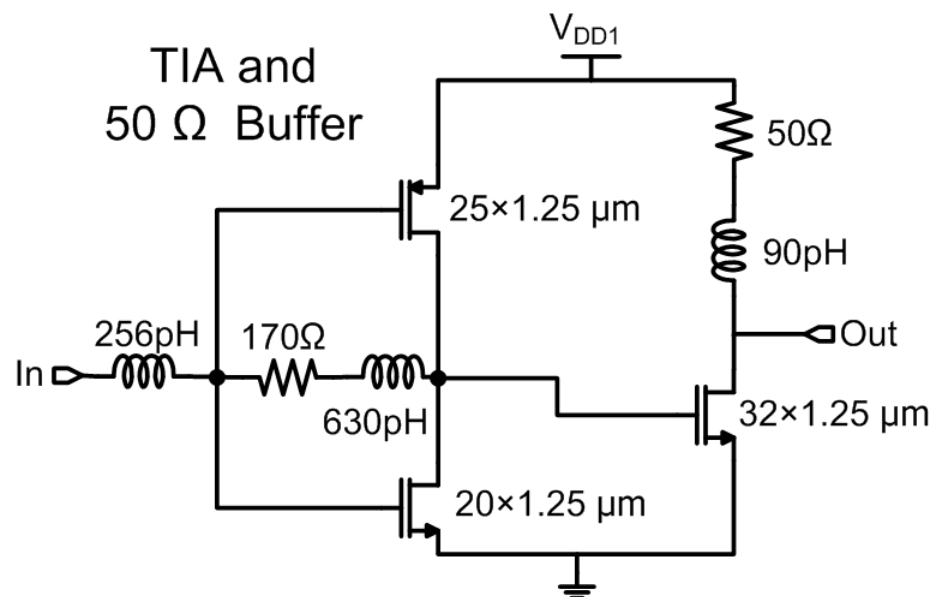
Power-DAC Cell with N-MOS output stage



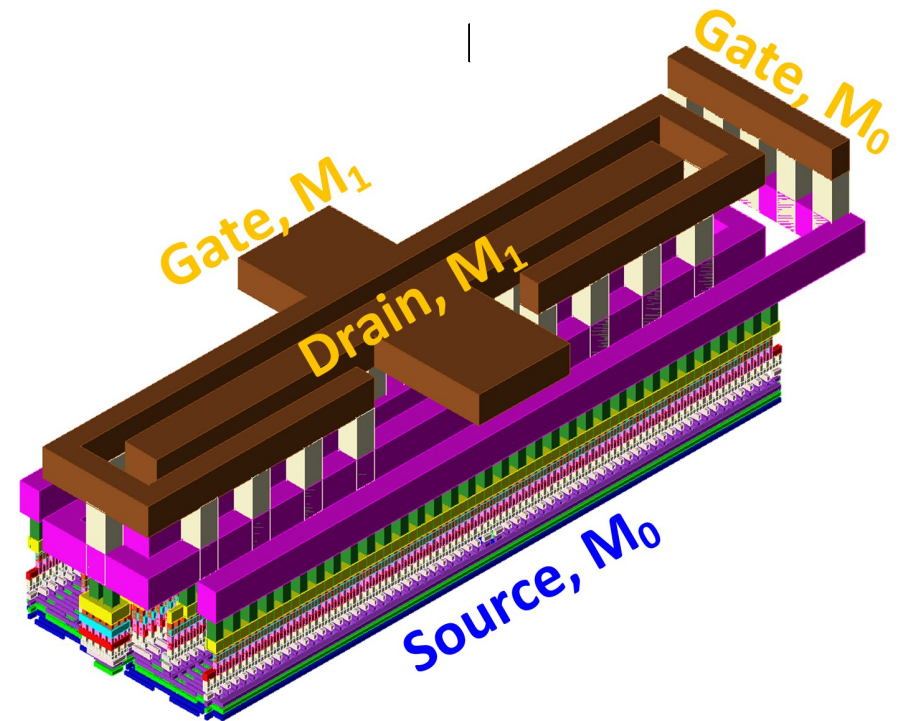
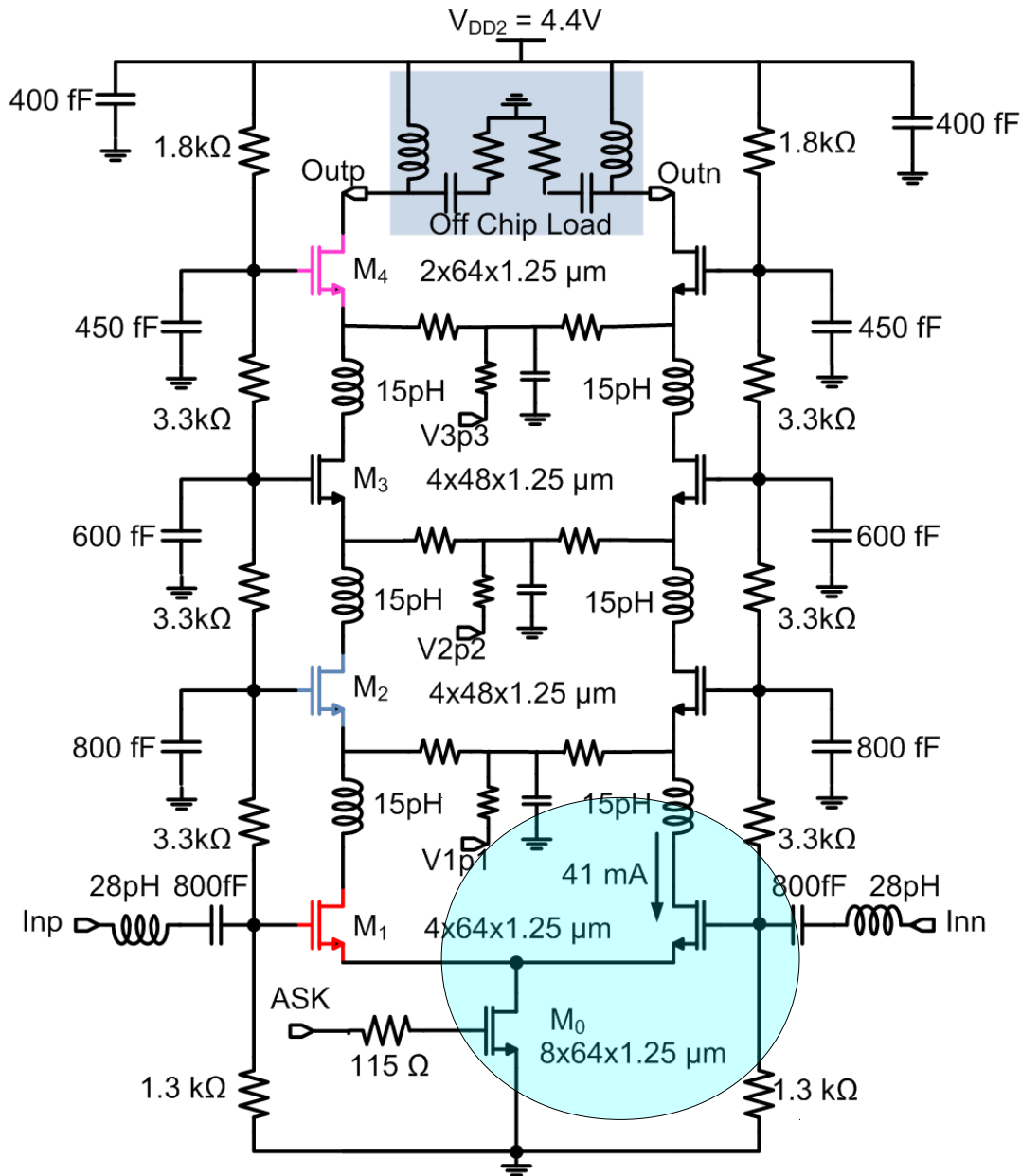
- DC – 50 GHz in 45-nm SOI
- CMOS inverter based. Purely digital
- Scalable to 240 GHz using tuned LO path

[A. Balteanu
RFIC-2012]

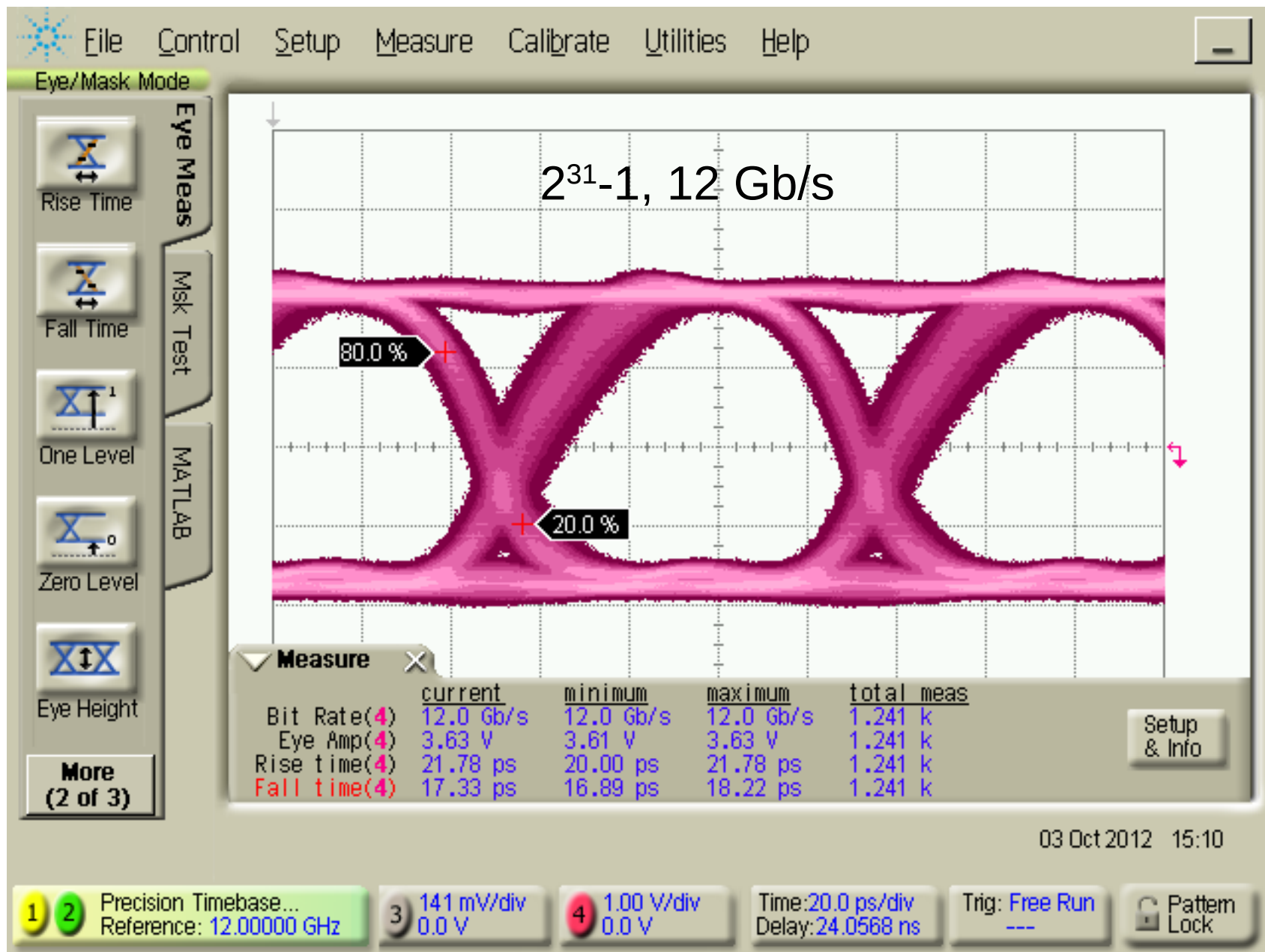
TIA, BPSK Modulator



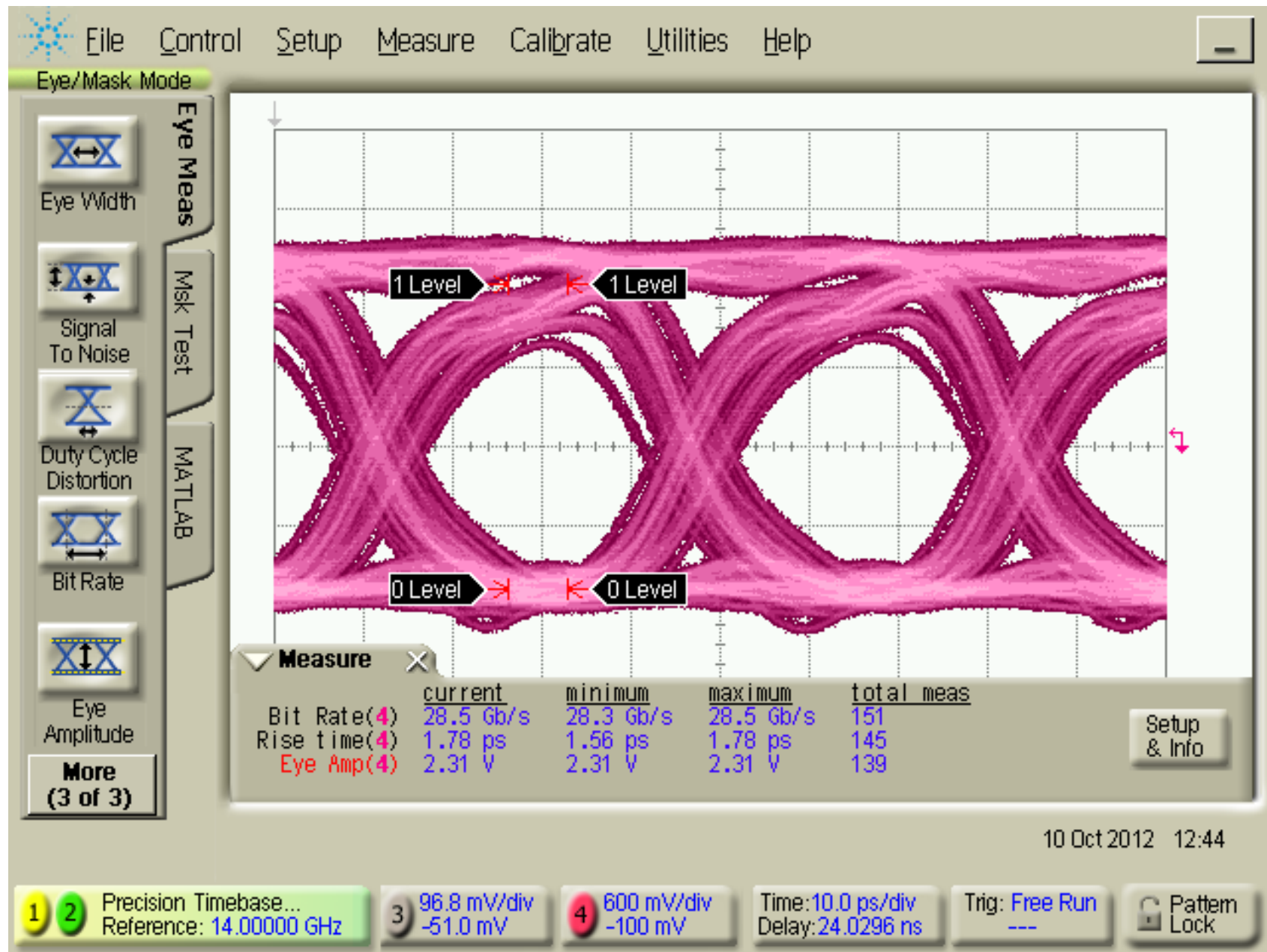
Differential output stage with On-Off switch



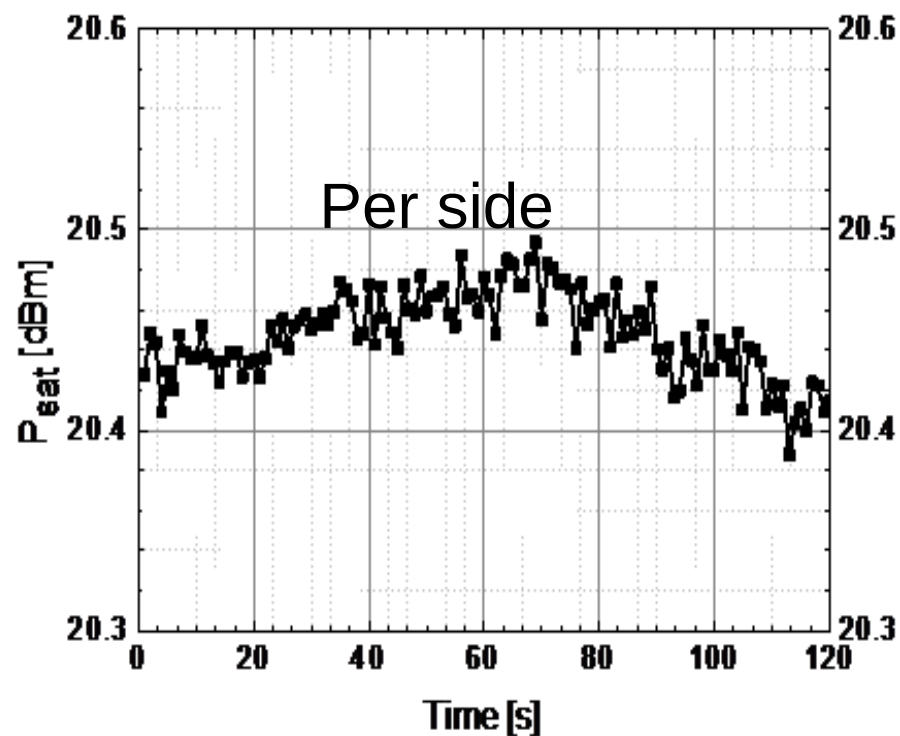
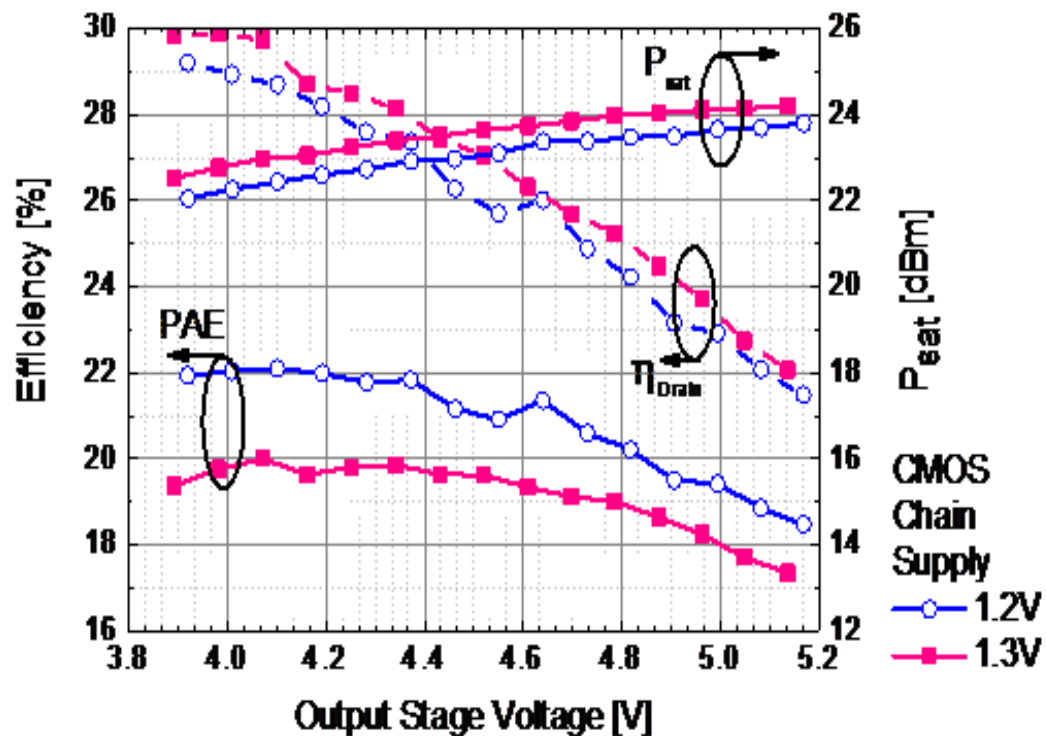
4-Stacked n-MOS Cascode



DAC Cell: 28 Gb/s Eyes

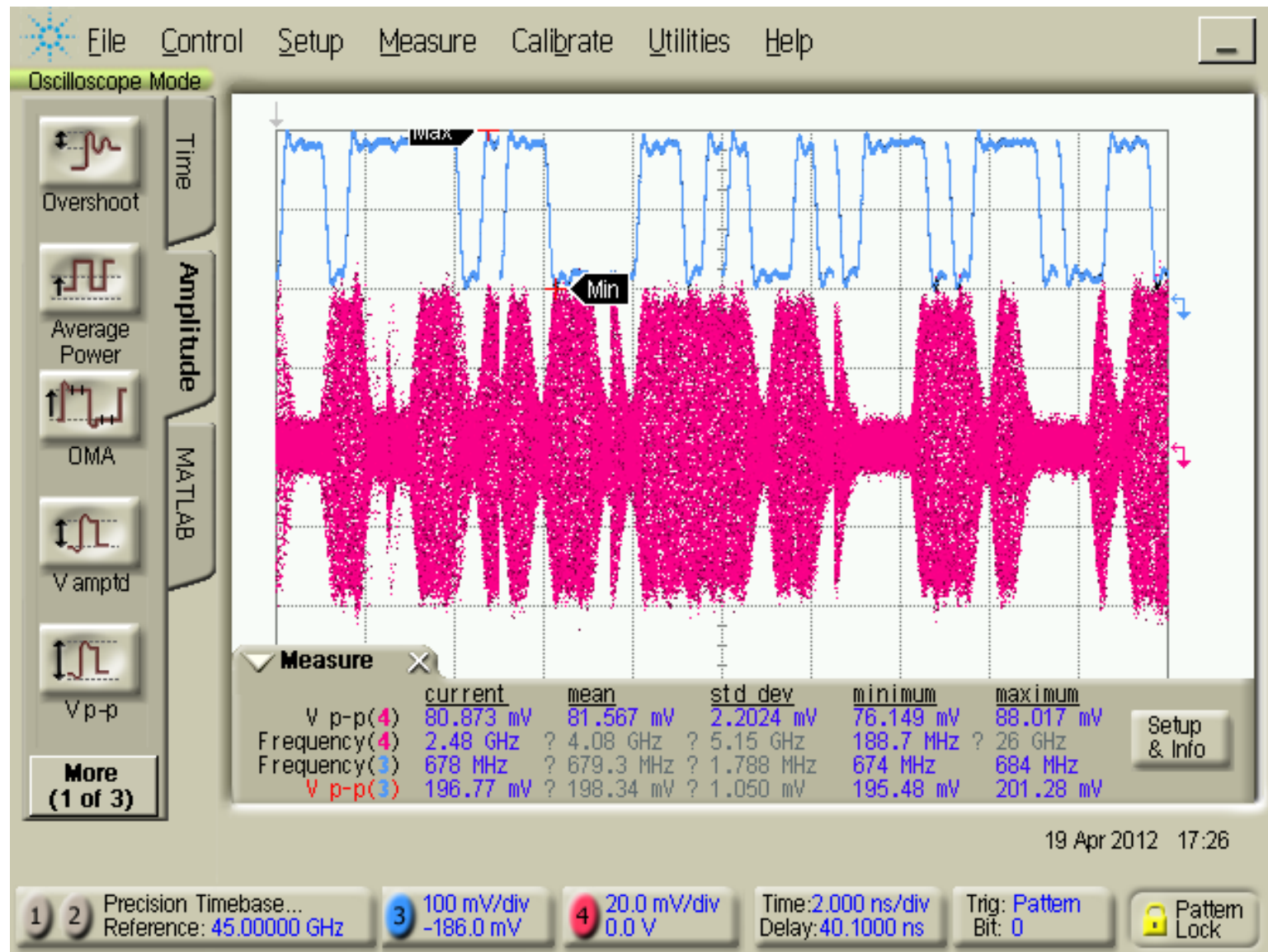


Pout of 45-GHz DAC cell vs. time

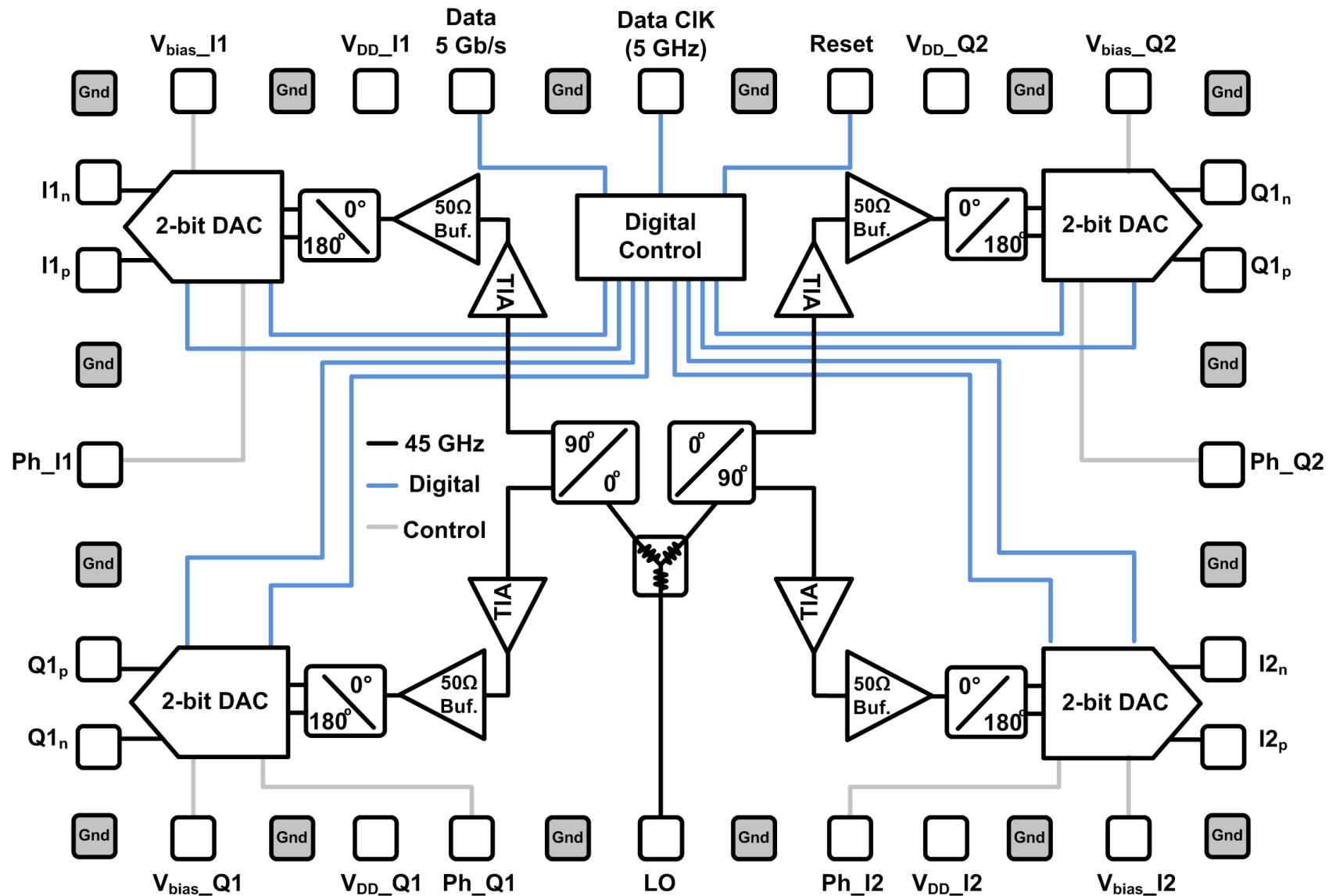


- $P_{sat} = 23$ dBm, $\eta_{Drain} = 30\%$, PAE = 20%, 4.1V/1.3V
- $P_{sat} = 24.3$ dBm, $\eta_{Drain} = 22\%$, PAE = 16.3%, 5.1V/1.4V

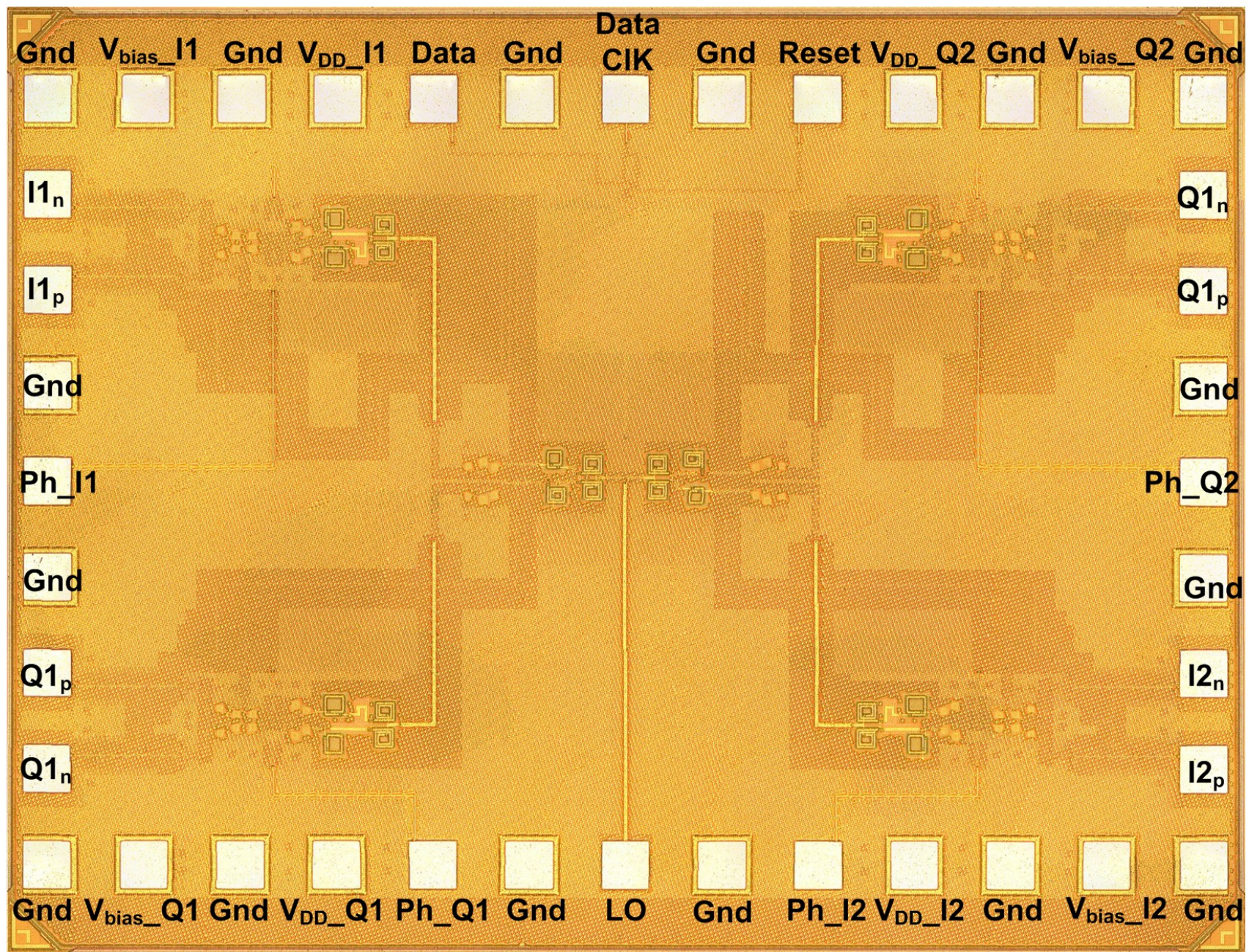
2-Gb/s ASK+ 2-Gbs BPSK Mod of 45-GHz Carrier



45-GHz 8-bit IQ DAC chiplet



Die photo

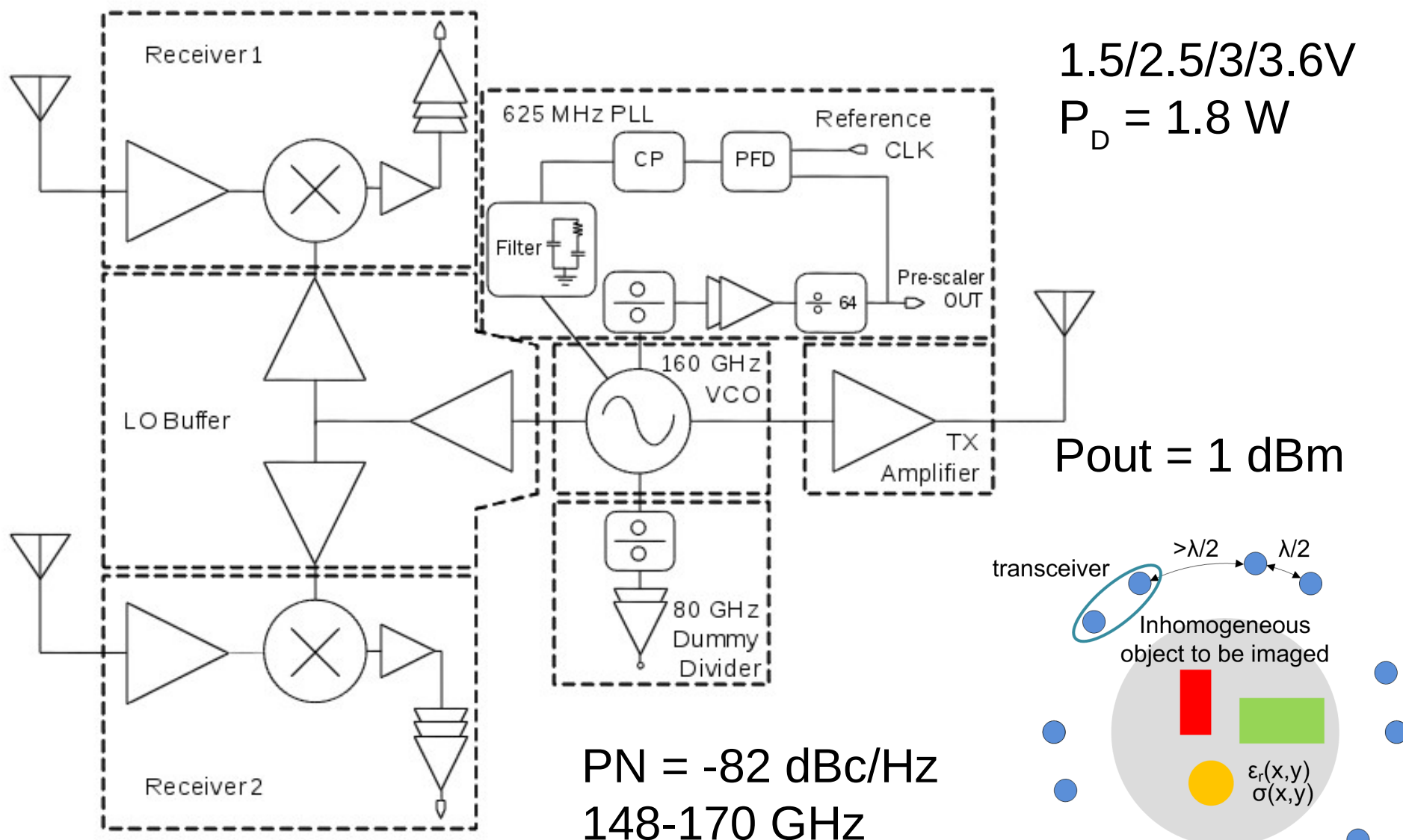


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mm-wave Transceivers

- Broadband and Tuned mm-wave DAC Transmitters
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Dual Receive Channel Transceiver

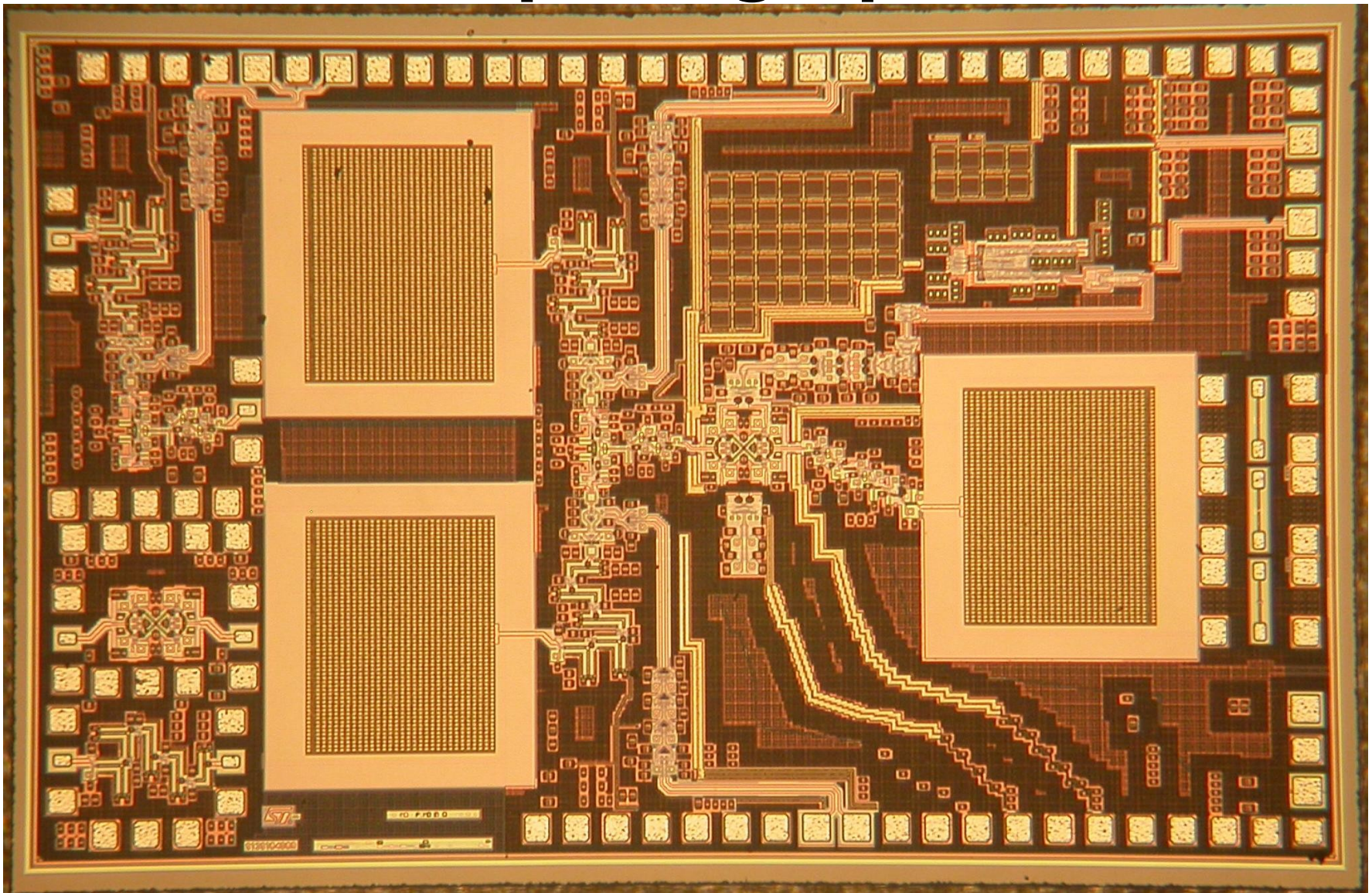


RX Gain = 27 dB

NF = 12 dB

[I. Sarkas et al., MIKON-2012]

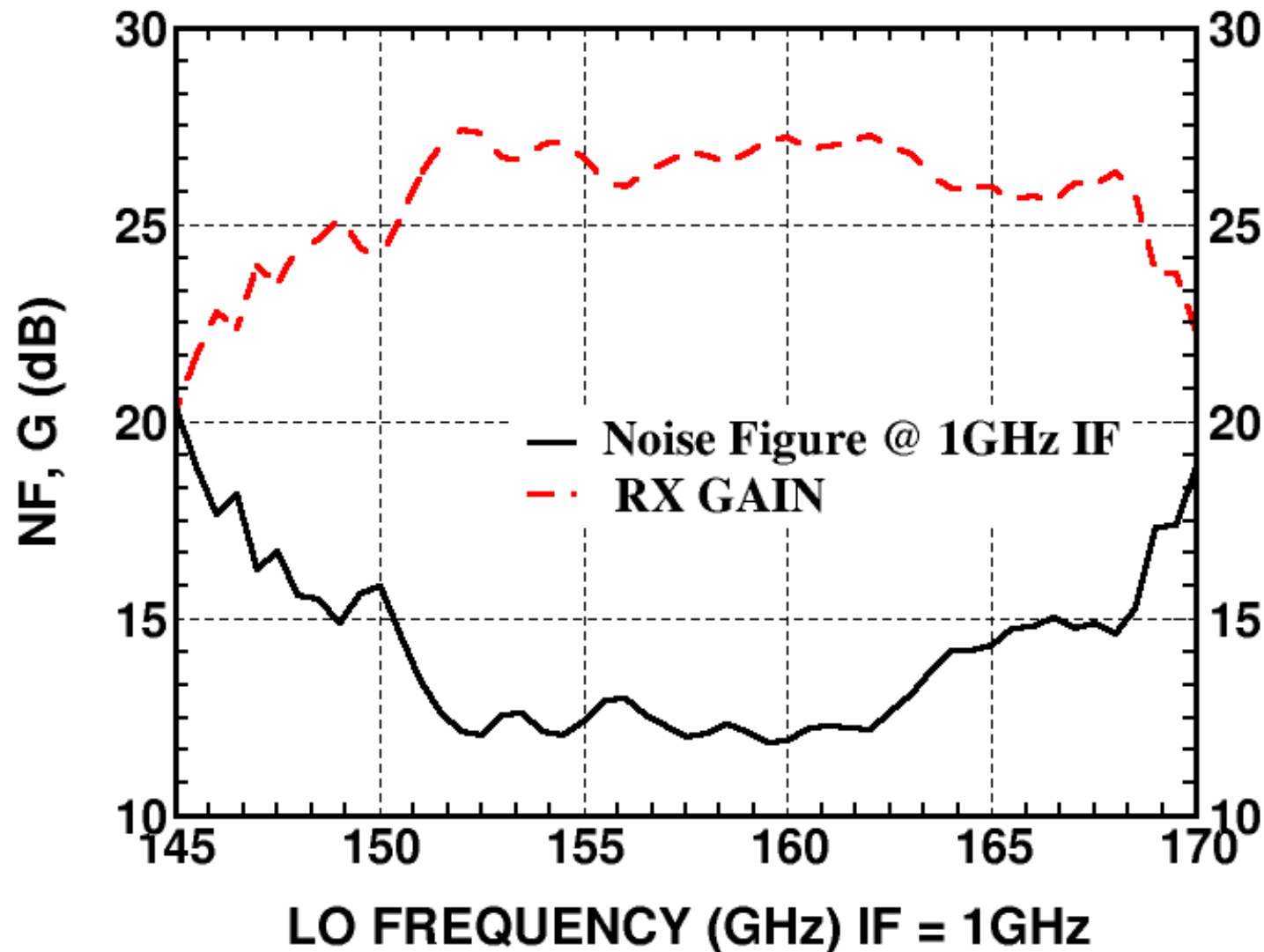
Die photograph



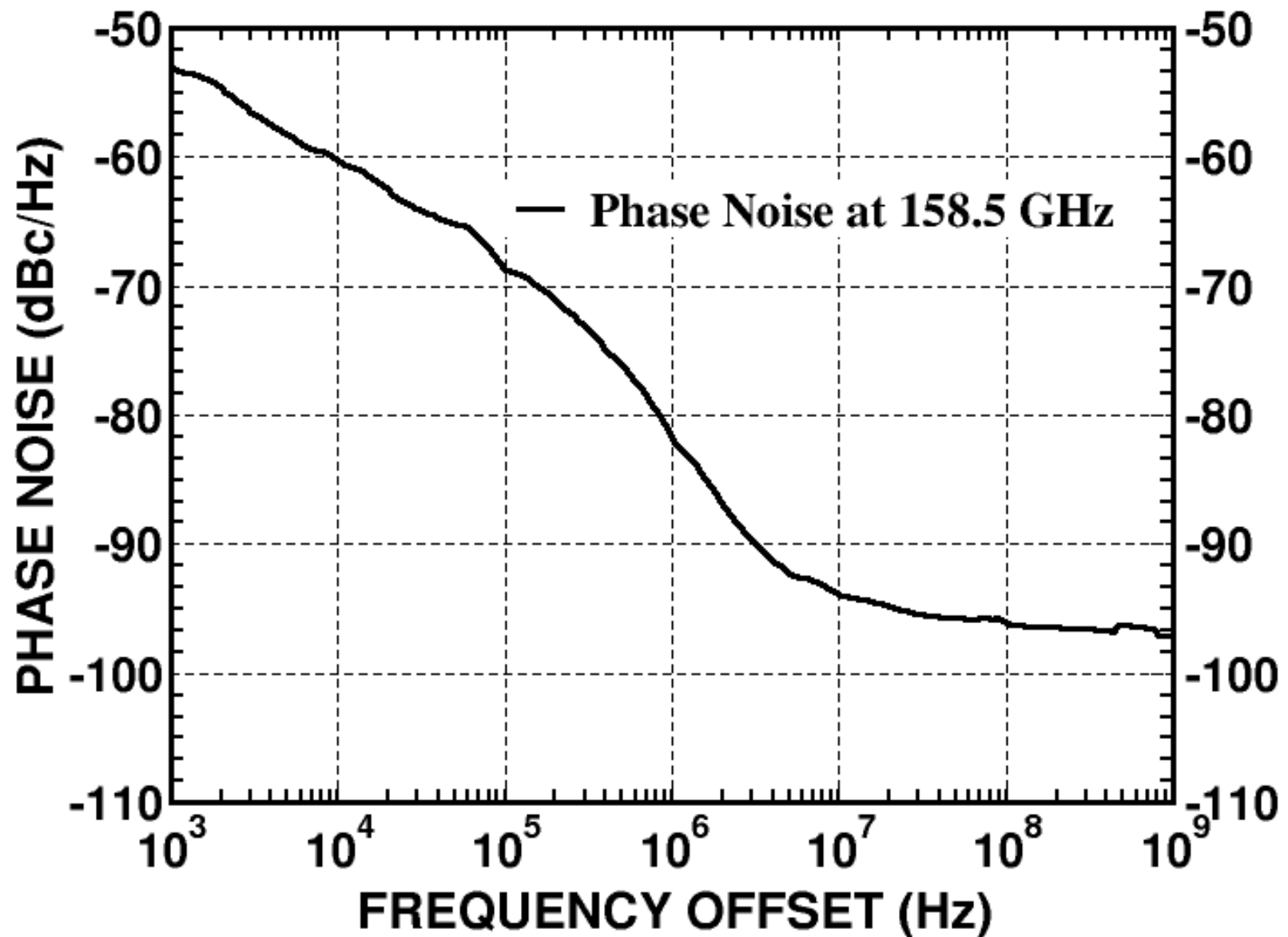
Chip: 2.1mm×2.9mm

130-nm BiCMOS9MW: SiGe HBT $f_T = 230$ GHz, $f_{MAX} = 280$ GHz

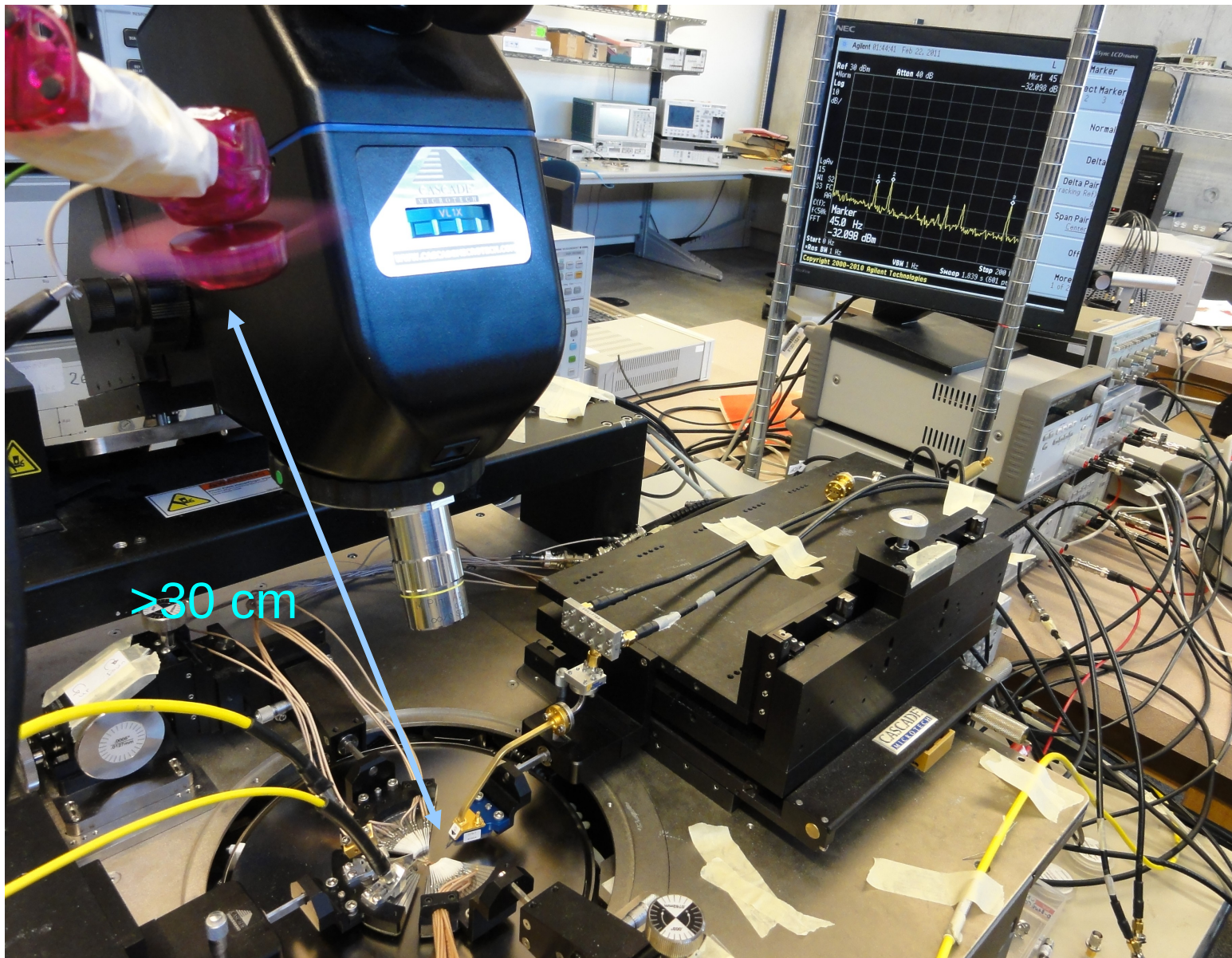
RX Breakout Gain and Noise Figure



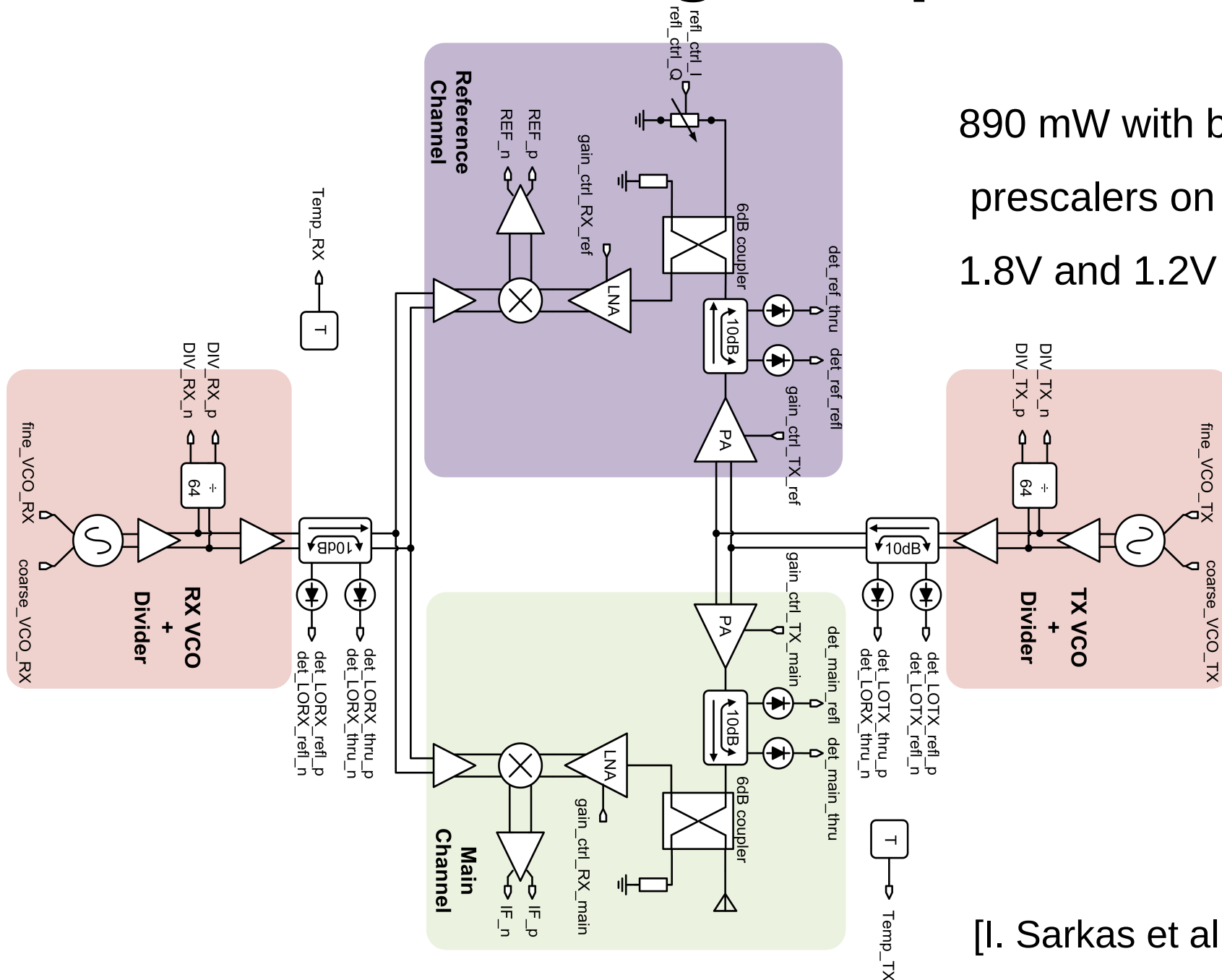
Transceiver PLL Phase Noise



On-die Doppler Test



Monostatic single-chip sensor



890 mW with both
prescalers on from
1.8V and 1.2V supplies

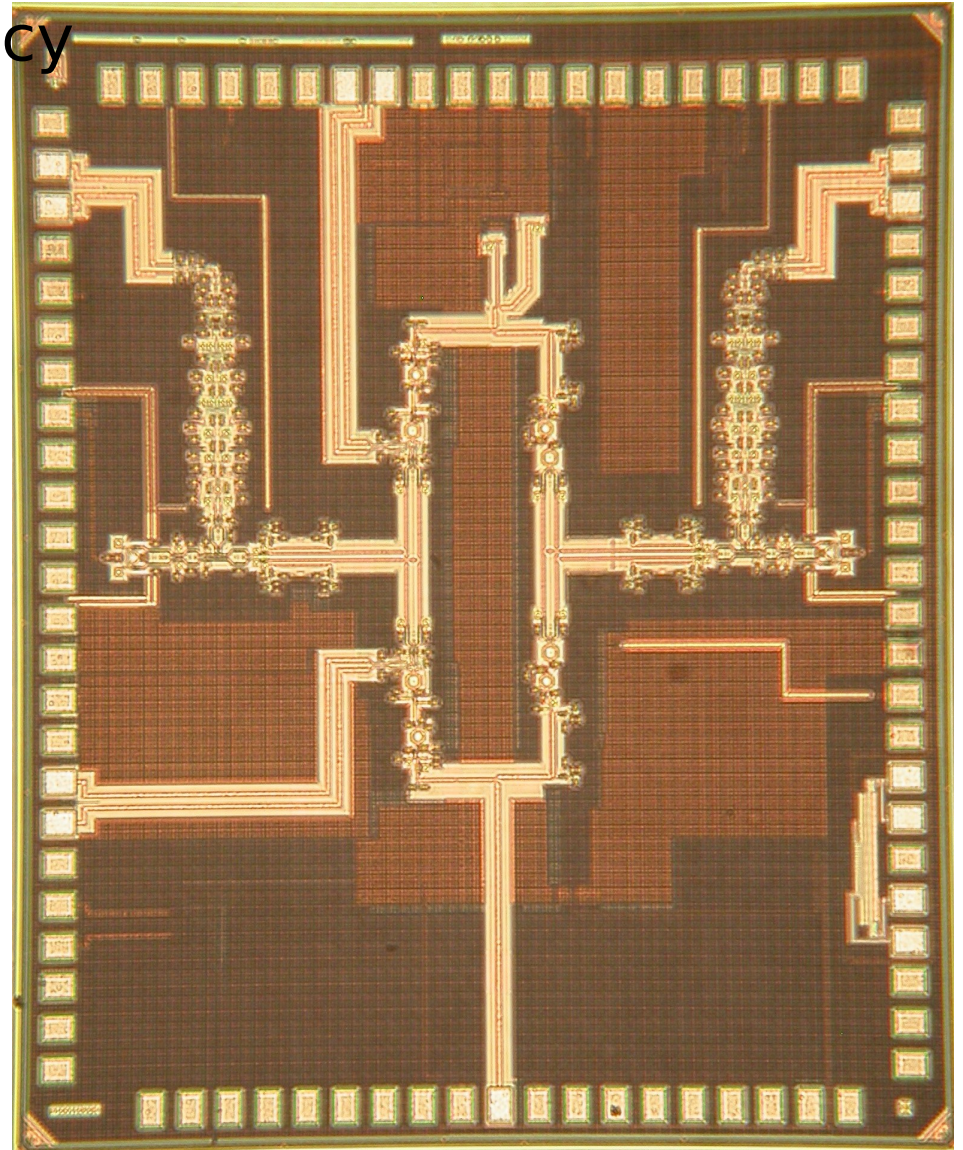
[I. Sarkas et al. CSICS 2012]

Layout and performance summary

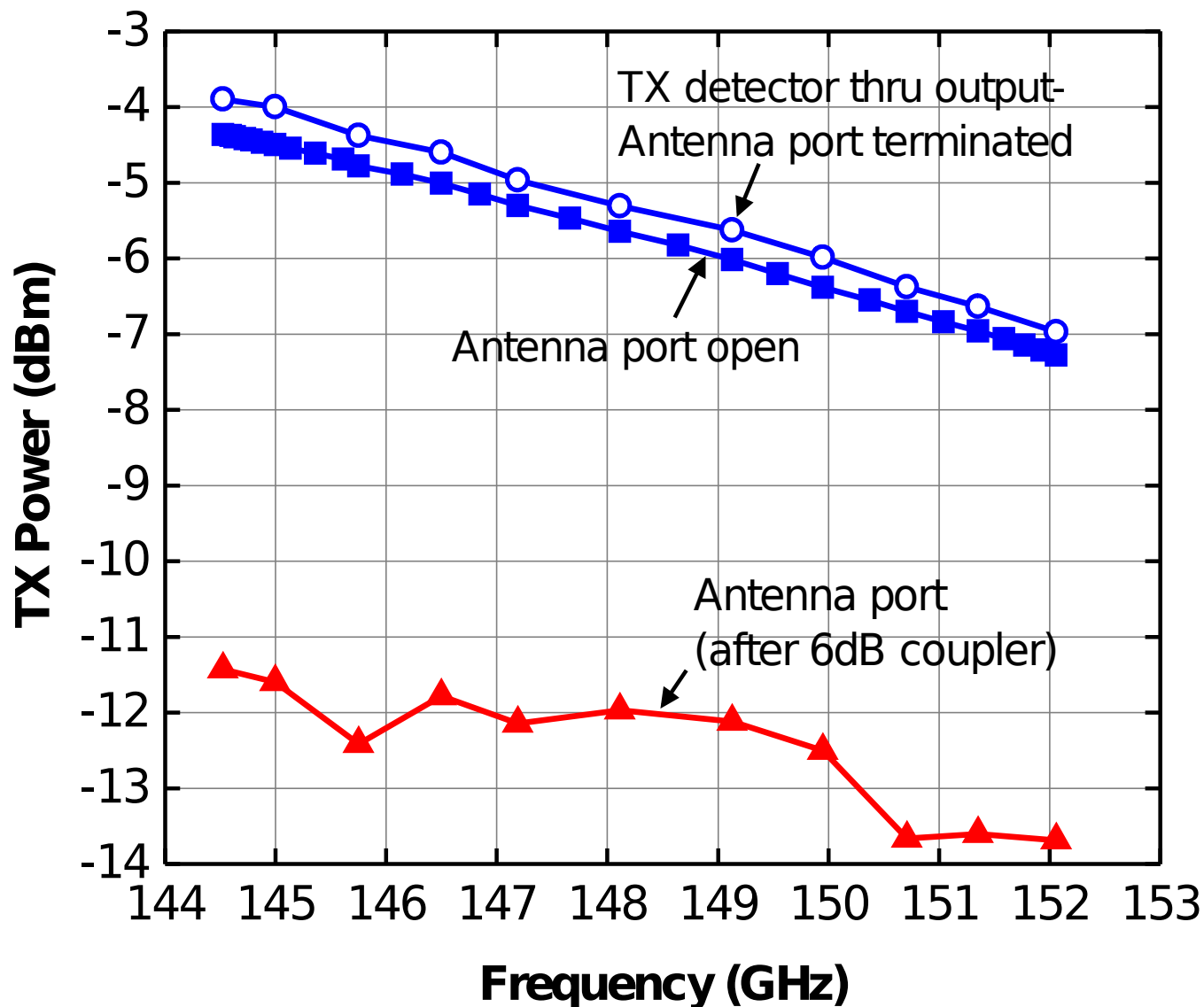
- Tuning range 142-152 GHz
- Highest fundamental frequency transceiver
- $NF < 10$ dB, $P_{out} > -6$ dBm.
- $PN < -83$ dBc/Hz at 1MHz

2.6mmx2.3mm

Block	Count	Power (mW)
VCO	2	2×76
Divider chain	1	145
LO dist	1	115
TX	1	230
RX	1	165
Total		807

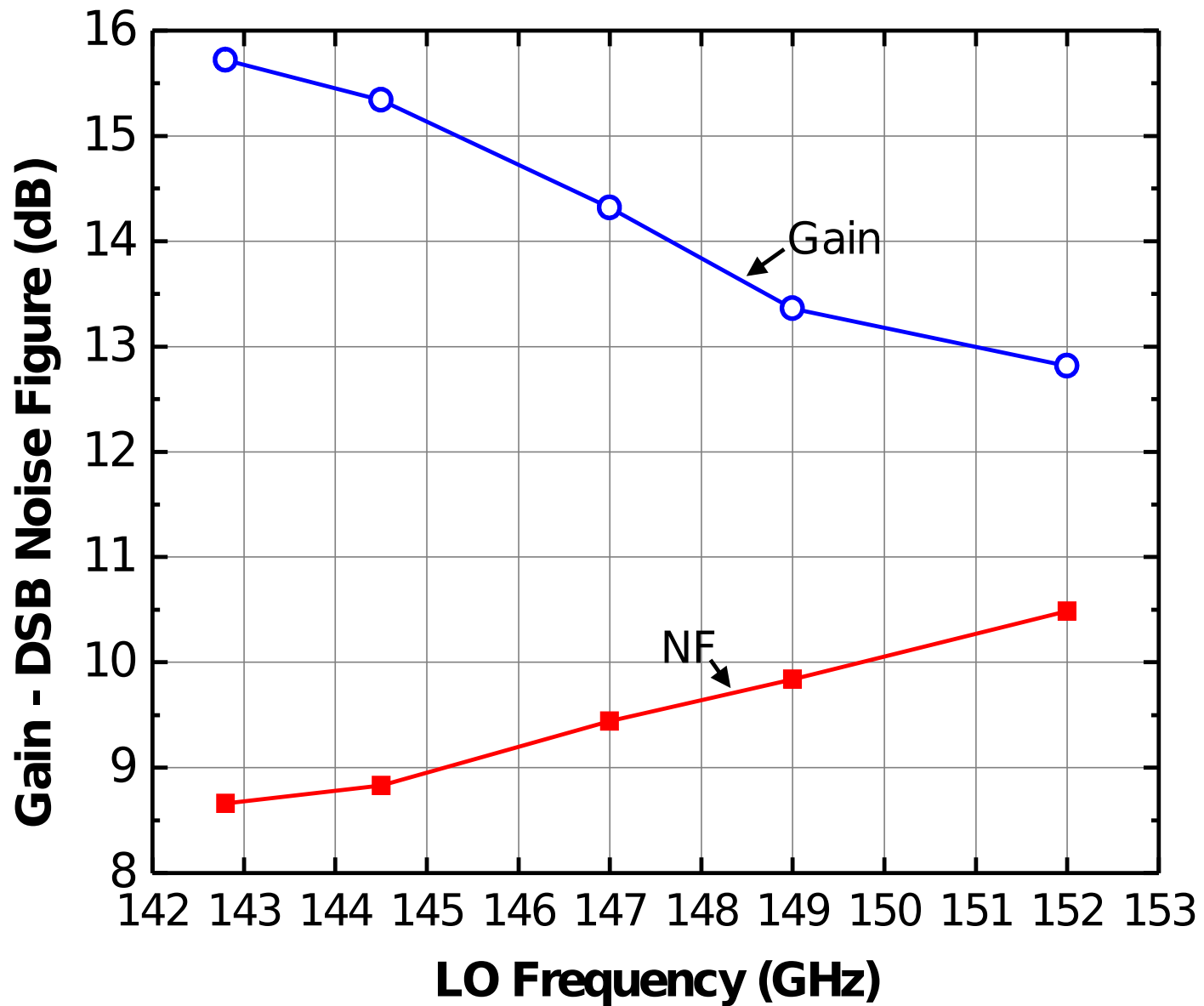


Measured output power



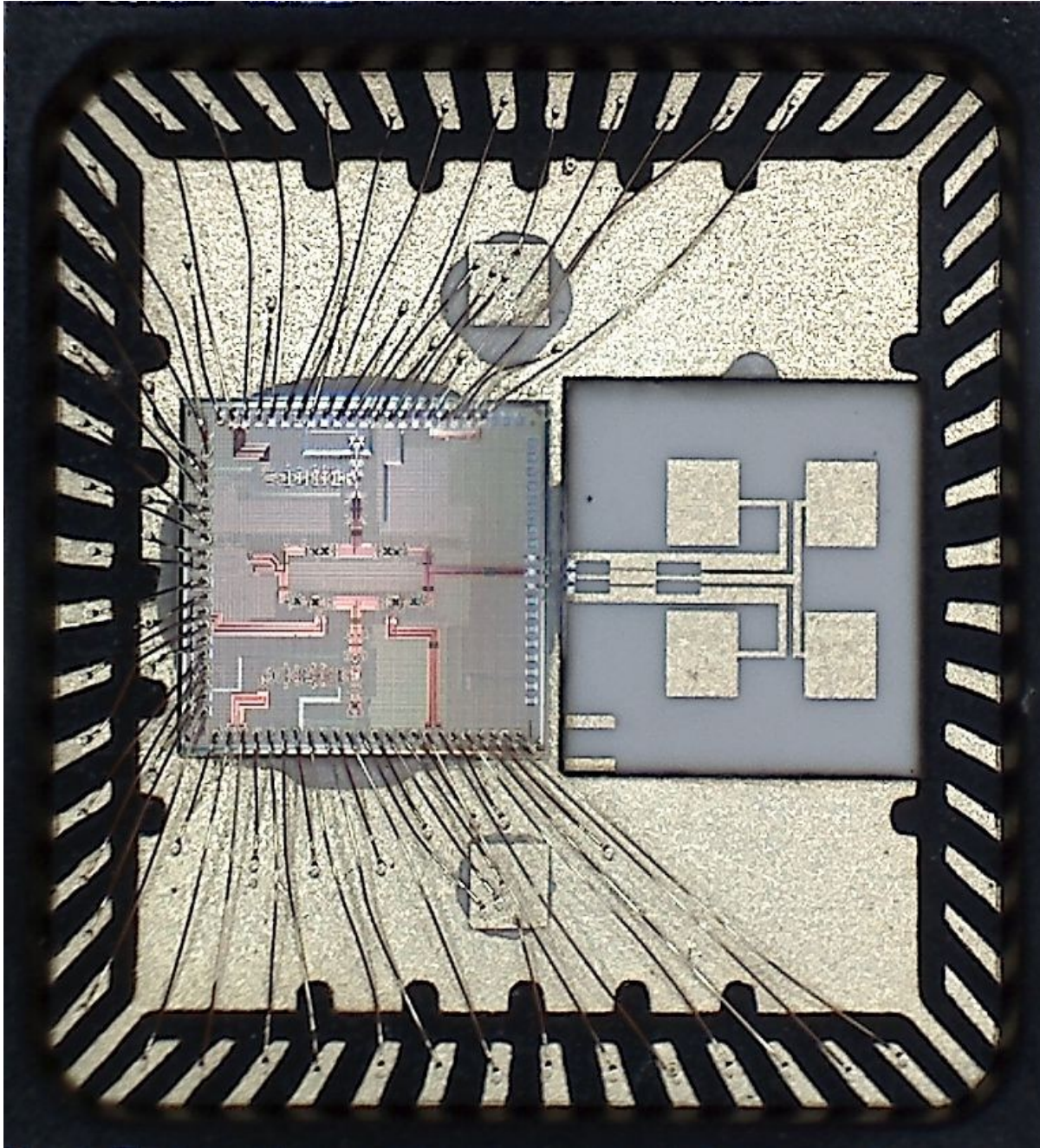
- Power at antenna port measured with ELVA power sensor
- On-chip and external measurements track very well

Receiver Gain and Noise Figure



Low noise figure: 8.5-10.5dB

Antenna and die in package



- QFN package with bondwire transition to antenna on alumina

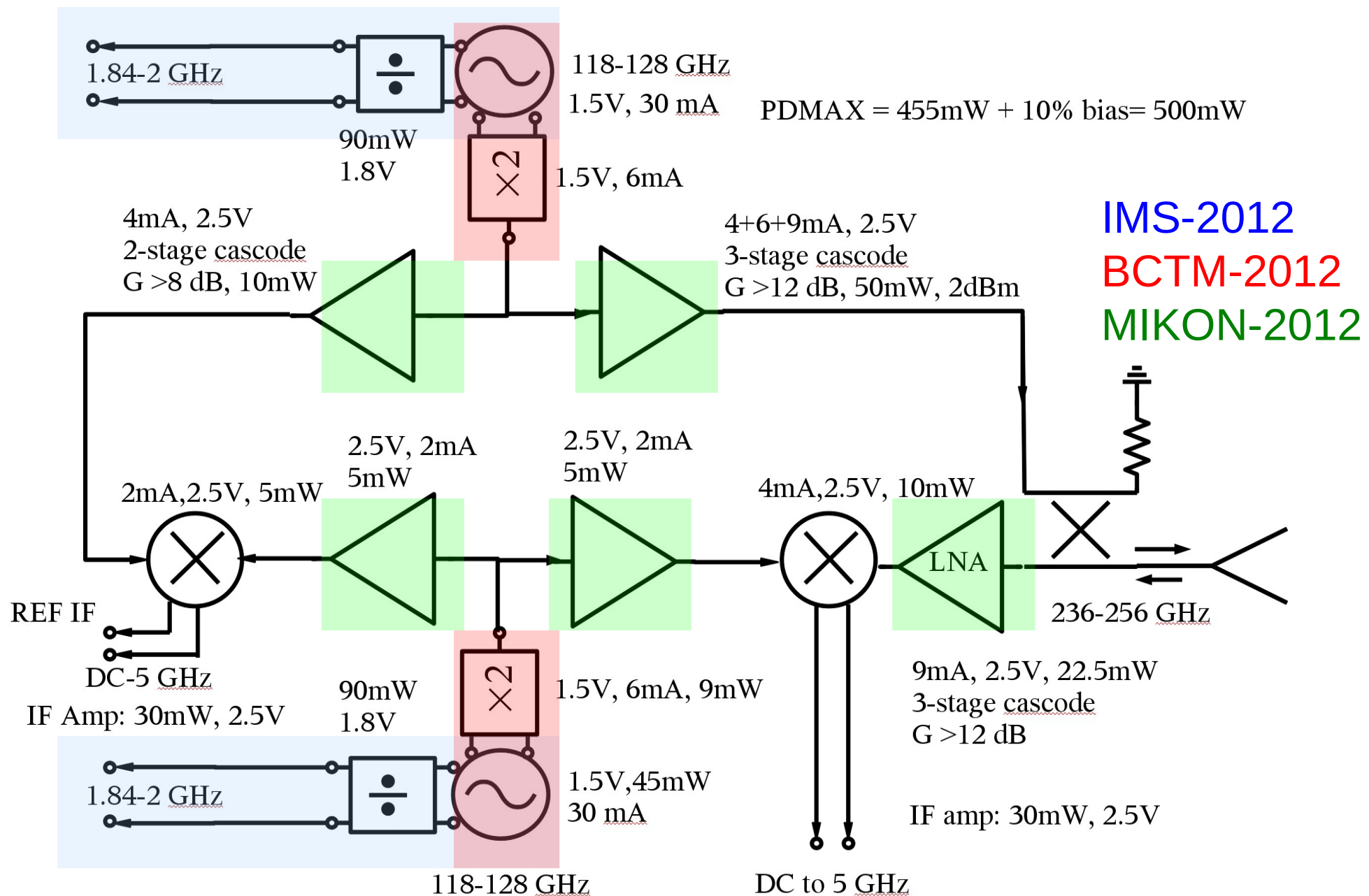
Courtesy of Robert Bosch GmbH,
Karlsruhe Institute of
Technology and
EU SUCCESS project partners

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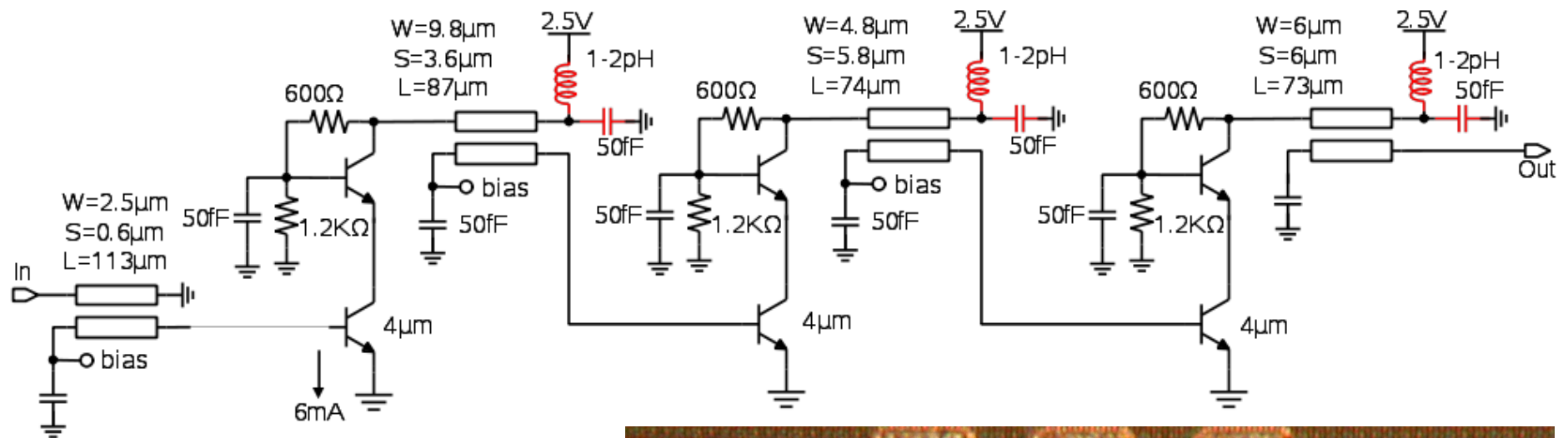
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What's Next: 240-GHz Transceiver?

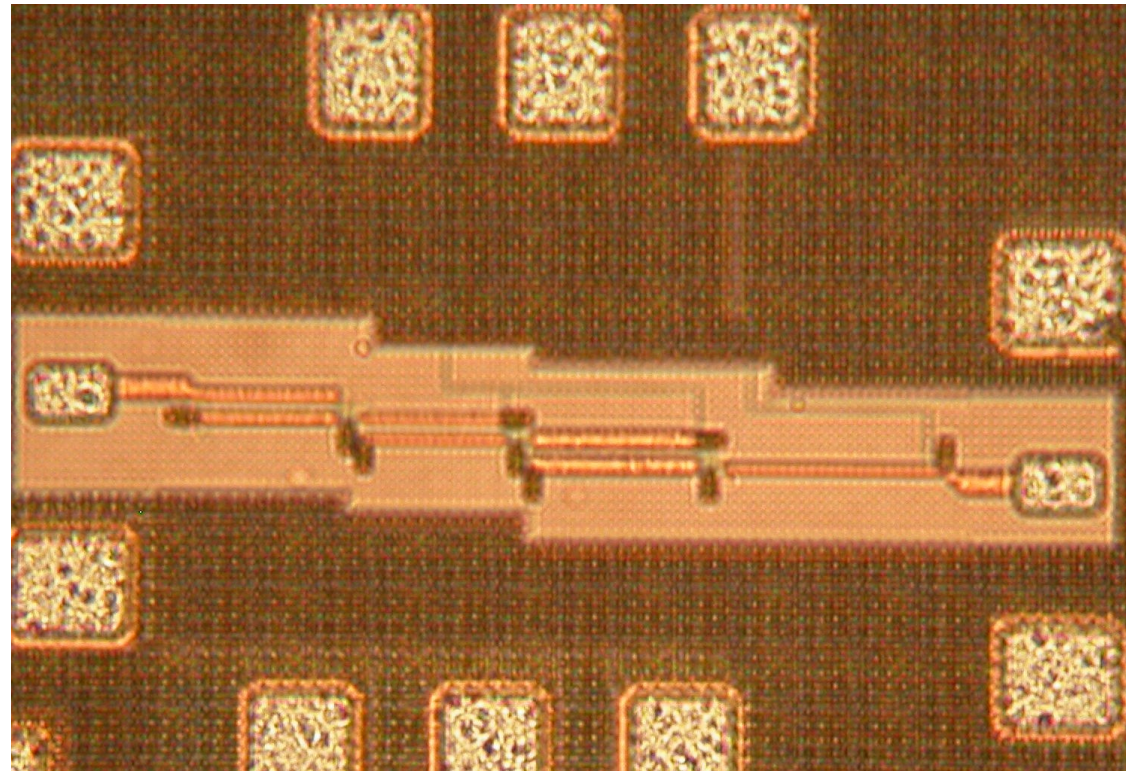


240-GHz Amplifier



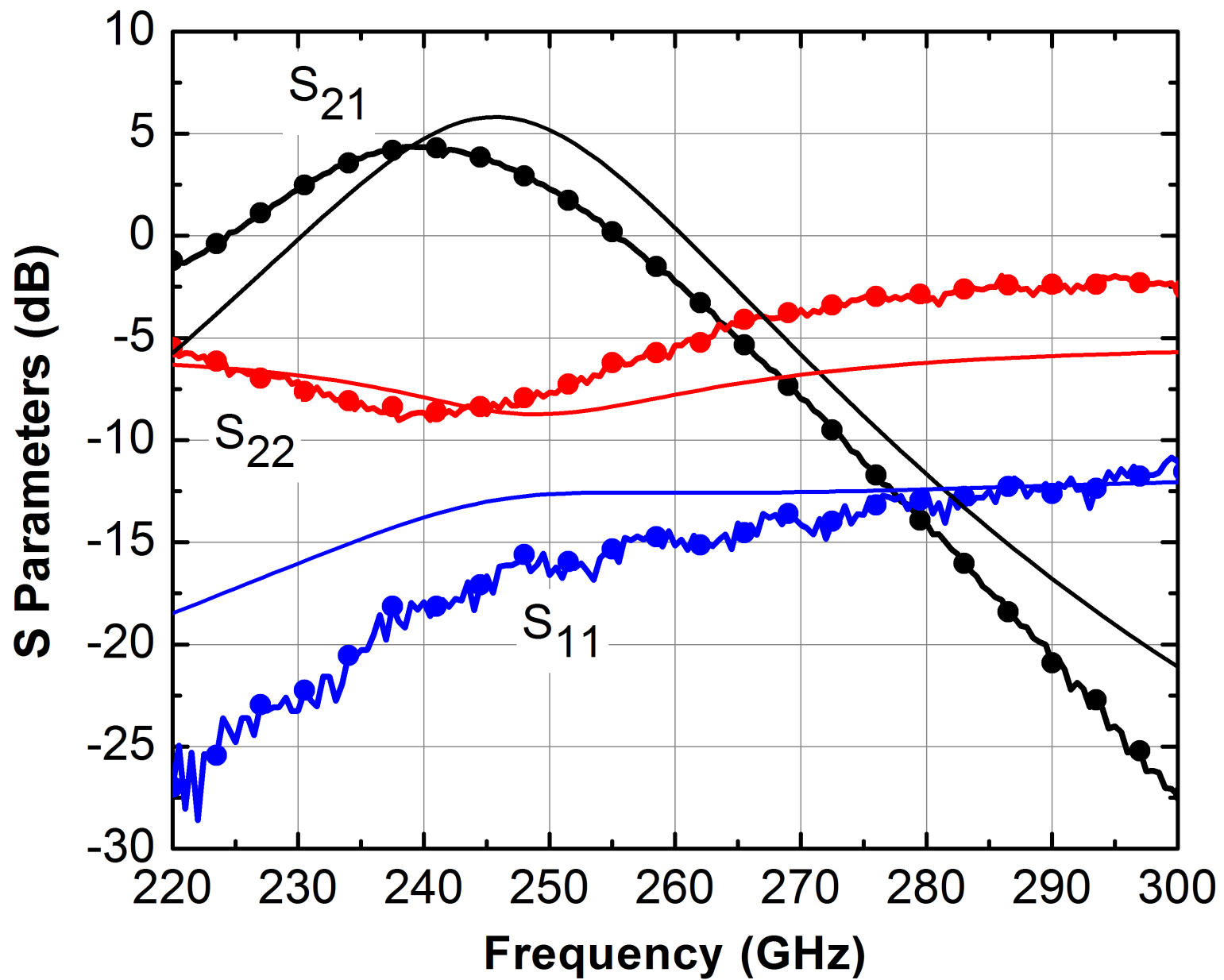
$$P_D = 37.5 \text{ mW}$$

$$G = 4.5 \text{ dB @ 240 GHz}$$

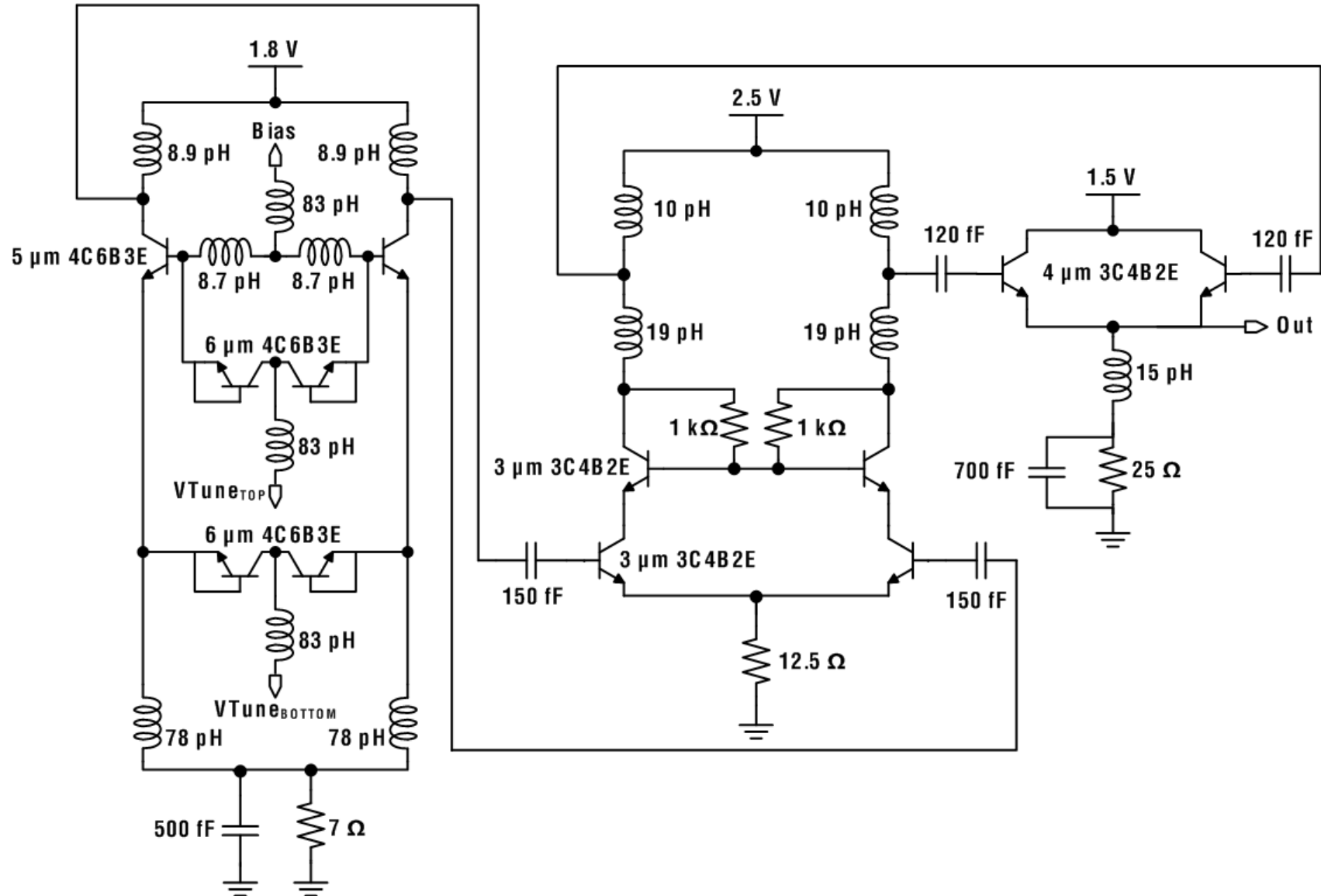


[I. Sarkas et al, MIKON 2012]

240-GHz Amplifier

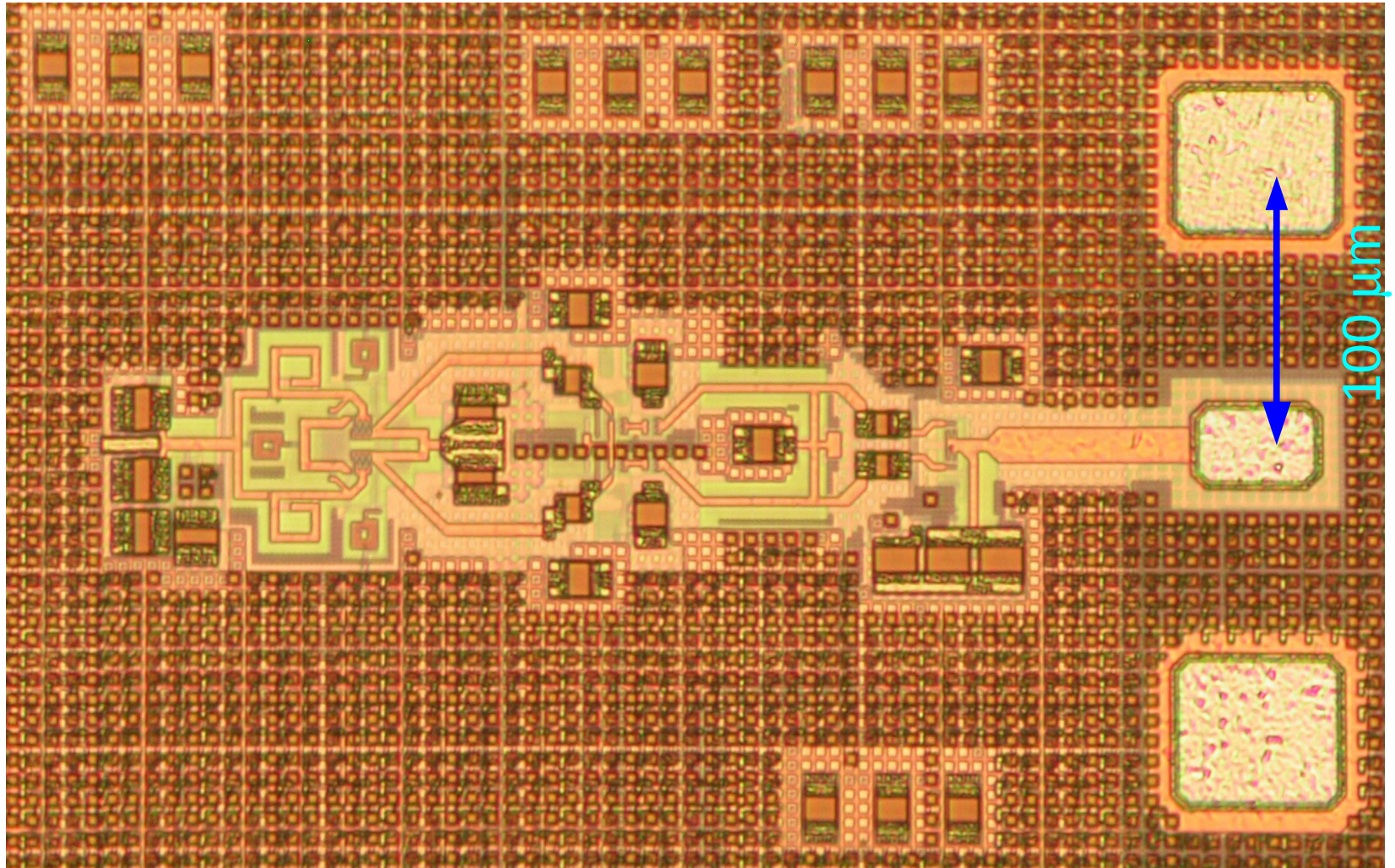


300-GHz VCO-Doubler

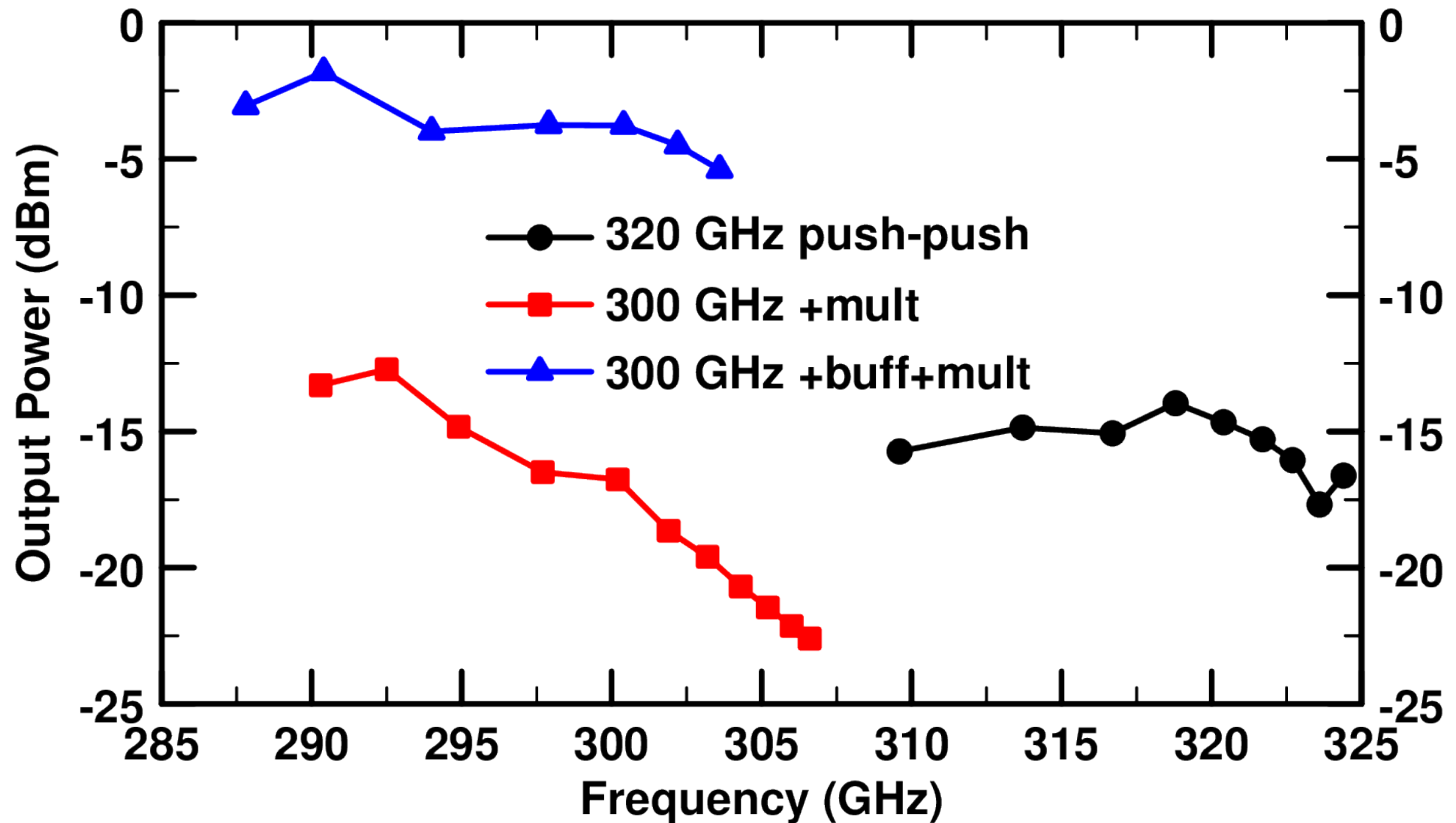


[A. Tomkins et al., BCTM 2012]

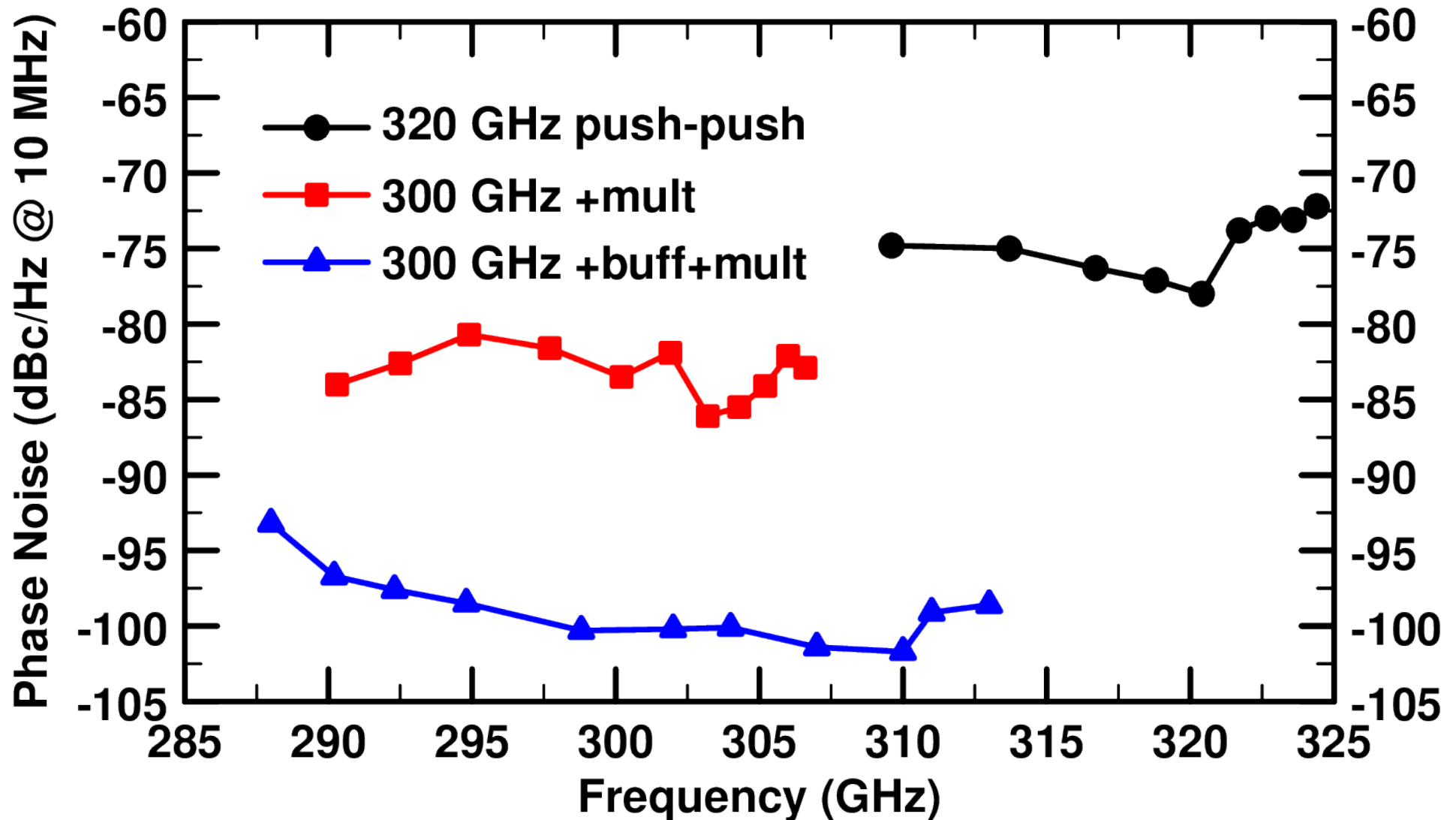
Layout



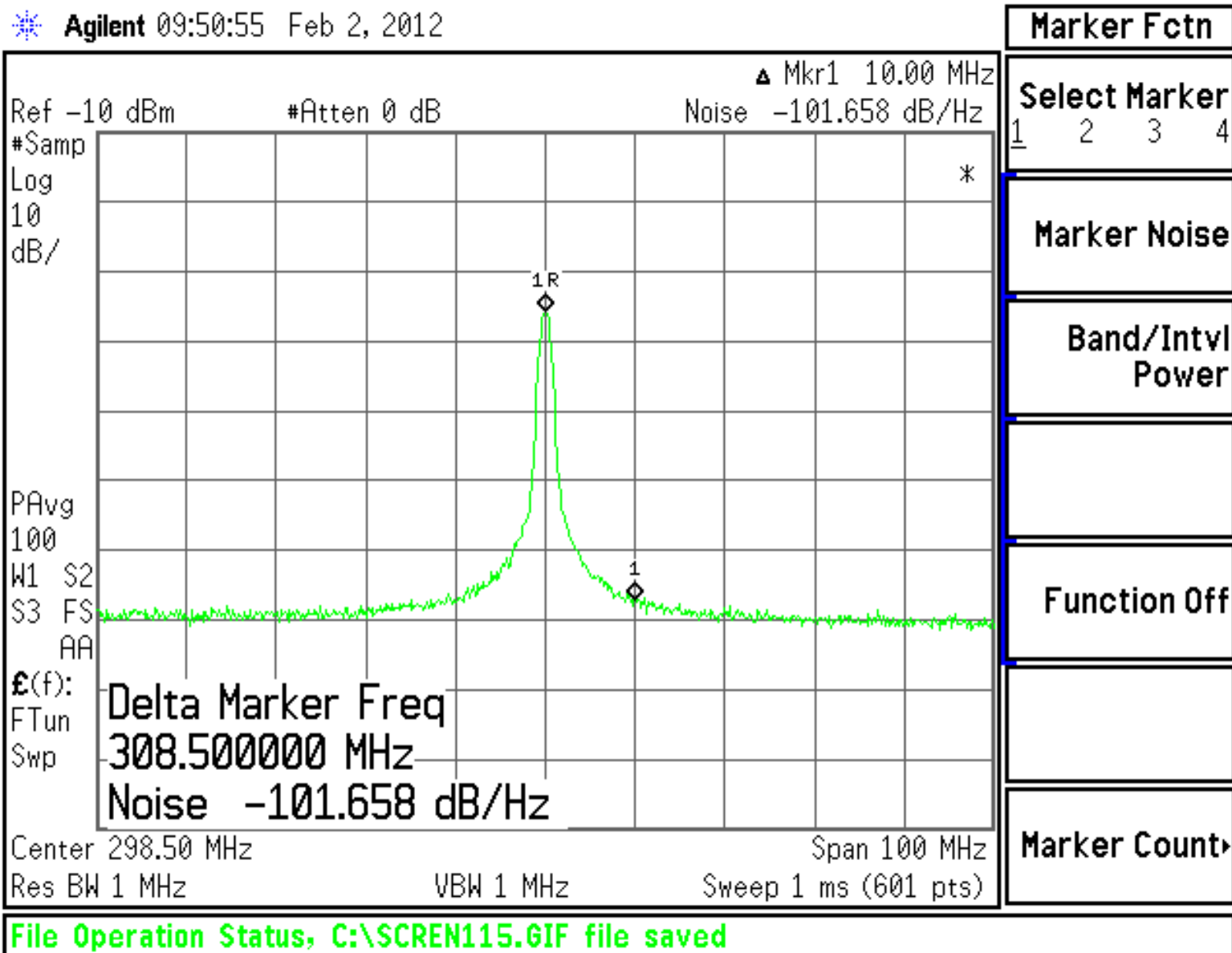
300-GHz Signal Source Comparison



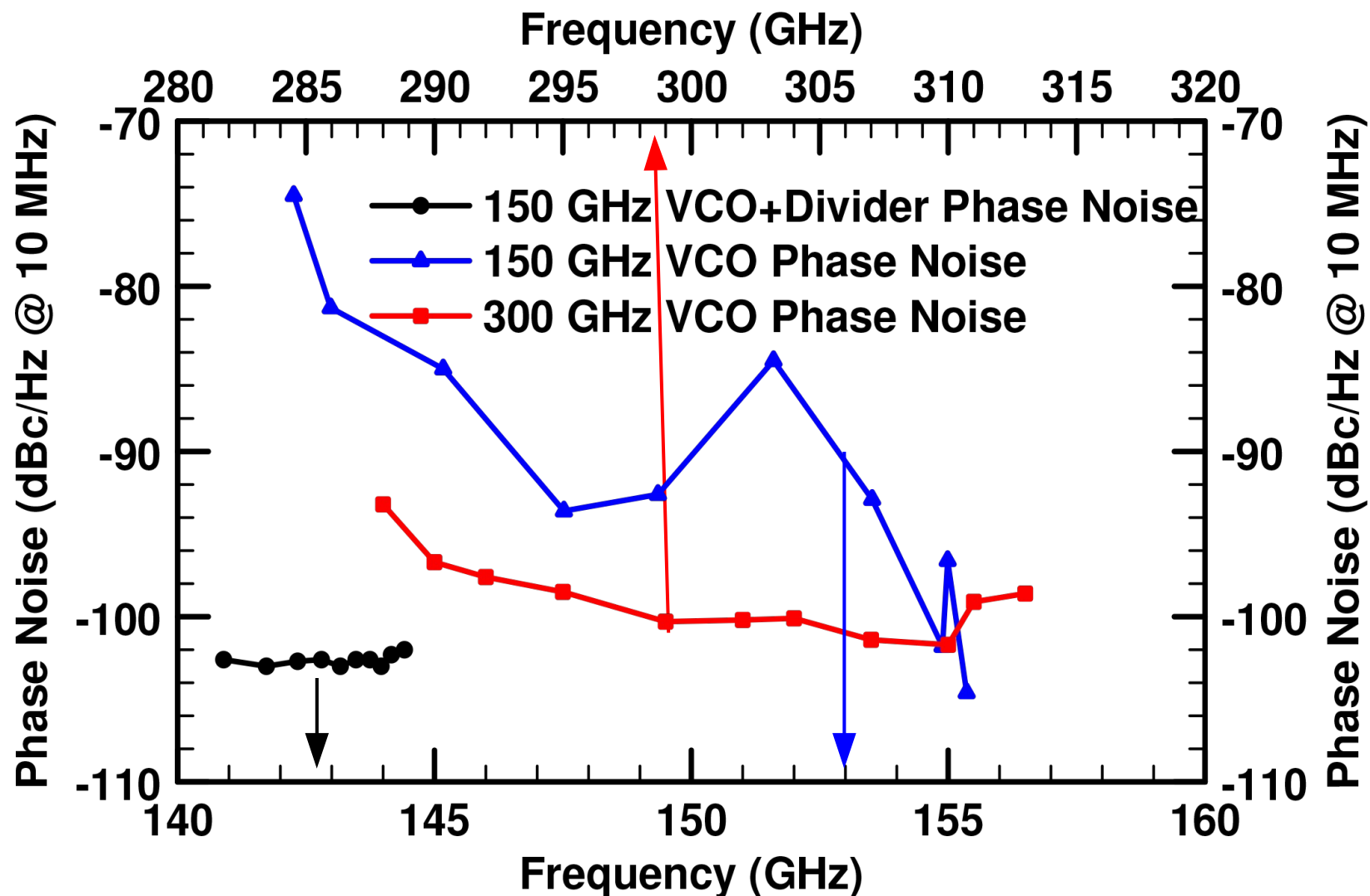
300-GHz Signal Source Comparison (ii)



Phase Noise of VCO-doubler at 309 GHz



300-GHz vs. 150-GHz Phase Noise



SAME VCO in BOTH!

Conclusions

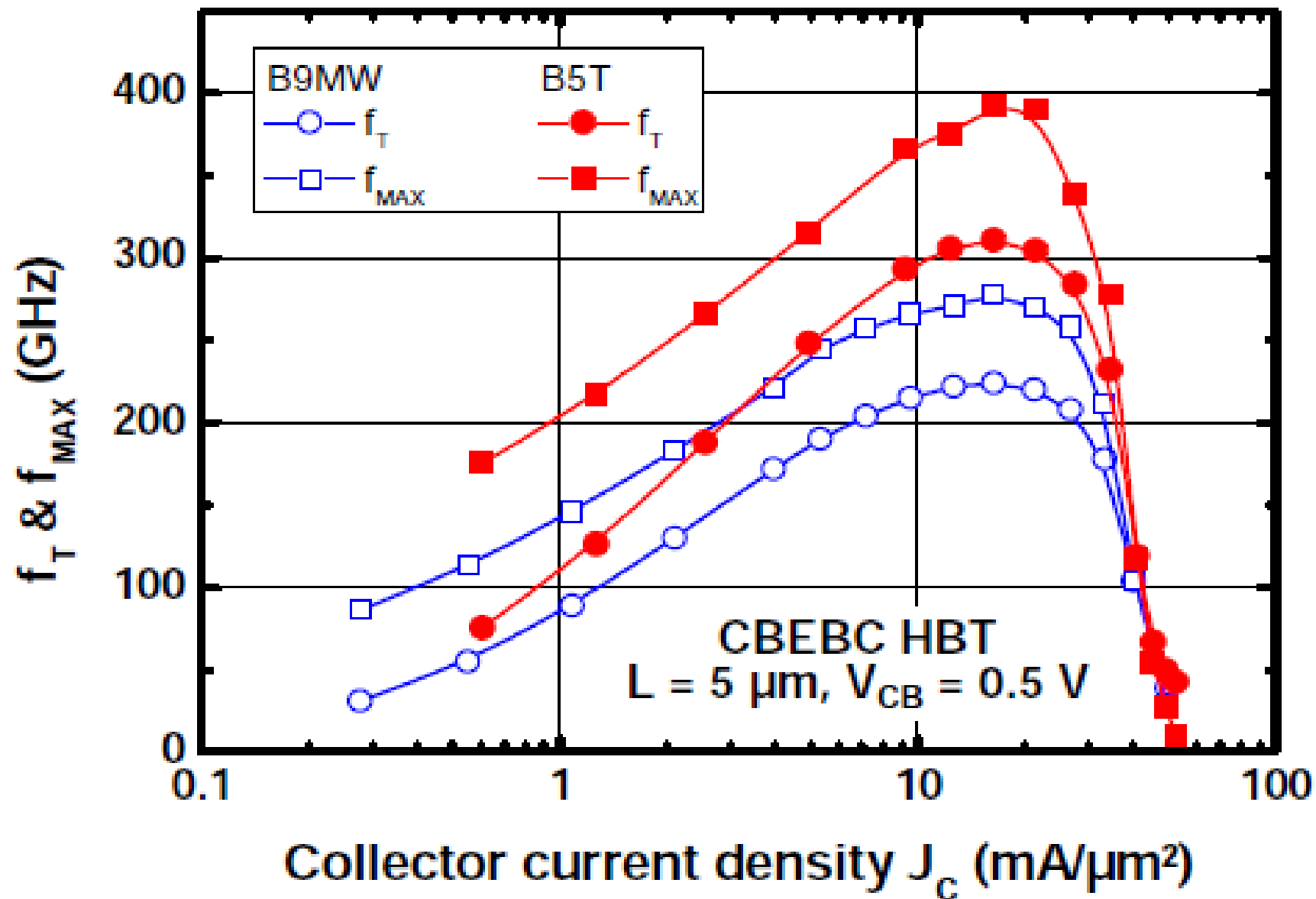
- Why?

- ◆ Because we can!
- ◆ “Cloud” unsustainable without 10x speed and 100x efficiency improvement
- ◆ Need 1Tb/s for near field and intra data center comms

- How?

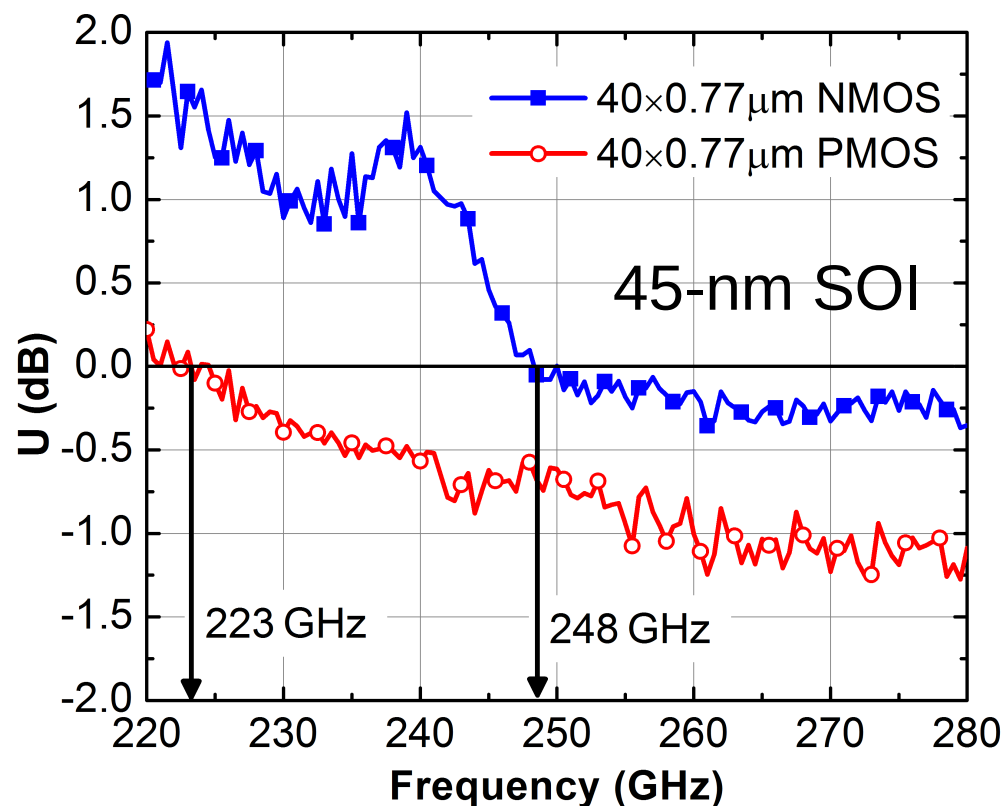
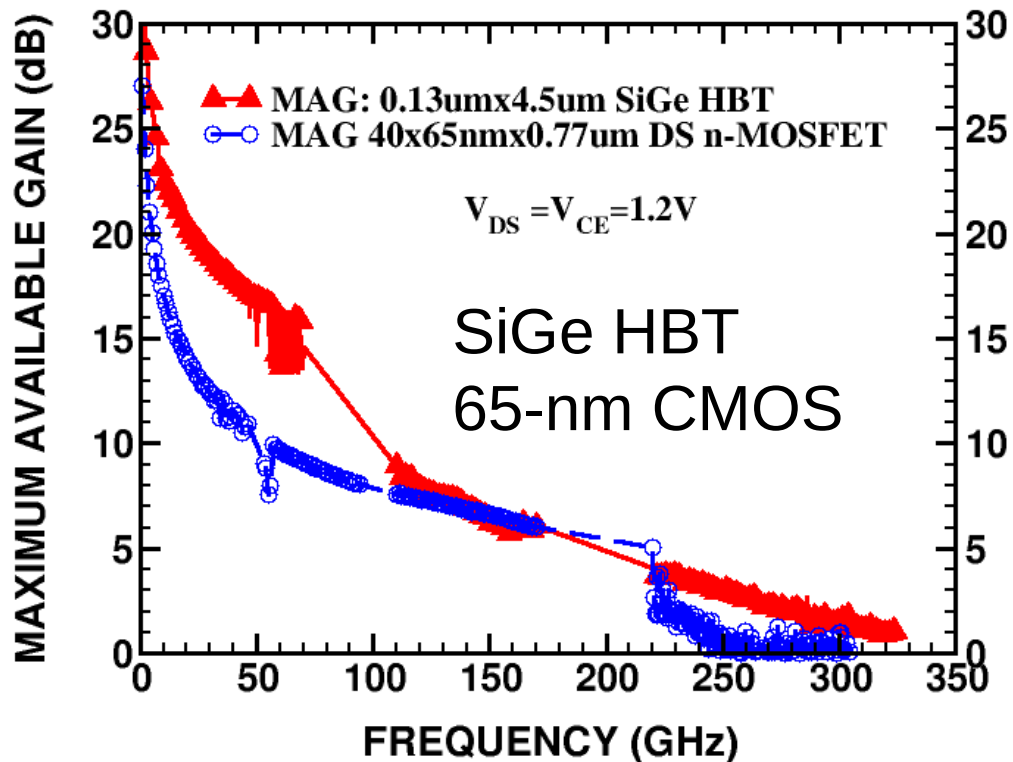
- ◆ 50-100 Gb/s inductively peaked CMOS logic
- ◆ Mm-wave Power-DAC Transmitter
- ◆ ADC-based receiver equalization
- ◆ H-Band SoCs with on-die antennas
- ◆ Low-cost QFN package

SiGe HBT: BC9MW vs. B5T



[Pascal Chevalier, CSICS-2012]

Si Transistor Performance at G-Band

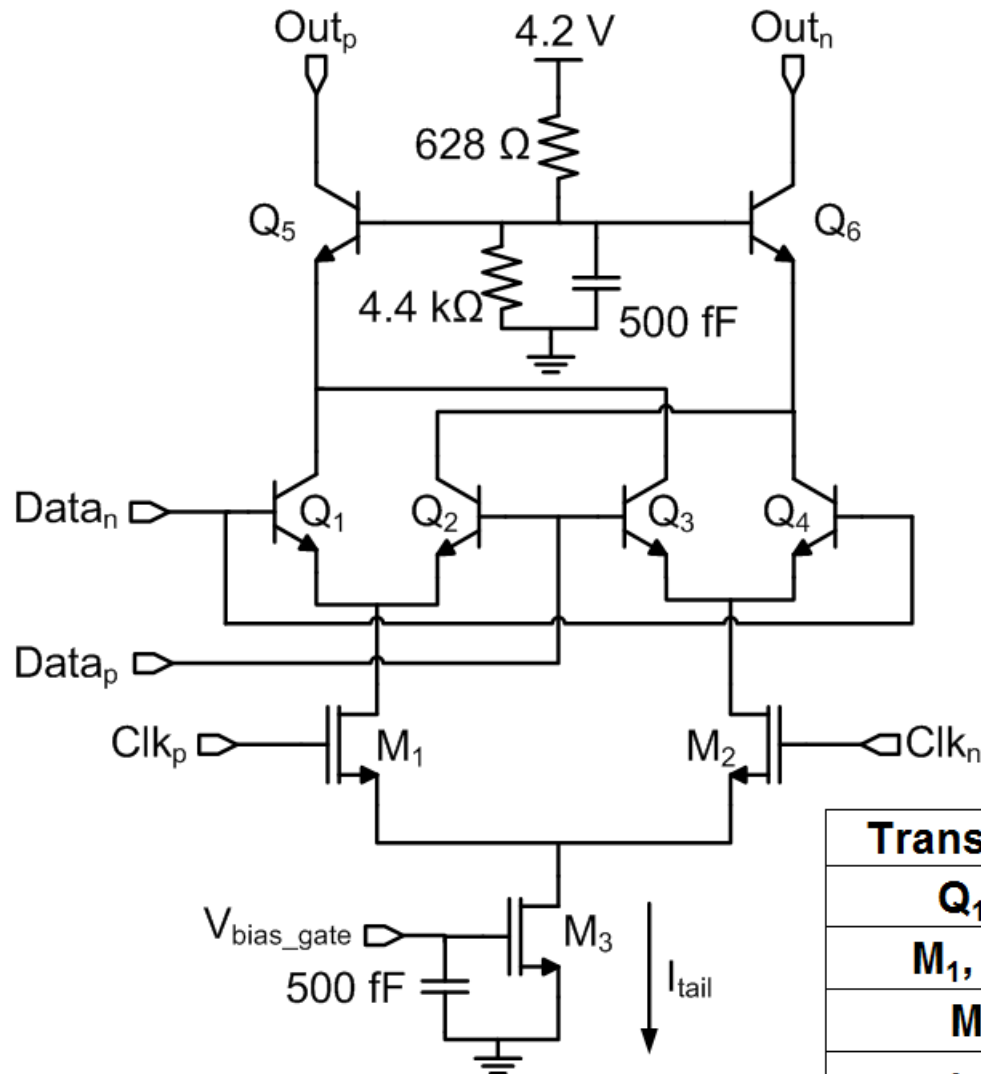


Comparison Table

Reference	[2]	[6]	[3]	[4]	This Work
Technology	32 nm CMOS	65 nm CMOS	180 nm SiGe	130 nm SiGe	130 nm SiGe
Peak Freq.	14	20		52	57
Gain @ peak (dB)	10 (RX)		12	12.1	26
Min. Gain (dB)	0 (RX)			-19	-14
Equalization	29 dB @ 14 GHz	9 dB @ 20 GHz	17 dB @ 24 GHz	18 dB @ 30 GHz	30 dB @ 40 GHz
P _{DC} (mW)	693	80	750	337	250
FOM[pJ/bit]	24.7	2	15	5.6	3.15

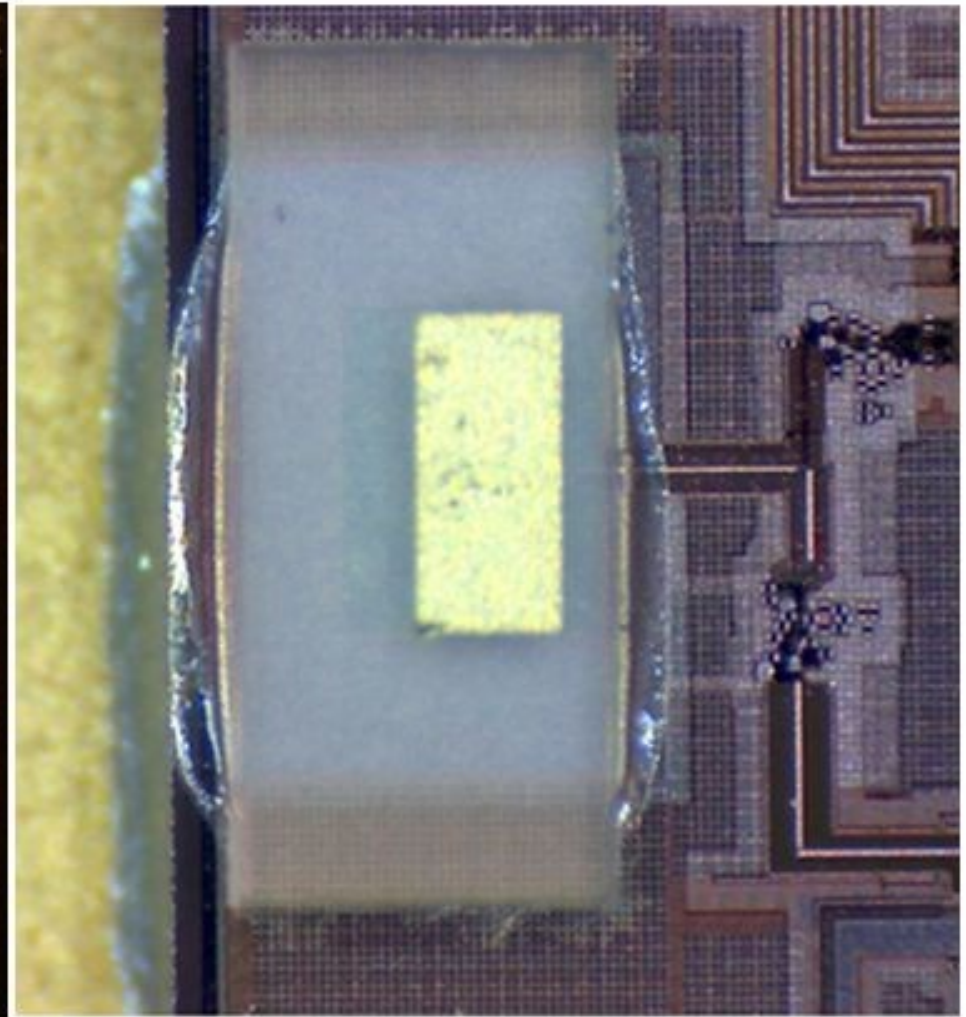
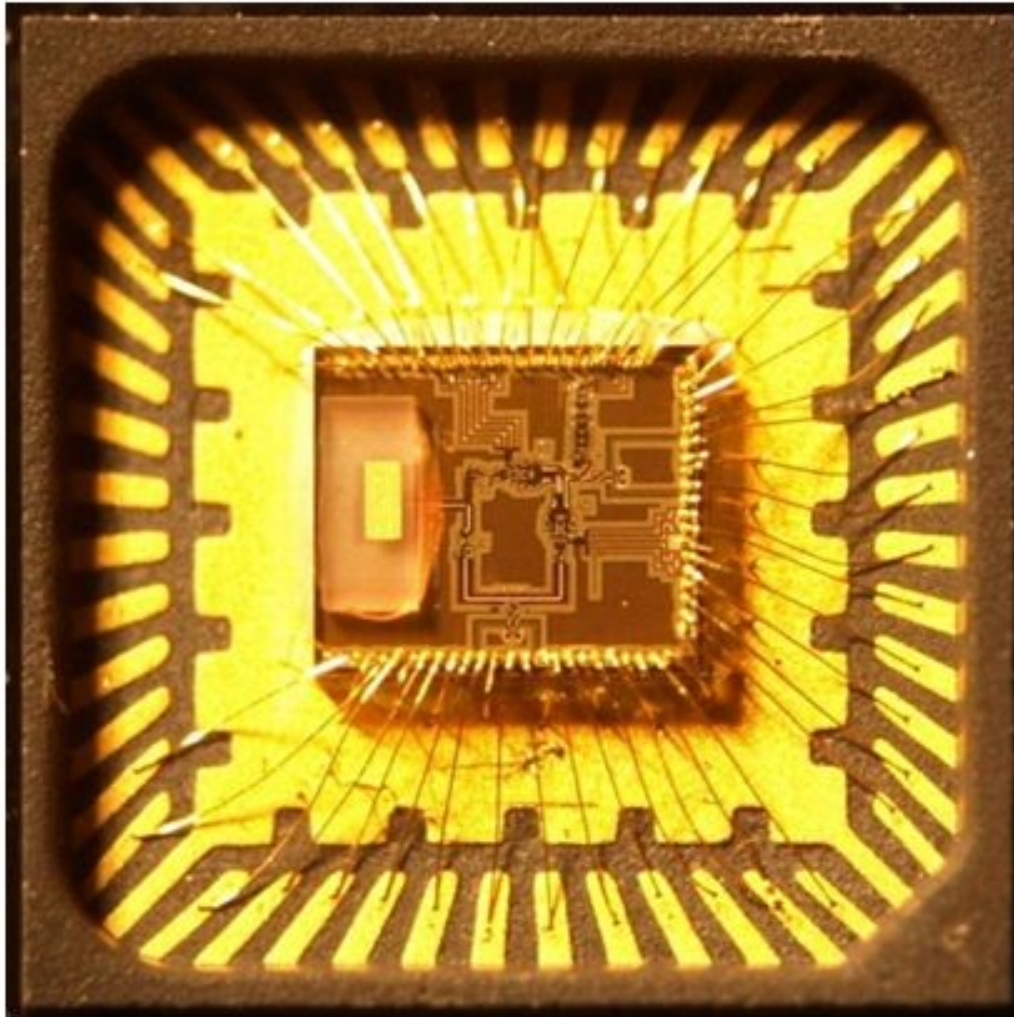
- [2] J. Bulzacchelli *et al.*, “A 28 Gb/s 4-Tap FFE/15-Tap DFE Serial Link Transceiver in 32 nm SOI CMOS Technology,” in *IEEE ISSCC Dig. Tech. Papers*, Feb. 2012, pp. 324–325.
- [3] A. Hazneci *et al.*, “49-Gb/s, 7-Tap Transversal Filter in 0.18 μ mSiGe BiCMOS for Backplane Equalization,” in *IEEE CSICS*, Oct. 2004, pp. 101–104.
- [4] A. Balteanu *et al.*, “A Cable Equalizer with 31 dB of Adjustable Peaking at 52 GHz,” in *IEEE BCTM*, Oct. 2009, pp. 154–157.
- [6] A. Momtaz *et al.*, “An 80 mW 40 Gb/s 7-Tap T/2-Spaced Feed-Forward Equalizer in 65 nm CMOS,” *IEEE JSSC*, vol. 45, no. 3, pp. 629–639, Mar. 2010.

BPSK Cell Schematics



Transistor	LSB	MSB
Q₁₋₆	1 μm	4×2 μm
M₁, M₂	3×2 μm	24×2 μm
M₃	5×4 μm	40×4 μm
I_{tail}	2 mA	16 mA

120 GHz Antenna above IC in QFN



Chip: 2.2mm×2.6mm

Package: 7mm×7mm

[I. Sarkas Trans MTT, March 2012]